

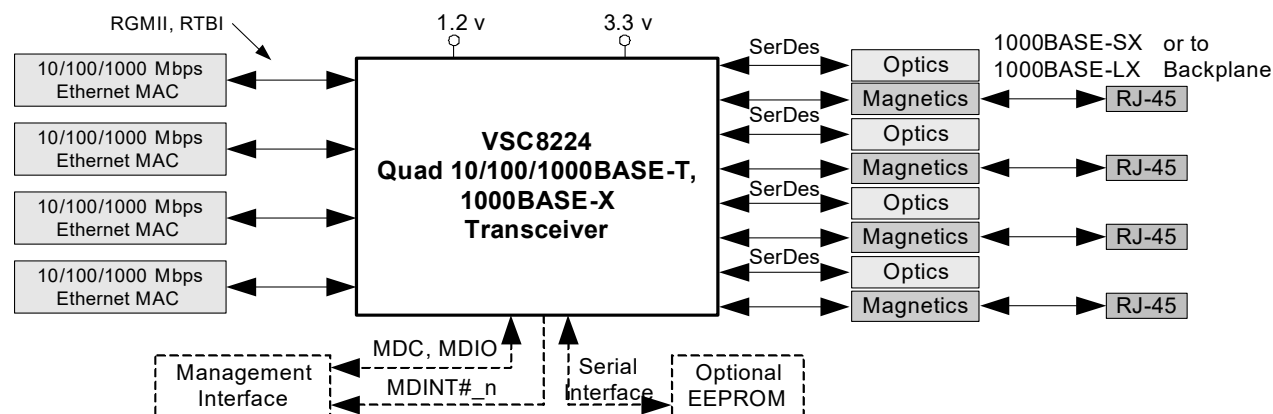


Figure 2-2. VSC8224 System Diagram - Copper + Optical Media (RGMII-to-SerDes)

3 Features and Benefits

Features	Benefits
- Quad, low power, 10/100/1000BASE-T and 1000BASE-X transceivers in 19 mm HS-BGA - Lowest power consumption in the industry at less than 640mW/port (1000BASE-T mode) - Supports PICMG 2.16 and 3.0 Ethernet backplanes at less than 500mW/port	- Catalyzes market for low-cost & high density LAN, WAN, SAN, & MAN switches - Eliminates heatsinks and fans for Gigabit to the desktop LAN switches - Lowest power mode reduces supply costs
Patented, low EMI line driver with integrated line side termination resistors	- Removes 12 passive components per PHY*, reducing PCB area & cost by 50% - Saves up to 50% on magnetic module cost with SimpliPHY'd magnetics - Enables magnetic-less PICMG backplane designs
- Supports RGMII v1.3 (2.5 V and 3.3 V) and v2.0 (1.5 V HSTL) - User-programmable RGMII timing compensation - High performance 1.25 Gbps SerDes - Less than 165 mW/port (RGMII-to-SerDes mode)	- Compatible with a wide variety of parallel interface switch ICs - Simplifies PCB layout; eliminates PCB trombones - Supports CAT-5, fiber optic, and backplane interfaces from a single device
Auto-media Sense detects and configures to support fiber or copper media on a per port basis	Single chip solution for flexible media support
User-configurable copper or fiber link selection preference with programmable interrupt and signal detect I/O pins on each port	Ensures plug-n-play link configuration when connected to any copper, fiber, or backplane link partner
Compliant with IEEE 802.3 (10BASE-T, 100BASE-TX, 1000BASE-T, 1000BASE-X) specifications	Ensures seamless deployment throughout copper and optical networks with industry's highest tolerance to noise and substandard cable plants
>10 kB jumbo frame support with programmable synchronization FIFOs	Provides for maximum jumbo frame sizes in custom SAN and LAN systems

Features	Benefits
Five Direct drive LEDs per port with on-chip filtering, or serial LED interface option	Eliminates external components and EMI issues
Three user configuration options: 1) optional serial EEPROM, 2) hardware configuration pins, or 3) Serial Management Interface (SMI)	Offers design engineer a solution to fit any unmanaged or managed system requirement
Full suite of BIST, near-end, and far-end loopback modes	Simplifies comprehensive in-system test to ensure highest product quality
VeriPHY[®] cable diagnostics	Identifies cable length and operating conditions to isolate common faults that can occur on Cat5 twisted pair cabling
Automatic detection and correction of cable pair swaps, pair skew and pair polarity, along with HP Auto MDI/MDI-X crossover function	- Compatible with 1st generation 1000BASE-T PHYs - Supports Auto MDI/MDI-X even when Autonegotiation is disabled
Manufactured in advanced 0.13μm, 3.3V/1.2V digital CMOS process	Most cost effective technology eliminates more expensive analog process variants
* or, 576 components for a 48-port switch	

4 Applications

- High Port Density 10/100/1000BASE-T Switches
- Workgroup LAN Switches & Routers
- Backplane Applications such as PICMG 2.16, 3.0
- Gigabit Ethernet-based SAN, NAS, and MAN Systems
- High Performance Workstations & Multi-Port Server NICs
- Multi-port fiber to CAT5 media converter

5 Device Block Diagram

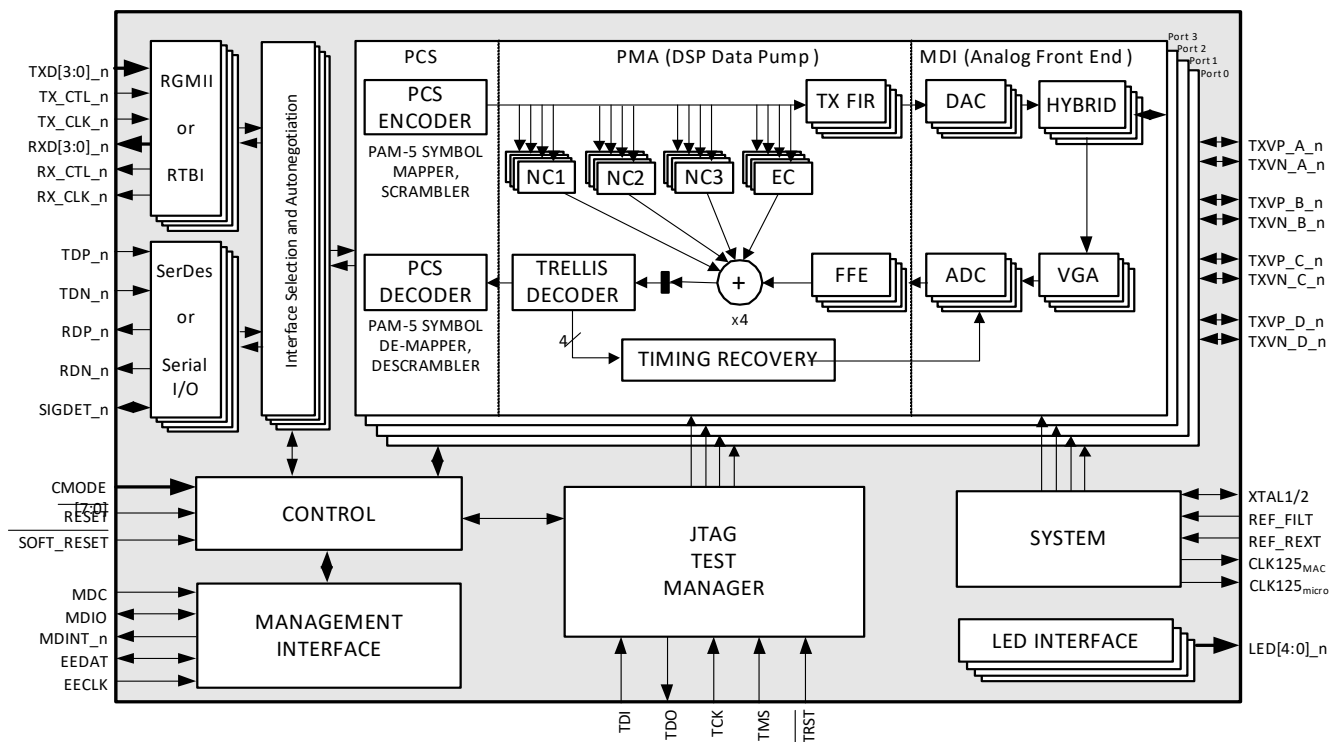


Figure 5-1. VSC8224 Block Diagram¹

¹n = port number (0, 1, 2, 3)

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6 Relevant Specifications and Documentation

The VSC8224 conforms to the following specifications. Please refer to these documents for additional information.

Table 6-1. VSC8224 Relevant Specifications

Specification - Revision	Description
IEEE 802.3-2002	Carrier Sense Multiple Access with Collision Detection (CSMA/CD) Access Method and Physical Layer Specifications. IEEE 802.3-2002 consolidates and supersedes the following specifications: 802.3ab (1000BASE-T), 802.3z (1000BASE-X), 802.3u (Fast Ethernet), with references to ANSI X3T12 TP-PMD standard (ANSI X3.263 TP-PMD).
IEEE 1149.1-1990	Test Access Port and Boundary Scan Architecture ¹ . Includes IEEE Standard 1149.1a-1993 and IEEE Standard 1149.1b-1994.
JEDEC EIA/JESD8-5	2.5V±0.2V (Normal Range), and 1.8V to 2.7V (Wide Range) Power Supply Voltage and Interface Standard for Nonterminated Digital Integrated Circuits.
JEDEC JESD22-A114-B	Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM). Revision of JESD22-A114-A.
JEDEC JESD22-A115-A	Electrostatic Discharge (ESD) Sensitivity Testing Machine Model (MM). Revision of EIA/JESD22-A115.
JEDEC EIA/JESD78	IC Latch-Up Test Standard.
MIL-STD-883E	Military Test Method Standard for Microcircuits.
RGMII Specification - v1.3, v2.0	Reduced Pin-Count Interface for Gigabit Ethernet Physical Layer Devices (per Hewlett Packard). Includes both RGMII and RTBI standards.
PICMG 2.16	IP Backplane specification for CompactPCI v2.16.
Advanced TCA™ Base PICMG 3.0	IP Backplane specification for CompactPCI v3.0.
Cisco InLine Power Detection Algorithm	Cisco Systems InLine Power Detection: http://www.cisco.com/en/US/products/hw/phones/ps379/products_tech_note09186a00801189b5.shtml

¹ Often referred to as the "JTAG" test standard.

7 VSC8224 Differences vs. VSC8234 and VSC8244 Devices

The VSC8224 device is one of three Quad port PHY devices featuring Microsemi's proprietary fourth-generation DSP technology. The VSC8224 is a dual media capable device featuring RGMII/RTBI parallel MAC interfaces with support for both the

10/100/1000BASE-T and 1000BASE-X media interfaces. The VSC8234 supports serial SGMII/SerDes MAC interfaces with 10/100/1000BASE-T copper media interfaces. The VSC8244 provides parallel RGMII/RTBI interfaces with 10/100/1000BASE-T copper media interfaces.

The following table summarizes the MAC and media interfaces supported by the various VSC8224, VSC8234, and VSC8244 quad-port PHYs:

Table 7-1. VSC8224/VSC8234/VSC8244 MAC / Media Interface Support Options

Device #	MAC Interface	Media Interface	Package Options	Full Part Number
VSC8224	RGMII / RTBI	CAT-5	260-pin HS-PBGA	VSC8224HG
	RGMII / RTBI	SerDes (1000Base-X)		
VSC8234	SGMII (4 or 6 pin)	CAT-5	260-pin HS-PBGA	VSC8234HG
	SerDes (1000Base-X)	CAT-5		
VSC8244	RGMII / RTBI	CAT-5	260-pin HS-PBGA	VSC8244HG

8 Data Sheet Conventions

Conventions used throughout this data sheet are specified in the following table.

Table 8-1. Data Sheet Conventions

Convention	Syntax	Examples	Description
Register number	RegisterNumber.Bit or RegisterNumber.BitRange	23.10 23.12:10	Register 23 (address 17h), bit 10. Register 23 (address 17h), bits 12, 11, and 10.
Extended Page Register number	RegisterNumberE.Bit or RegisterNumberE.BitRange	23E.10 23E.12:10	Extended Register 23 (address 17h), bit 10. Extended Register 23 (address 17h), bits 12, 11, and 10.
Signal name (active high)	SIGNALNAME ¹	PLLMODE	Signal name for PLLMODE.
Signal name (active low)	$\overline{\text{SIGNALNAME}}$ ¹	$\overline{\text{RESET}}$	Active low reset signal.
Signal bus name	BUSNAME[MSB:LSB] ¹	CMODE[4:0] ²	CMODE configuration bits 4, 3, 2, 1, and 0.
PHY port number	_n	_3	Denotes a specific PHY port #3. n = {3 2 1 0}.
PHY-specific port signal	SIGNALNAME_n ¹	RX_CTL_3	RX_CTL signal for PHY port 3 ³ .
Signal bus for a specific PHY port	SIGNALNAME[MSB:LSB]_n ¹	RXD[3:0]_3	Receive data bus, bits 3 through 0, for PHY port #3 ³ .

¹ All signal names are in all CAPITAL LETTERS.

² CMODE is common to entire device.

³ RXD signals are unique to each PHY.

9 Package Pin Assignments & Signal Descriptions

9.1 260 HS-PBGA Package Ball Diagram

For complete specifications, refer to [Section 32: "Packaging Specifications"](#).

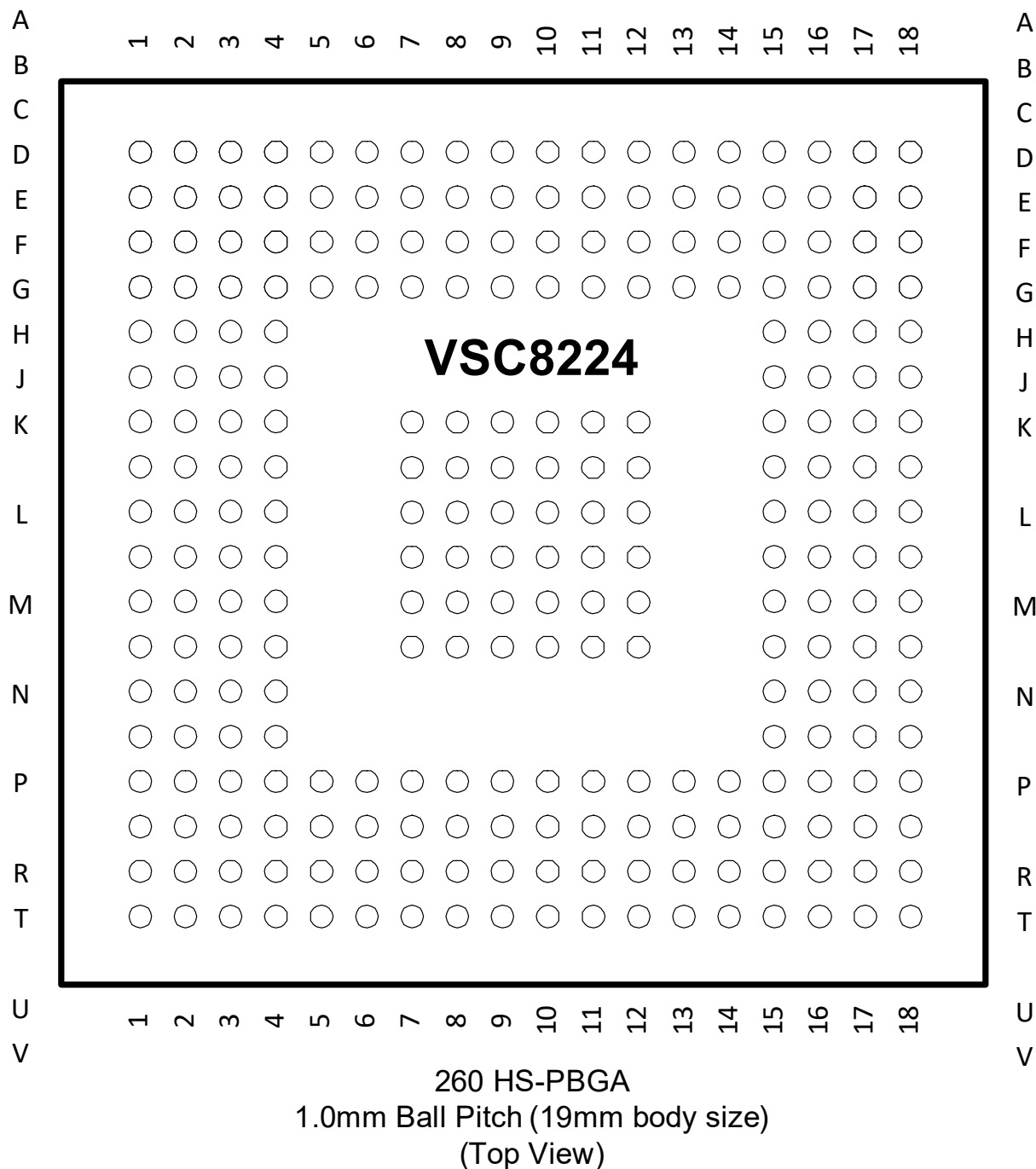


Figure 9-1. 260 HS-PBGA Package Ball Diagram
(View from top of package with underlying BGA ball positions superimposed)

9.2 BGA Ball to Signal Name Cross Reference (LEFT side)

	1	2	3	4	5	6	7	8	9					
A	LED[4]_3	LED[0]_2	TXVPD_3	TXVPC_3	TXVPB_3	TXVPA_3	TXVPD_2	TXVPC_2	TXVPB_2					
B	RDN_0	LED[1]_2	TXVND_3	TXVNC_3	TXVNB_3	TXVNA_3	TXVND_2	TXVNC_2	TXVNB_2					
C	RDP_0	RCP_0	LED[2]_2	LED[3]_2	LED[4]_2	NC	NC	VDD33	REF_REXT					
D	TDP_0	RCN_0	LED[3]_3	VDD33	VDD33	VDD33	VSSS	VSSS	VDD33					
E	TDN_0	SIGDET_0	LED[2]_3	VDD12										
F	RDN_1	VSSS	LED[1]_3	VDD12										
G	RDP_1	RCP_1	LED[0]_3	VSSS						VSSS	VSSS	VSSS		
H	TDP_1	RCN_1	VDD12	VDDDIG						VSSS	VSSS	VSSS		
J	TDN_1	SIGDET_1	VDD12	VDDDIG						VSSS	VSSS	VSSS		
K	RDN_2	VSSS	VSSS	VSSS						VSSS	VSSS	VSSS		
L	RDP_2	RCP_2	VSSS	VDD33						VSSS	VSSS	VSSS		
M	TDP_2	RCN_2	VDD12	VSSS						VSSIO	VSSIO	VSSIO		
N	TDN_2	SIGDET_2	VDD12	VSSS										
P	RDN_3	VSSS	VSSS	VDDDIG										
R	RDP_3	RCP_3	VDD12	VDDDIG	VDDIO _{MAC}	VDDIO _{MAC}	VDDIO _{MAC}	TXREF_2	VDDIO _{MAC}					
T	TDP_3	RCN_3	TXREF_3	RXD[2]_3	TX_CLK_3	TXD[2]_3	RX_CLK_2	RXD[2]_2	TX_CLK_2					
U	TDN_3	SIGDET_3	RX_CTL_3	RXD[1]_3	TX_CTL_3	TXD[1]_3	RX_CTL_2	RXD[1]_2	TX_CTL_2					
V	NC	RX_CLK_3	RXD[3]_3	RXD[0]_3	TXD[3]_3	TXD[0]_3	RXD[3]_2	RXD[0]_2	TXD[3]_2					
	1	2	3	4	5	6	7	8	9					

Figure 9-2. 260-Pin HS-PBGA (19mm) Signal Map (TOP LEFT side of package)

9.3 BGA Ball to Signal Name Cross Reference (RIGHT side)

10	11	12	13	14	15	16	17	18						
TXVPA_2	TXVPD_1	TXVPC_1	TXVPB_1	TXVPA_1	TXVPD_0	TXVPC_0	TXVPB_0	TXVPA_0	A					
TXVNA_2	TXVND_1	TXVNC_1	TXVNB_1	TXVNA_1	TXVND_0	TXVNC_0	TXVNB_0	TXVNA_0	B					
REF_FILT	VSSS	VSSS	VSSS	VSSS	NC	CMODE[7]	CMODE[6]	CMODE[5]	C					
VDD33	VDD33	VDD33	VDD33	VDD12	VDD12	CMODE[4]	XTAL1 or REFCLK	XTAL2	D					
					NC	CMODE[3]	CMODE[2]	CMODE[1]	E					
					VDD33	CMODE[0]	LED[0]_1	LED[1]_1	F					
					VSSS	VSSS	VSSS	VDD33	LED[2]_1	LED[3]_1	LED[4]_1	G		
					VSSS	VSSS	VSSS	VDDDIG	LED[0]_0	LED[1]_0	LED[2]_0	H		
					VSSS	VSSS	VSSS	VDDDIG	TDI	LED[3]_0	LED[4]_0	J		
					VSSS	VSSS	VSSS	VDDIO _{ctl}	TDO	TCK	TMS	K		
					VSSS	VSSS	VSSS	VDDIO _{micro}	$\overline{\text{TRST}}$	EECLK or PLLMODE	EEDAT	L		
					VSSIO	VSSIO	VSSIO	VSSIO	$\overline{\text{RESET}}$	$\overline{\text{SOFT}}\overline{\text{RESET}}$	OSCEN or CLK125 _{micro}	M		
										VSSS	MDINT_1	MDINT_2	MDINT_3	N
										VSSS	MDC	MDIO	MDINT_0	P
TXREF_1	VDDIO _{MAC}	VDDIO _{MAC}	TXREF_0	VDDDIG	VDDDIG	VDD33	CLK125 _{MAC}	MICROREF	R					
TXD[2]_2	RX_CLK_1	RXD[0]_1	TXD[3]_1	TXD[0]_1	RXD[3]_0	RXD[0]_0	TXD[3]_0	TXD[0]_0	T					
TXD[1]_2	RX_CTL_1	RXD[1]_1	TX_CLK_1	TXD[1]_1	RX_CTL_0	RXD[1]_0	TX_CTL_0	TXD[1]_0	U					
TXD[0]_2	RXD[3]_1	RXD[2]_1	TX_CTL_1	TXD[2]_1	RX_CLK_0	RXD[2]_0	TX_CLK_0	TXD[2]_0	V					
10	11	12	13	14	15	16	17	18						

Figure 9-3. 260-Pin HS-PBGA (19mm) Signal Map (TOP RIGHT side of package)

9.4 Signal Type Descriptions

Table 9-1. Signal Type Descriptions

Symbol	Signal Type	Description
I	Digital Input	Standard digital input signal. No internal pull-up or pull-down.
I _{PU}	Digital Input with Pull-up	Standard digital input. Includes on-chip 100k Ω pull-up to VDDIO.
I _{PD}	Digital Input with Pull-down	Standard digital input. Includes on-chip 100k Ω pull-down to VSSIO.
I _{DIFF}	Differential Input Pair	SerDes differential input pair with 100 Ω differential terminations. Pins should be AC-coupled with external 0.01 μ F capacitors) ¹ .
O _{DIFF}	Differential Output Pair	SerDes differential output pair, with on-chip 100 Ω differential terminations. Pins should be AC-coupled with external 0.01 μ F capacitors.
O _{ZC}	Impedance Controlled Output	50 Ω integrated (on-chip) source series terminated, digital output signal. Used primarily for timing-sensitive MAC I/F and 125MHz clock output pins, in addition to high speed manufacturing test mode pins.
I _{PD/O}	Digital Bidirectional	Tristate-able, digital input and output signal. Includes on-chip 100k Ω pull-down to VSSIO.
OD	Digital Open Drain Output	Open drain digital output signal. Must be pulled to VDDIO through an external pull-up resistor.
A _{DIFF}	Analog Differential	Analog differential signal pair for twisted pair interface.
A _{BIAS}	Analog Bias	Analog bias or reference signal. Must be tied to external resistor and/or capacitor bias network, as shown in Section 10: "System Schematics" .
I _A	Analog Input	Analog input for sensing variable voltage levels.
OS	Open Source	Open source digital output signal. Must be pulled to GND through an external pull-down resistor.
V _{REF}	Voltage Reference Input	Voltage Reference input pins required for VDDIO HSTL mode
I _{PUJTAG}	JTAG Input	JTAG input. Includes on-chip pull-up to VDDIO _{CTL} . These pins are 5V tolerant when VDDIO _{CTL} = 3.3V. For VDDIO _{CTL} = 2.5V, these pins are up to 4.7V tolerant.
O _{CRYST}	Crystal Output	Crystal Clock output pin. If not used, leave unconnected.
NC	No Connect	No connect signal. Must be left floating.

¹ AC-Coupling capacitors may be eliminated as long as Vicm and Vocm limits are observed. See [Section 30: "SerDes Specifications"](#).

9.5 Parallel MAC Transmit Interface (MAC TX) Pins

The following pins are used for connecting to a parallel data bus MAC via the industry-standard RGMII and RTBI interfaces. If these parallel side interfaces are not used, all of the following pins may be left unconnected.

Table 9-2. MAC TX Signal Descriptions

HSBGA Ball #	Signal Name Parallel MAC Interface Modes		Type	Description
	RGMII	RTBI		
V5, T6, U6, V6 V9, T10, U10, V10 T13, V14, U14, T14 T17, V18, U18, T18	TXD[3:0]_3 TXD[3:0]_2 TXD[3:0]_1 TXD[3:0]_0	TXD[3:0]_3 TXD[3:0]_2 TXD[3:0]_1 TXD[3:0]_0	I _{PD}	Multiplexed Transmit Data Nibbles (RGMII mode) Bits [3:0] are synchronously input on the rising edge of TX_CLK_n, and bits [7:4] on the falling edge of TX_CLK_n. Multiplexed Transmit Data Nibbles (RTBI mode) Bits [3:0] are synchronously input on the rising edge of TX_CLK_n, and bits [8:5] on the falling edge of TX_CLK_n.
U5 U9 V13 U17	TX_CTL_3 TX_CTL_2 TX_CTL_1 TX_CTL_0	TXD[4]_3 TXD[4]_2 TXD[4]_1 TXD[4]_0	I _{PD}	Transmit Enable, Transmit Error Multiplexed Input (RGMII mode) In RGMII mode, this input is sampled by the PHY on opposite edges of TX_CLK_n to indicate two transmit conditions of the MAC: 1) on the rising edge of TX_CLK_n, this input serves as TXEN, indicating valid data is available on the TD input data bus. 2) on the falling edge of TX_CLK_n, this input signals a transmit error from the MAC, based on a logical derivative of TXEN and TXER, per RGMII specification Version 2.0. Multiplexed Transmit Data (RTBI mode) Bit [4] is synchronously input on the rising edge of TX_CLK_n, and bit [9] on the falling edge of TX_CLK_n.
T5 T9 U13 V17	TX_CLK_3 TX_CLK_2 TX_CLK_1 TX_CLK_0	TX_CLK_3 TX_CLK_2 TX_CLK_1 TX_CLK_0	I	Transmit Clock Input (RGMII mode) The transmit clock shall be either a 125MHz or 25MHz (for 1000Mb or 100Mb modes, respectively), with a +/-50ppm tolerance. If left unconnected, these pins will require a pull-down resistor to ground.

9.6 Parallel MAC Receive Interface (MAC RX) Pins

All output pins for the MAC interface include impedance-calibrated, tri-state-able output drive capability.

Table 9-3. MAC RX Signal Descriptions

HSBGA Ball #	Signal Name Parallel MAC Interface Modes		Type	Description
	RGMII	RTBI		
V3, T4, U4, V4 V7, T8, U8, V8 V11, V12, U12, T12 T15, V16, U16, T16	RXD[3:0]_3 RXD[3:0]_2 RXD[3:0]_1 RXD[3:0]_0	RXD[3:0]_3 RXD[3:0]_2 RXD[3:0]_1 RXD[3:0]_0	O _{ZC}	Multiplexed Receive Data Nibble (RGMII mode only) Bits [3:0] are synchronously output on the rising edge of RX_CLK_n, and bits [7:4] on the falling edge of RX_CLK_n. Multiplexed Receive Data Nibbles (RTBI mode) Bits [3:0] are synchronously output on the rising edge of RX_CLK_n, and bits [8:5] on the falling edge of RX_CLK_n.

Table 9-3. MAC RX Signal Descriptions (*continued*)

HSBGA Ball #	Signal Name Parallel MAC Interface Modes		Type	Description
	RGMII	RTBI		
V2 T7 T11 V15	RX_CLK_3 RX_CLK_2 RX_CLK_1 RX_CLK_0	RX_CLK_3 RX_CLK_2 RX_CLK_1 RX_CLK_0	O _{ZC}	Receive Clock Output (RGMII and RTBI modes) Receive data is sourced from the PHY synchronously on the rising edge of RX_CLK_n and is the recovered clock from the media.
U3 U7 U11 U15	RX_CTL_3 RX_CTL_2 RX_CTL_1 RX_CTL_0	RXD[4]_3 RXD[4]_2 RXD[4]_1 RXD[4]_0	O _{ZC}	Multiplexed Receive Data Valid / Receive Error Output (RGMII mode only). In RGMII mode, this output is sampled by the MAC on opposite edges of RX_CLK_n to indicate two receive conditions from the PHY: 1) on the rising edge of RX_CLK_n, this output serves as RXDV, signaling valid data is available on the RD input data bus, 2) on the falling edge of RX_CLK_n, this output signals a receive error from the PHY, based on a logical derivative of RXDV and RXER, per RGMII specification Version 2.0. Multiplexed Receive Data (RTBI mode) Bit [4] is synchronously output on the rising edge of RX_CLK_n, and bit [9] on the falling edge of RX_CLK_n.

9.7 SerDes Interface Pins

Table 9-4. SerDes Interface Signal Descriptions

HSBGA Ball #	Signal Name	Type	Description
T1 M1 H1 D1 U1 N1 J1 E1	TDP_3 TDP_2 TDP_1 TDP_0 TDN_3 TDN_2 TDN_1 TDN_0	I _{DIFF}	Transmitter Data Differential Input Pair (for SerDes mode) 1.25Gbaud differential inputs with on-chip 100Ω or 150Ω differential termination. The TDP_n and TDN_n pins should be AC-coupled with external 0.01μF series capacitors ¹ . See Section 10: "System Schematics" for further information.
E2 J2 N2 U2	SIGDET_0 SIGDET_1 SIGDET_2 SIGDET_3	I _{PD/O}	SerDes Signal Detect SIGDET_n can be configured as an input or output. The function of SIGDET_n changes based on the direction. For more information please refer to MII Register 19E . When configured as an input, SIGDET_n must be asserted to allow the SerDes clock recovery to take place and to allow for a 1000BASE-X link to be established. See Section 24: "Initialization and Configuration" and MII Register 19E for information on how to configure the SIGDET_n pins.
R1 L1 G1 C1 P1 K1 F1 B1	RDP_3 RDP_2 RDP_1 RDP_0 RDN_3 RDN_2 RDN_1 RDN_0	O _{DIFF}	Receiver Data Differential Output Pair (for SerDes mode) Differential, AC-coupled, 1.25 Gbaud outputs. External 0.01μF AC coupling capacitors should be located on the VSC8224 side. The 100Ω or 150Ω differential termination should be placed at the far end of the circuit board trace away from the VSC8224. For information on adjusting the output swing of these pins, see Table 26.35, "Register 17E (11h) - CLK125micro Clock Enable," on page 99 .

Table 9-4. SerDes Interface Signal Descriptions (*continued*)

HSBGA Ball #	Signal Name	Type	Description
R2 L2 G2 C2 T2 M2 H2 D2	RCP_3 RCP_2 RCP_1 RCP_0 RCN_3 RCN_2 RCN_1 RCN_0	O _{DIFF}	Clock Differential Output Pair This optional signal pair is a differential, AC-coupled, 625 MHz source synchronous clock for the SerDes data. These pins should be left unconnected when not using the source synchronous output clock with the SerDes interface. In four-pin SerDes mode, these pins are normally not used. For information on adjusting the output swing of these pins, see Table 26.35, "Register 17E (11h) - CLK125micro Clock Enable," on page 99.

¹ AC-Coupling capacitors may be eliminated as long as Vicm and Vocm limits are observed. See [Section 30: "SerDes Specifications"](#).

9.8 Twisted Pair Interface Pins

Table 9-5. Twisted Pair Interface Pins

HSBGA Ball #	Signal Name	Type	Description
A6 A10 A14 A18	TXVPA_3 TXVPA_2 TXVPA_1 TXVPA_0	A _{DIFF}	TX/RX Channel "A" Positive Signal Positive differential signal connected to the positive primary side of the transformer. This pin signal forms the positive signal of the "A" data channel. In all three speeds, these pins generate the secondary side signal, normally connected to RJ-45 pin 1. See See "System Schematics" on page 29..
B6 B10 B14 B18	TXVNA_3 TXVNA_2 TXVNA_1 TXVNA_0	A _{DIFF}	TX/RX Channel "A" Negative Signal Negative differential signal connected to the negative primary side of the transformer. This pin signal forms the negative signal of the "A" data channel. In all three speeds, these pins generate the secondary side signal, normally connected to RJ-45 pin 2. See See "System Schematics" on page 29..
A5 A9 A13 A17	TXVPB_3 TXVPB_2 TXVPB_1 TXVPB_0	A _{DIFF}	TX/RX Channel "B" Positive Signal Positive differential signal connected to the positive primary side of the transformer. This pin signal forms the positive signal of the "B" data channel. In all three speeds, these pins generate the secondary side signal, normally connected to RJ-45 pin 3. See See "System Schematics" on page 29..
B5 B9 B13 B17	TXVNB_3 TXVNB_2 TXVNB_1 TXVNB_0	A _{DIFF}	TX/RX Channel "B" Negative Signal Negative differential signal connected to the negative primary side of the transformer. This pin signal forms the negative signal of the "B" data channel. In all three speeds, these pins generate the secondary side signal, normally connected to RJ-45 pin 6. See See "System Schematics" on page 29..
A4 A8 A12 A16	TXVPC_3 TXVPC_2 TXVPC_1 TXVPC_0	A _{DIFF}	TX/RX Channel "C" Positive Signal Positive differential signal connected to the positive primary side of the transformer. This pin signals forms the positive signal of the "C" data. In 1000Mb mode, these pins generate the secondary side signal, normally connected to RJ-45 pin 4 (pins not used in 10M/100M modes). See See "System Schematics" on page 29..
B4 B8 B12 B16	TXVNC_3 TXVNC_2 TXVNC_1 TXVNC_0	A _{DIFF}	TX/RX Channel "C" Negative Signal Negative differential signal connected to the negative primary side of the transformer. This pin signal forms the negative signal of the "C" data channel. In 1000Mb mode, these pins generate the secondary side signal, normally connected to RJ-45 pin 5 (pins not used in 10M/100M modes). See See "System Schematics" on page 29..

Table 9-5. Twisted Pair Interface Pins (*continued*)

HSBGA Ball #	Signal Name	Type	Description
A3 A7 A11 A15	TXVPD_3 TXVPD_2 TXVPD_1 TXVPD_0	A _{DIFF}	TX/RX Channel "D" Positive Signal Positive differential signal connected to the positive primary side of the transformer. This pin signal forms the positive signal of the "D" data channel. In 1000Mb mode, these pins generate the secondary side signal, normally connected to RJ-45 pin 7 (pins not used in 10M/100M modes). See "System Schematics" on page 29..
B3 B7 B11 B15	TXVND_3 TXVND_2 TXVND_1 TXVND_0	A _{DIFF}	TX/RX Channel "D" Negative Signal Negative differential signal connected to the negative primary side of the transformer. This pin signal forms the negative signal of the "D" data channel. In 1000Mb mode, these pins generate the secondary side signal, normally connected to RJ-45 pin 8 (pins not used in 10M/100M modes). See "System Schematics" on page 29..

9.9 Serial Management Interface Pins (IEEE SMI)

Table 9-6. Serial Management Interface Pins (IEEE SMI)

HSBGA Ball	Signal Name	Type	Description
P16	MDC	I	Management Data Clock A 0 to 12.5MHz reference input is used to clock serial MDIO data into and out of the VSC8224. The expected nominal frequency is 2.5MHz, as specified by the IEEE standard. This clock is typically asynchronous with respect to the PHY's transmit or receive clock.
P17	MDIO	OD	Management Data I/O MDIO configuration and status data is exchanged on this pin bidirectionally between the PHY and the Station Manager, synchronously to the rising edge of MDC. This signal normally requires a 1.5k Ω to 2k Ω external pull-up resistor at the Station Manager. The value of the pull-up resistor depends on the MDC clock frequency and the maximum capacitive load on the MDIO pin.
P18 N16 N17 N18	MDINT_0 MDINT_1 MDINT_2 MDINT_3	OS/OD	Management Interrupt Outputs These output signals indicate a change in each of the four PHY's link operating conditions for which a station manager must interrogate to determine further information. Upon reset or powerup, the VSC8224 will automatically configure these pins as active-low (open drain) or active-high (open source) based on the polarity of an external resistor connection. For active-low configuration, tie each MDINT_n pin to VDD33 through an external 10k Ω pull-up resistor. For active-high configuration, tie each MDINT_n pin to GND through an external 10k Ω pull-down resistor. If only one MDINT_n signal is desired for all four PHYs, these pins can be tied together on the PCB in a wired-OR configuration with only a single pull-up or pull-down resistor.

9.10 Back-door Serial EEPROM Interface Pins

Table 9-7. Back-door Serial EEPROM Interface Pins

HSBGA Ball	Signal Name	Type	Description
L18	EEDAT	I _{PD} /O	EEPROM Serial I/O Data The optional EEPROM data interface pin can be used to allow VSC8224 operating mode and configuration data to be read from an external EEPROM. (The EEPROM can also be written if desired.) EEPROM data is synchronously exchanged, bi-directionally, between the VSC8224 and the external EEPROM. Data is clocked from the VSC8224 on the falling edge of EECLK, and into the VSC8224 on the rising edge of EECLK as defined by the ATMEL "AT24CXXX" type EEPROMs. This pin should be connected to the SDA pin of the EEPROM. Refer to Section 24.4: "EEPROM Interface" for more information. The VSC8224 determines that an external EEPROM is present by monitoring the EEDAT pin at power-up or when RESET is de-asserted: if EEDAT has a 4.7k external pull-up resistor, the VSC8224 assumes an EEPROM is present. The EEDAT pin can be left floating or grounded to indicate no EEPROM.
L17	EECLK or PLLMODE	I _{PD} /O _{ZC}	EECLK - Serial EEPROM Clock Output This output is the clock line of the two-wire, serial EEPROM interface. The VSC8224 drives this line at a 50kHz rate on reset. When accessed through the MII registers, this line is driven at a 100kHz rate. This pin should be connected to the SCL pin of the EEPROM. Refer to Section 24.4: "EEPROM Interface" for more information. PLLMODE - PLL Mode Select Input PLLMODE is sampled during the device power-up sequence or in reset. When PLLMODE is high, the VSC8224 expects a 125MHz clock input as the PHY's reference clock. When pulled low (default), a reference clock of 25MHz is expected from either an external crystal or a clock reference input. This pin is internally pulled down with a 100k resistor.

9.11 Configuration and Control Pins

Table 9-8. Configuration and Control Pins

HSBGA Ball	Signal Name	Type	Description
F16 E18 E17 E16 D16 C18 C17 C16	CMODE0 CMODE1 CMODE2 CMODE3 CMODE4 CMODE5 CMODE6 CMODE7	I _A	Hardware Chip Mode Select The CMODE inputs are used for hardware configuration of the various operating modes of the VSC8224. Each pin has multiple settings, each of which is established by an external 1% resistor tied to GND or VDD33. See Section 24.3: "CMODE Pin Configuration" for details on configuring the VSC8224 with the CMODE pins.
M16	$\overline{\text{RESET}}$	I _{PU}	Hardware Chip Reset RESET is an active low input, which powers down all of the internal reference voltages and the PLL, and resets all internal logic, including the DSPs, PLLs and the MII Management Register bits are set to their default states. Hardware reset is distinct from Software reset which only resets the standard MII Registers.
M17	$\overline{\text{SOFT_RESET}}$	I _{PU}	Soft Reset SOFT_RESET is an active low input, which places the VSC8224 in a low power state, which includes disabling the SerDes interface. Although the device is powered down; non-volatile, serial management interface registers retain their values.

9.12 System Clock Interface Pins

Table 9-9. System Clock Interface Pins

HSBGA Ball	Signal Name	Type	Description
R17	CLK125 _{MAC}	O _{ZC}	Reference Clock Output for MAC This pin serves as a 125MHz reference clock output, which can be used to drive a MAC or other external device. CLKOUT_{MAC} is powered by the VDDIO_{MAC} supply. This 125MHz clock output pin is enabled by default, but can be disabled via an MII register setting.
M18	OSCEN or CLK125 _{micro}	I _{PD} /O _{ZC}	OSCEN - Oscillator Enable OSCEN is sampled on the rising edge of $\overline{\text{RESET}}$ to determine if the on-chip oscillator circuit is enabled, or an external clock is to be used. When tied high through an external 10k pull-up resistor, the oscillator is enabled, allowing operation with an external 25MHz crystal. If OSCEN is tied low (or left floating), the oscillator circuit is disabled and the device must be supplied with either a 25MHz or 125MHz clock input to REFCLK (see EECLK or PLLMODE pin description for more details). CLK125_{micro} - Reference Clock Output for Microprocessor This pin serves as a 125MHz or 4MHz reference clock output, which can be used to drive a Microprocessor or other external device. CLK125_{micro} is powered by the VDDIO_{micro} supply. This 125MHz or 4MHz clock output pin is disabled by default, but can be enabled via an MII register setting.
D17	XTAL1 or REFCLK	I	XTAL1 - Crystal Oscillator Input If enabled by OSCEN high, a 25MHz parallel resonant crystal, with +/-50ppm frequency tolerance, should be connected across XTAL1 and XTAL2. 33pF capacitors should be connected from XTAL1 and XTAL2 to ground. PLLMODE should be left floating (or pulled low) on reset when a 25MHz crystal is used. REFCLK - PHY Reference Clock Input If enabled by OSCEN low, the reference input clock can either be a 25MHz (PLLMODE is low) or 125MHz (PLLMODE is high) reference clock, with a +/-50ppm frequency tolerance. See EECLK or PLLMODE pin description for more details.
D18	XTAL2	O _{CRYST}	Crystal Output 25MHz parallel resonant crystal oscillator output. 33pF capacitors should be connected from both XTAL1 and XTAL2 to ground when using a crystal. PLLMODE should be left floating (or tied low) on reset when using the 25MHz crystal. If not using a crystal, this output pin can be left floating if driving XTAL1/REFCLK with a reference clock.

9.13 LED Interface Pins

Table 9-10. LED Interface Pins

HSBGA Ball	Signal Name	Type	Description
A1, D3, E3, F3, G3 C5, C4, C3, B2, A2 G18, G17, G16, F18, F17 J18, J17, H18, H17, H16	LED[4:0]_3 LED[4:0]_2 LED[4:0]_1 LED[4:0]_0	O _{ZC}	LED - Direct-Drive LED Outputs After reset, these pins serve as the direct drive, low EMI, LED driver output pins that can indicate individual status per pin or can be configured to output a serial data stream. All LEDs are active-low and are powered by the VDD33 power supply. The function of each LED pin is configured either through CMODE hardware configuration pins (see Section 24.3: "CMODE Pin Configuration") or through MII Register 27.

9.14 JTAG Test Access Port Pins

Table 9-11. JTAG TAP Signal Descriptions

HSBGA Ball #	Signal Name	Type	Description
J16	TDI	I _{PUJTAG}	JTAG Test Data Serial Input Data. Serial test pattern data is scanned into the device on this input pin, which is sampled with respect to the rising edge of TCK. This pin should be tied high during normal chip operation.
K16	TDO	O _{ZC}	JTAG Test Data Serial Output Data. Serial test data from the VSC8224 is driven out of the device on the falling edge of TCK. This pin should be left floating during normal chip operation.
K18	TMS	I _{PUJTAG}	JTAG Test Mode Select. This input pin, sampled on the rising edge of TCK, controls the TAP (Test Access Port) controller's 16-state, instruction state machine. This pin should be tied high during normal chip operation.
K17	TCK	I _{PUJTAG}	JTAG Test Clock. This input pin is the master clock source used to control all JTAG test logic in the device. This pin should be tied high or left floating during normal chip operation.
L16	$\overline{\text{TRST}}$	I _{PUJTAG}	JTAG Reset. This active low input pin serves as an asynchronous reset to the JTAG TAP controller's state machine. As required by the JTAG standard, this pin includes an integrated on-chip pull-up resistor. Because of the internal pull-up, if the JTAG controller on the printed circuit board does <i>not</i> utilize the TRST signal, then the device will still function correctly when the $\overline{\text{TRST}}$ pin is left unconnected on the board. Alternatively, if the JTAG port of the VSC8224 is <i>not</i> used on the printed circuit board, then this pin should be tied to ground (VSSIO) with a pull-down resistor.

9.15 Analog Bias Pins

Table 9-12. Analog Bias Pins

HSBGA Ball	Signal Name	Type	Description
C9	REF_REXT	A _{BIAS}	REF_REXT - Reference External Resistor Bias pin connects to an external 2k Ω (1%) resistor to analog ground.
C10	REF_FILT	A _{BIAS}	REF_FILT - Reference Filter Filter internal reference to an external 1 μ F ($\pm 10\%$) capacitor to analog ground.

9.16 HSTL Voltage Reference Pins

Table 9-13. HSTL Voltage Reference Pins

HSBGA Ball	Signal Name	Type	Description
T3 R8 R10 R13	TXREF_3 TXREF_2 TXREF_1 TXREF_0	V _{REF}	If VDDIO _{MAC} = 1.5V : HSTL voltage reference level from MAC If VDDIO _{MAC} = 2.5V or 3.3V : Tie to GND.
R18	MICROREF	V _{REF}	If VDDIO _{micro} = 1.5V : HSTL voltage reference level from micro If VDDIO _{micro} = 2.5V or 3.3V : Tie to GND.

9.17 No Connect Pins

Table 9-14. No Connect Pins

HSBGA Ball	Signal Name	Type	Description
C6 C7 C15 E15 V1	NC NC NC NC NC	NC	These pins are no connects. Do not connect these pins together or to ground. Leave these pins unconnected (floating).

9.18 Power Supply Pins

Table 9-15. Power Supply Pins

HSBGA Ball	HSBGA Supply Name	Type	Nominal Supply Voltage (V)	Description
Digital I/O Power Supply Pins				
R5, R6, R7, R9, R11, R12	VDDIO _{MAC}	P	3.3V, 2.5V, 1.5V	The I/O power supplies on the VSC8224 are separated on the chip itself to facilitate support for different VDDIO supply voltages. These VDDIO supplies can be run independently at the voltages specified in the previous column.
L15	VDDIO _{micro}	P	3.3V, 2.5V, 1.5V	
K15	VDDIO _{ctl}	P	3.3V, 2.5V	
Digital Core Power Supply Pins				
H4, J4, P4, R4, R14, R15, J15, H15	VDDDIG	P	1.2V	Power for internal digital logic.
Analog Power Pins				
D4, L4, G15, F15, D13, D12, D11, D10, D9, D6, D5, C8, R16	VDD33	P	3.3V	General 3.3v analog power
E4, F4, H3, J3, M3, N3, R3, D15, D14	VDD12	P	1.2V	General 1.2v analog power, SerDes I/O power

Table 9-15. Power Supply Pins (continued)

HSBGA Ball	HSBGA Supply Name	Type	Nominal Supply Voltage (V)	Description
Ground Pins				
G[7:12], H[7:12], J[7:12], K[7:12], L[7:12], F2, P2, P3, G4, K4, K3, K2, L3, M4, N4, P15, N15, C14, C13, C12, C11, D8, D7	VSSS	G	0V	Ground for all blocks except parallel I/O
M7, M8, M9, M10, M11, M12, M15	VSSIO	G	0V	Ground for parallel I/O

9.19 Power Supply and Associated Functional Pins¹

Table 9-16. Power Supply and Associated Functional Pins

Power Supply Pins	Nominal Voltages	Associated Functional Pins
VDDIO _{MAC}	3.3V, 2.5V, 1.5V	TXD[3:0], TX_CTL, TX_CLK, RXD[3:0], RX_CTL, RX_CLK, TXREF_n, CLK125 _{MAC}
VDDIO _{micro}	3.3V, 2.5V, 1.5V	SOFT_RESET, RESET, MDINT_n, MDIO, MDC, MICROREF, CLK125 _{micro}
VDDIO _{ctl}	3.3V, 2.5V	TDI, TDO, TMS, TCK, TRST, EEDAT, EECLK
VDD12	1.2V	TDN_n, TDP_n, RDN_n, RDP_n, RCN_n, RCP_n
VDD33	3.3V	SIGDET_n, LED[4:0], CMODE[7:0], TXVN, TXVP, REF_REXT, REF_FILT, XTAL1

¹While certain function pins may not be used for a specific application, all power supply pins must be connected to their respective voltage input. For example, if the JTAG and EEPROM pins are not used, VDDIO_{ctl} must still be connected to 3.3V or 2.5V power supply.

10 System Schematics

10.1 RGMII with Dual Media System Schematic

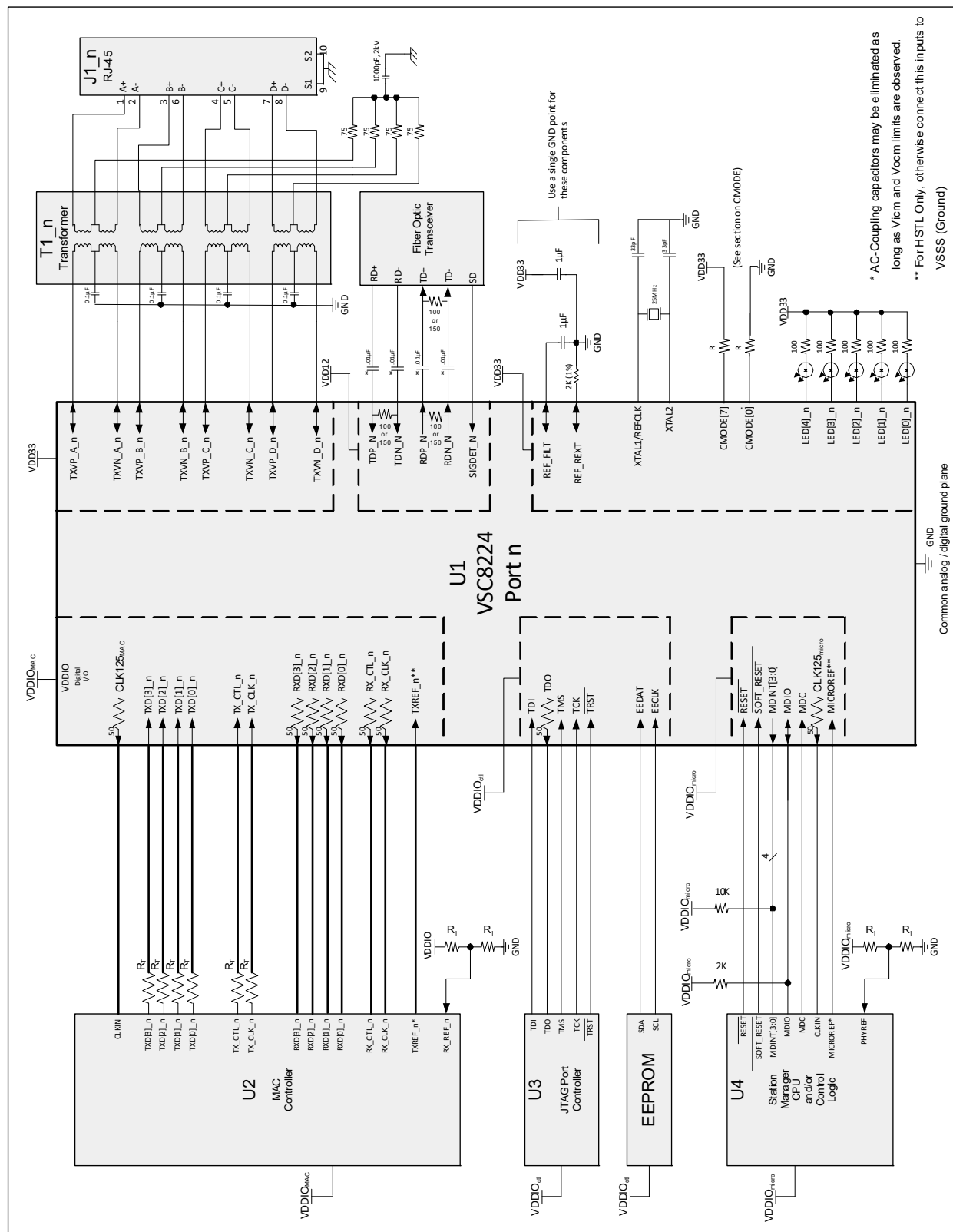


Figure 10-1. General System Schematic (shown with RGMII and 3.3V I/O)

10.2 Input Clock Options

The VSC8224 can be driven by three different clocking schemes providing the end user with design flexibility for clock strategy.

10.2.1 Crystal Clock Option

A 25 MHz crystal can be connected to the XTAL1 and XTAL2 pins as described in [Section 9.12: “System Clock Interface Pins”](#). The OSCEN must be pulled high and the PLLMODE can be left floating. The crystal clock option is not recommended or supported for use in dual media applications (that is, RGMII-to-dual-media supporting copper or fiber media). Please refer to Figure 10-2.

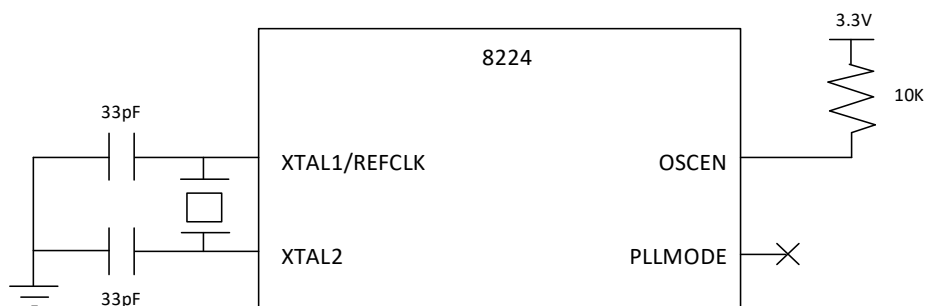


Figure 10-2. Crystal Clock Option

10.2.2 25MHz Reference Clock Option

A 25 MHz reference clock can be connected to XTAL1, with XTAL2 left floating as described in [Section 9.12: “System Clock Interface Pins”](#). The OSCEN and the PLLMODE can be left floating. Please refer to Figure 10-3.

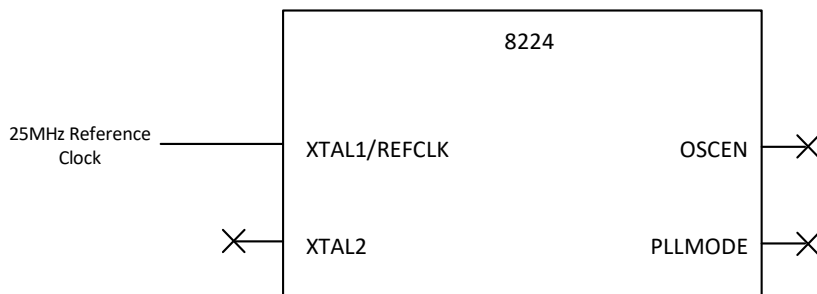


Figure 10-3. 25MHz Reference Clock Option

10.2.3 125MHz Reference Clock Option

A 125 MHz reference clock can be connected to XTAL1, with XTAL2 left floating as described in [Section 9.12: “System Clock Interface Pins”](#). The OSCEN can be left floating and the PLLMODE will need to be pulled high. Please refer to Figure 10-4.

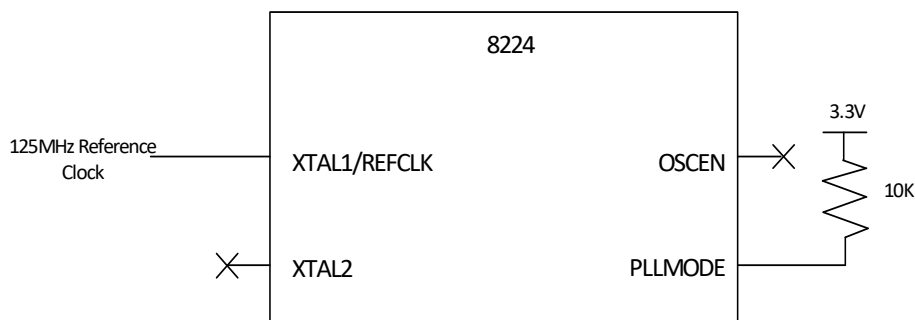


Figure 10-4. 125MHz Reference Clock Option

10.3 Analog Bias Pins Configuration

For proper operation, the VSC8224 must generate an on-chip band gap reference voltage at the REF_FILT pin. For this, the following components are required for each VSC8224 in the system as specified in [Section 9.15: "Analog Bias Pins"](#).

- 2.00k Ω resistor, 1% tolerance.
- Two 1 μ F capacitors, with 10% tolerance or better.

The resistor will connect between the REF_REXT pin and ground. One 1 μ F capacitor will connect between the REF_FILT pin and ground. The other capacitor will connect between VDD33 voltage supply and ground.

For best performance, special consideration for the ground connection of the voltage reference circuit is necessary to prevent bus drops which would cause inaccuracy in the reference voltage. Each of these ground connections should join together at a small common area and then a short trace should then connect this area to the main ground plane (Refer to Figure 10-5). All of these components should be placed as close as possible to the VSC8224.

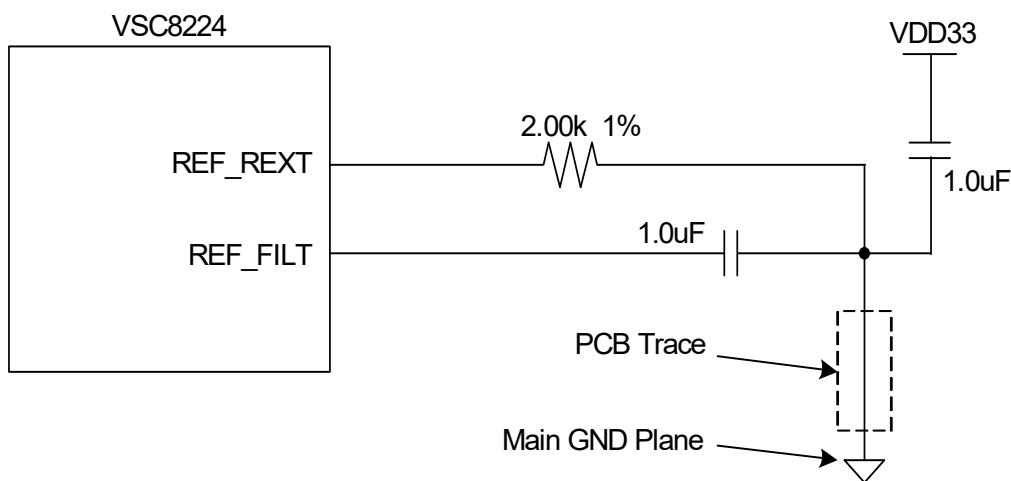


Figure 10-5. Analog Bias Pins Ground Connection Diagram

10.3.1 Crystal Clock Option with Dual Media

The crystal clock option in the VSC8224 device is not recommended or supported for use in dual media applications such as RGMII-to-dual media supporting copper or fiber media.

11 Twisted Pair Interface

The twisted pair interface on the VSC8224 is fully compliant with the IEEE802.3-2000 specification for CAT-5 media. The VSC8224 PHY, unlike other traditional Gigabit PHYs, has all passive components (required to connect the PHY's CAT-5 interface to an external 1:1 transformer) fully integrated into the device. This reduces the number of components in a design and greatly simplifies the layout of this interface. The connection of the twisted pair interface is shown in Figure 11-1.

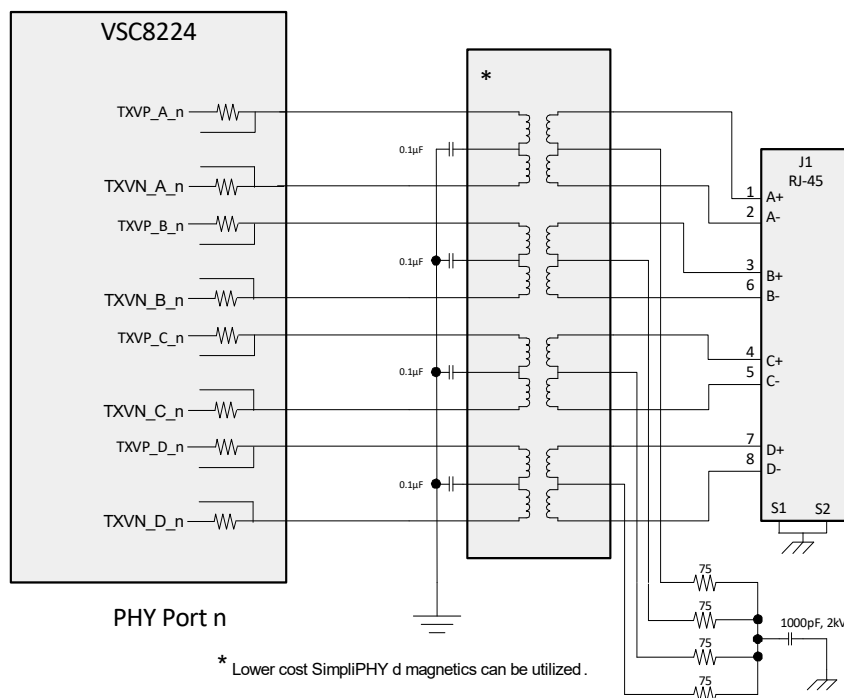


Figure 11-1. VSC8224 Twisted Pair Interface

For more information about the VSC8224 twisted pair interface, see the application note “*SimpliPHY’d Magnetics for EMI Control*”.

11.1 Twisted Pair Autonegotiation (IEEE802.3 Clause 28)

The VSC8224 supports twisted pair autonegotiation, as defined in IEEE 802.3-2002 clause 28. This process evaluates the advertised capabilities of the local PHY and its link partner to determine the best possible operating mode. In particular, autonegotiation can determine speed, duplex, and MASTER/SLAVE modes for 1000BASE-T. Autonegotiation also allows the local MAC to communicate with the Link Partner MAC (via optional “Next-Pages”) to set attributes that may not be defined in the standard. If the link partner does not support autonegotiation, the VSC8224 will automatically use parallel-detect to select the appropriate link speed.

Clause 28 twisted-pair autonegotiation can be disabled by clearing MII Register bit 0.12. If autonegotiation is disabled, the operating speed and duplex mode of the VSC8224 is determined by the state of MII Register bits 0.6, 0.13 and MII Register bit 0.8.

11.2 Twisted Pair Auto MDI/MDI-X Function

For trouble-free configuration and management of Ethernet links, the VSC8224 includes robust Automatic Crossover Detection functionality for all three speeds on the twisted pair interface (10BASE-T, 100BASE-TX, and 1000BASE-T) – fully compliant with the IEEE standard. In addition, the VSC8224 detects and corrects polarity errors on all MDI pairs, which is not required by the standard. Both the Automatic MDI/MDI-X and Polarity Correction functions are enabled by default. However, complete user

control of these two features is contained in MII Register bit 18.5 and MII Register bit 18.4. Status bits for each of these functions are indicated in MII Register 28.

The VSC8224's Automatic MDI/MDI-X algorithm will successfully detect, correct, and operate with any of the MDI wiring pair combinations listed in the following table:

Table 11-1. Accepted MDI Pair Connection Combinations

MDI Pair Connection Combinations Accepted by VSC8224	RJ-45 Connections				Comments
	1,2	3,6	4,5	7,8	
	A	B	C	D	Normal MDI mode
	B	A	D	C	Normal MDI-X mode
	A	B	D	C	MDI mode Pair swap on C and D pairs
	B	A	C	D	MDI-X mode Pair swap on C and D pairs

11.3 Auto MDI/MDI-X in Forced 10/100 Link Speeds

The VSC8224 includes the ability to perform Auto MDI/MDI-X even when auto-negotiation is disabled (MII Register 0.12 = 0) and the link is forced into 10/100 link speeds. In order to enable this feature, additional MII register write settings are also needed in the following order:

To enable Auto MDI/MDI-X in forced 10/100 link speeds:

- Write MII Register 31 = 0x52b5
- Write MII Register 18 = 0x0012
- Write MII Register 17 = 0x2803
- Write MII Register 16 = 0x87fa
- Write MII Register 31 = 0x0000

To disable Auto MDI/MDI-X in forced 10/100 link speeds:

- Write MII Register 31 = 0x52b5
- Write MII Register 18 = 0x0012
- Write MII Register 17 = 0x3003
- Write MII Register 16 = 0x87fa
- Write MII Register 31 = 0x0000

11.4 Twisted Pair Link Speed Downshift

In addition to automatic crossover detection, the VSC8224 supports an automatic link speed “downshift” option for operation in cabling environments incompatible with 1000BASE-T. When this feature is enabled, the VSC8224 will automatically change its 1000BASE-T autonegotiation advertisement to the next slower speed after a set number of failed attempts at 1000BASE-T. This is especially useful in setting up networks using older cable installations which may include only pairs A and B and not pairs C and D. The link speed downshift feature is configured and monitored through MII Register bits 20E.4:1.

11.5 SimpliPHY'd Magnetics

Traditional Gigabit Ethernet transceivers require an average transformer that contains 12 internal core magnetics and their additional wire windings. These transformers size and design create a significant increase in cost as compared to original 10/100BT solutions that only need 6 core magnetics. Using the VSC8224's patented fully balanced voltage-mode line transceivers, system designers can take advantage of using lower cost, four core magnetics in Gigabit Ethernet applications. SimpliPHY'd Magnetics can be both smaller and significantly less expensive than the traditional 12 core transformer solutions. For more information, please refer to the SimpliPHY'd Magnetics and EMI Control applications note, available from the Microsemi website.

12 Transformerless Ethernet Operation for PICMG 2.16 and 3.0 IP-based Backplanes

The twisted pair interface supports 10/100/1000BT Ethernet for backplane applications such as those specified by the PICMG 2.16 and 3.0 specifications for 8-pin channels. With proper AC coupling, the typical category-5 transformer (magnetics) can be removed and replaced with capacitors. For more information, see the application note "*Transformerless Ethernet Concept and Applications*".

By enabling the PICMG reduced power mode (MII Register bit 24.12 = 1), power consumption can be reduced to under 600mW/port. For specific backplane applications it is possible for further reductions in power consumption (<500mW/port). To configure the device for this mode, the following MII register write settings are also needed in the following order:

- Write MII Register 31 = 0x2a30
- Write MII Register 22 = 0x4900
- Write MII Register 31 = 0x0000

13 Parallel MAC Interfaces

13.1 RGMII MAC I/F

RGMII MAC I/F mode clocks data at 125MHz in 1000BT mode, 25MHz in 100BT mode, or 2.5MHz in 10BT mode. The I/O power supply can be 3.3V, 2.5V, or 1.5V HSTL-compliant.

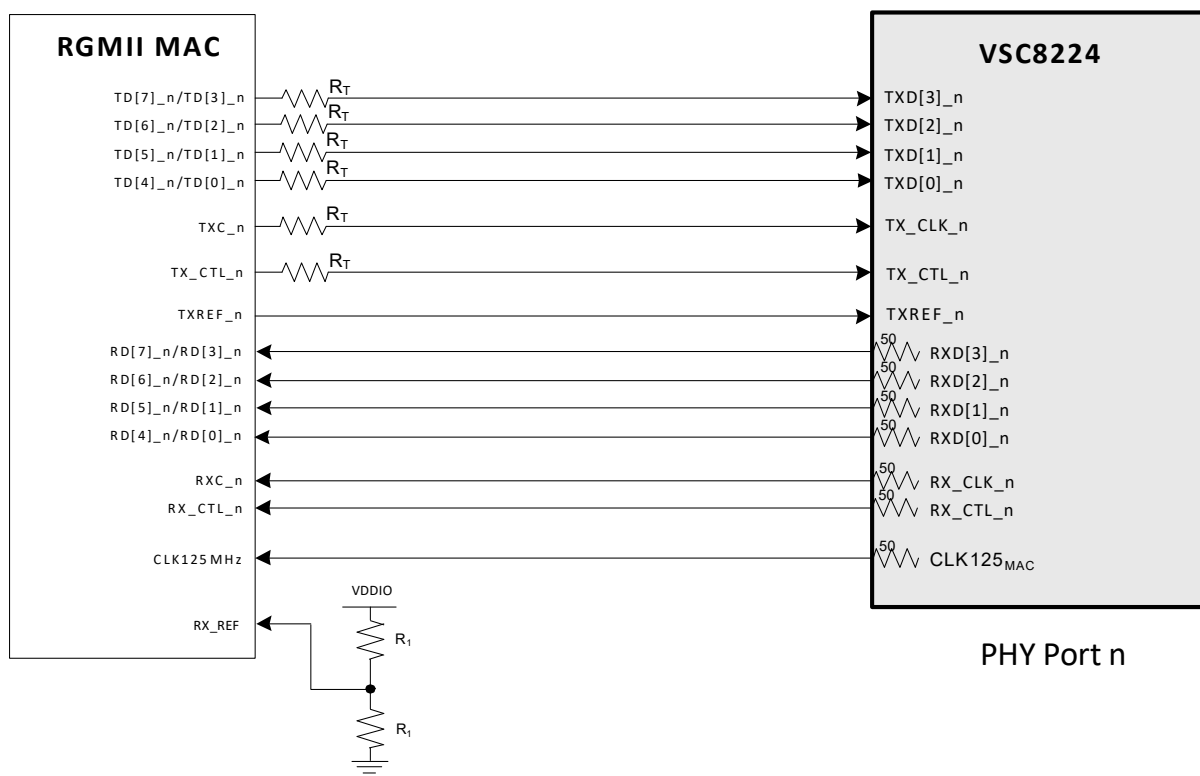


Figure 13-1. RGMII MAC Interface

Note:

- MAC TX lines are usually series-terminated close to the source (at the MAC), with R_T typically $\sim 22\Omega$.
- Since the VSC8224 includes on-chip, calibrated, series termination resistors, no external series termination resistors are required on the PCB.
- All PCB traces should be 50Ω controlled impedance traces.
- The VSC8224 includes innovative on-chip timing compensation circuitry to simplify PCB design and layout. Please refer to [Section 31.1: "RGMII Mode Timing"](#) for more information.
- RX_REF should be set to $VDDIO/2$ through an external resistor divider network (HSTL 1.5V I/O only).
- TXREF_n should be tied to ground if $VDDIO = 3.3V$ or $2.5V$.
- TXREF_n should be connected to the MAC's HSTL reference when $VDDIO = 1.5V$ HSTL.

13.2 RTBI MAC I/F

RTBI MAC I/F mode, selected by setting the MAC I/F selection bits to RTBI mode [Register 23.15:12](#), clocks data at 125MHz.

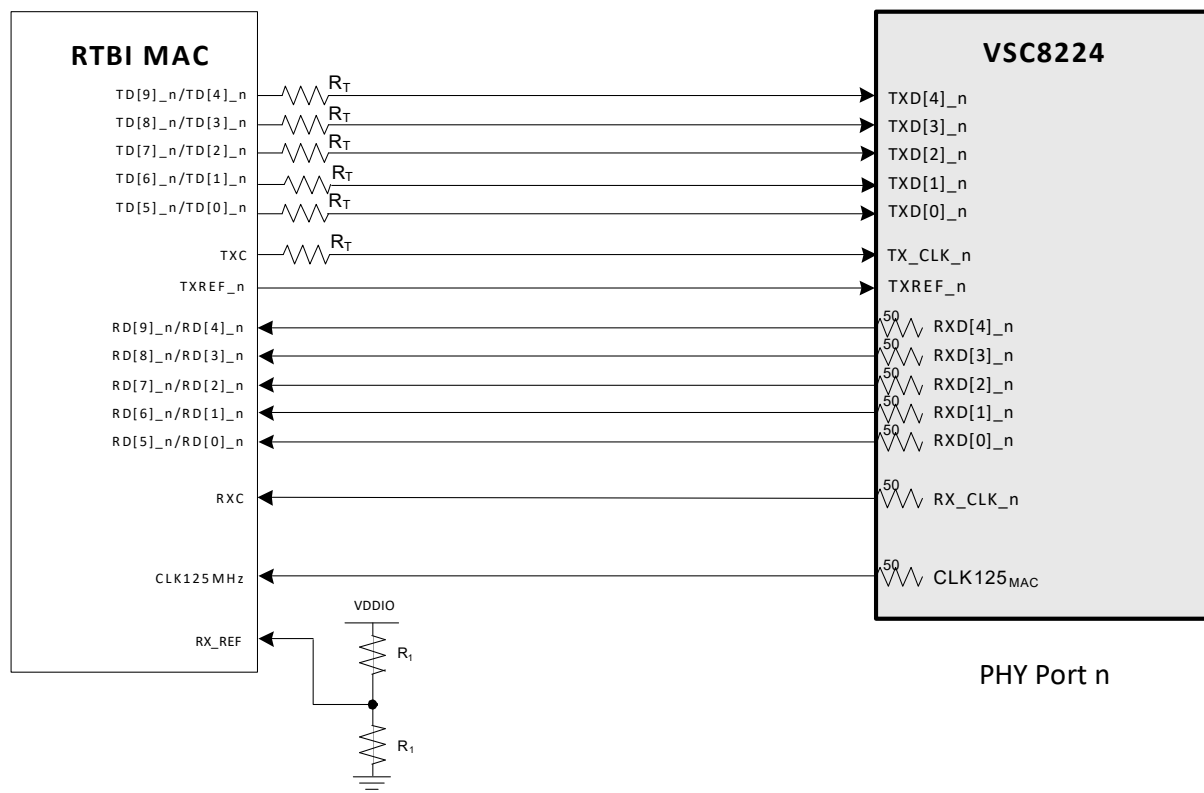


Figure 13-2. RTBI MAC Interface

Note:

- MAC TX lines are usually terminated on the source side (at the MAC), with R_T typically $\sim 22\Omega$.
- Since the VSC8224 includes on-chip, calibrated, series termination resistors, no external series termination resistors are required on the PCB.
- All PCB traces should be 50Ω controlled impedance traces.
- The VSC8224 includes innovative on-chip timing compensation circuitry to simplify PCB design and layout. Please refer to [Section 31.2: "RTBI Mode Timing"](#) for more information.
- RX_REF should be set to $VDDIO/2$ through an external resistor divider network (HSTL 1.5V I/O only).
- TXREF_n should be tied to ground if $VDDIO = 3.3V$ or $2.5V$.
- TXREF_n should be connected to the MAC's HSTL reference when $VDDIO = 1.5V$ HSTL.

14 High Speed Serial Interfaces

The VSC8224 contains quad SerDes, which can be used in parallel to the quad 10/100/1000BASE-T copper interfaces, to connect to 1000BASE-X compatible optical modules and system backplanes.

The 1000BASE-X SerDes function is selected by setting the appropriate MAC I/F bits, or by using the CMODE[7:0] hardware configuration pins. See [Section 24.3: "CMODE Pin Configuration"](#) for specific configuration information.

Depending on the operating configuration chosen, the 1000BASE-X SerDes can perform the following functions:

14.1 RGMII/RTBI to 1000BASE-X Serial Media Mode

If the RGMII or RTBI MAC interface is enabled with the 1000BASE-X SerDes function, the VSC8224 transfers data between the parallel MAC interface and the serial interface. This performs the same function as traditional 1000BASE-X SerDes devices.

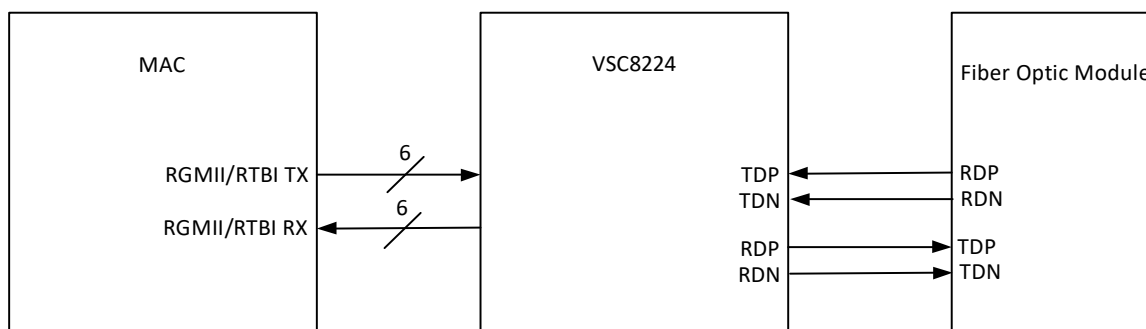


Figure 14-1. RGMII to 1000BASE-X SerDes (fiber media application shown)

15 Dual Media Interface -- RGMII to Auto Media Sense (AMS)

In this operating mode the MAC operation chosen is set to RGMII. The media interface can either be set to CAT-5 or 1000BASE-X Serial Media Modes automatically.

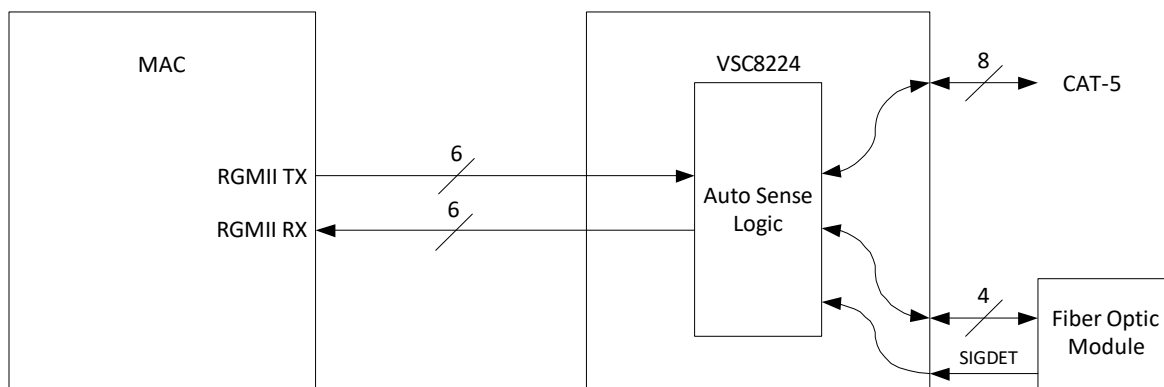


Figure 15-1. RGMII to Auto Media Sense (AMS)

The active media mode chosen is based on the AMS preferences set by MII Register 23. Active media mode preferences can be set as follows:

- 1000BASE-X serial media preference.
- CAT-5 media preference.
- No Preference (first linked-up media interface is the active media source).

For the fiber/CAT-5 media preference settings, when both media interfaces attempt to establish a link, the preferred media interface will override a link up of the non-preferred media interface. For example, when Fiber preference is set but not linked, if CAT5 media then establishes a link, CAT5 will become the active media interface. Once Fiber establishes link, the CAT5 interface will drop its link (since Fiber media is the preferred setting). Fiber will be the active media source until it loses its link.

For the No Preference setting, the preferred link in this case depends on which media interface established their link, first. The first linked media interface is the active media source until its link goes down. When the link goes down in no preference mode, the media interface to first re-establish a link will become the active media source. For example, if CAT-5 media was to first link, even if Fiber attempts to link some time after the CAT5 link, CAT5 will remain the active media source. If CAT-5 loses the link and Fiber can link up before the CAT5 interface, then Fiber becomes the preferred interface until the Fiber link is lost.

Table 15-1. RGMII-AMS Media Preference Table

AMS Preference Setting ¹	CAT-5 Linked, Fiber Not Linked	Fiber Linked, CAT-5 Not Linked	CAT-5 Linked, Fiber attempting to Link	Fiber Linked, CAT-5 attempting to Link	Both CAT-5 and Fiber attempting to Link
Fiber Media Preference	CAT-5 Media	Fiber Media	Fiber Media	Fiber Media	Fiber Media
CAT-5 Media Preference	CAT-5 Media	Fiber Media	CAT-5 Media	CAT-5 Media	CAT-5 Media
No Media Preference	CAT-5 Media	Fiber Media	CAT-5 Media	Fiber Media	Fiber or CAT-5 Media ²

¹ For backplane applications, set CAT-5 media preference and pull SIGDET input high with a pull-up resistor.

² If no preference is the AMS preference setting, then the preferred link will be the media interface that establishes its link, first and will be the active media source until it loses link.

16 Serial Management Interface (SMI)

The VSC8224 includes a Serial Management Interface, or “SMI”, that is fully compliant with the IEEE 802.3-2000 specifications. The SMI interface provides access to various status and control registers within the VSC8224. This MII Register set is comprised of a block of thirty-two 16-bit registers, which are segmented into two pages: PAGE0 (main page) and PAGE1 (extended page). Refer to [Section 25.3: “MII Extended Page Registers”](#) for more information. Registers 0 through 10, in addition to Register 15, (all main page) are required for IEEE compliance. The VSC8224 implements all IEEE-required registers, in addition to several others, providing additional performance-monitoring capabilities. See [Section 26: “MII Register Descriptions”](#) for more information.

The SMI is a two pin, synchronous serial interface, with bidirectional data on MDIO being clocked on the rising edge of MDC. The SMI can be clocked at a rate from 0 to 12.5MHz, depending on the total load on MDIO. An external pull-up is required on MDIO; it is typically 2kΩ, but depends on the total load on MDIO.

Data is transferred over the SMI using 32-bit frames with an optional and arbitrary length preamble. The SMI frame format is described in the following table.

Table 16-1. SMI Frame Format

	Direction from VSC8224	Preamble	Start of Frame	Op Code	PHY Address	Register Address	Turn-Around	Data	Idle
# of bits		1+	2	2	5	5	2	16	?
Read	Output	Z's	ZZ	ZZ	Z's	Z's	Z0	data	Z's
	Input	1's	01	10	addr	addr	ZZ	Z's	Z's
Write	Output	Z's	ZZ	ZZ	Z's	Z's	ZZ	Z's	Z's
	Input	1's	01	01	addr	addr	10	data	Z's

- **Idle:** During idle, the MDIO node goes to a high-impedance state. This allows an external pull-up resistor to pull the MDIO node up to a logical “1” state. Since idle mode should not contain any transitions on MDIO, the number of bits is undefined during idle.
- **Preamble:** For the VSC8224, the preamble is optional. By default, preambles are not expected or required. The preamble is a string of “1”s. If it exists, the preamble must be at least one bit, but otherwise may be arbitrarily long. See [MII Register 1.6](#) for more information.
- **Start of frame:** A “01” pattern indicates the start of frame. If these bits are anything other than “01”, all following bits are ignored until the next “preamble” pattern is detected.
- **Operation code:** A “10” pattern indicates a read. A “01” pattern indicates a write. If these bits are anything other than “01” or “10”, all following bits are ignored until the next “preamble” pattern is detected.
- **PHY address:** The next five bits are the PHY address. The VSC8224 responds to a message frame only when the received PHY address matches its physical address. Its physical address has 5 bits, 4:0. Bits 4:2 is set by the CMODE pin configuration setting. Bits 1:0 represent which PHY within the device is being addressed.
- **Register address:** The next five bits are the register address.
- **Turn-around:** The next two bits are “turn-around” (TA) bits. They are used to avoid contention when a read operation is performed on the MDIO. During read operations, the VSC8224 will drive the second TA bit, which is a logical “0”.
- **Data:** The next sixteen bits are data bits. When data is being read from the PHY, data is valid at the output of the PHY from one rising edge of MDC to the next rising edge of MDC. When data is being written to the PHY, data must be valid around the rising edge of MDC.
- **Idle:** The sequence is repeated.

The following two figures diagram SMI read and SMI write operations.

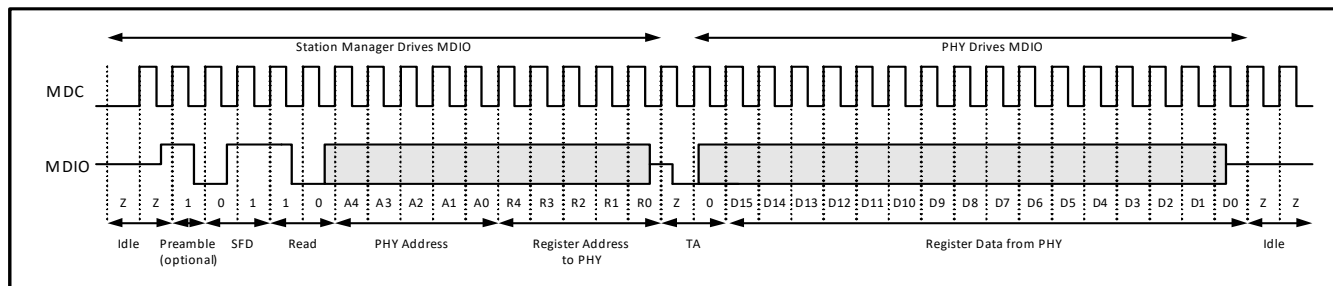


Figure 16-1. SMI Read Frame

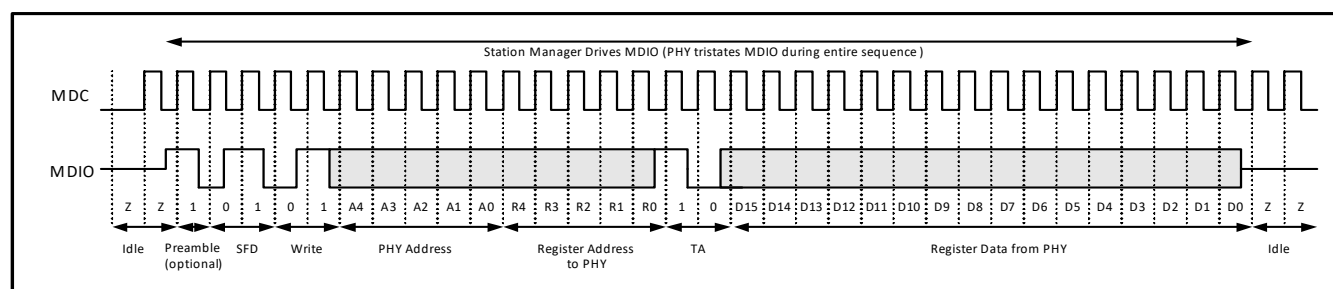


Figure 16-2. SMI Write Frame

16.1 SMI Interrupt

The SMI includes an output signal MDINT_n for signalling the Station Manager when certain events occur in the PHY. A separate MDINT_n pin is included for each PHY in the VSC8224. Each MDINT_n pin can be configured for open-drain (active-low), or open-source (active-high) by tying the pin to either a pull-up resistor to VDDIO_{micro} (see Figure 16-3), or to a pull-down resistor to GND (see Figure 16-4). If only one interrupt pin is required, each MDINT_n pin can be tied together to a single pull-up or pull-down resistor in a wired-OR configuration.

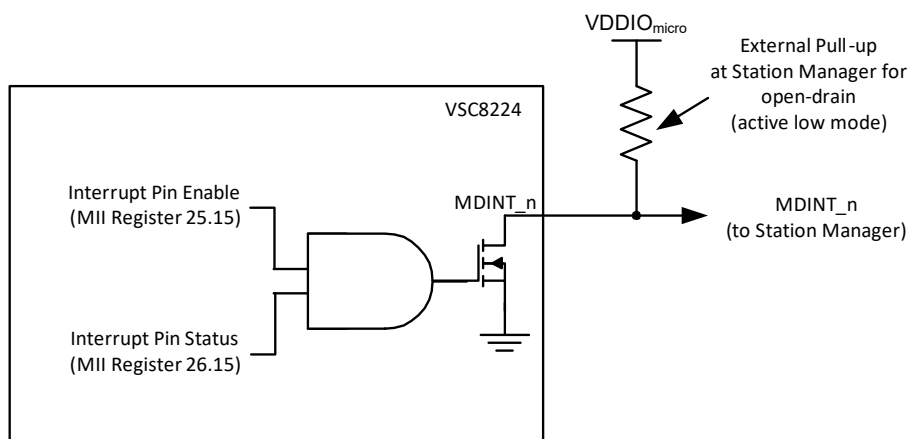


Figure 16-3. Logical Representation of Open-Drain (Active-Low) MDINT_n Pin

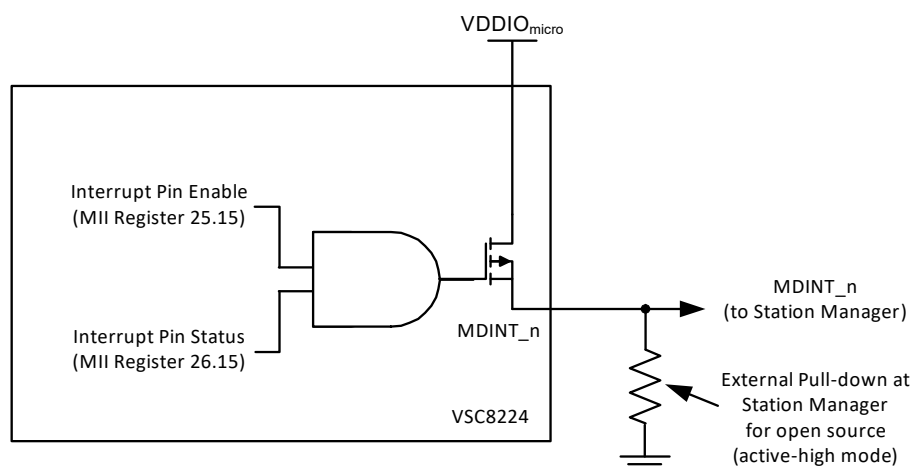


Figure 16-4. Logical Representation of Open-Source (Active-High) MDINT_n Pin

When the VSC8224 PHY generates an interrupt, the MDINT_n pin is asserted (driven either high or low, depending on the external resistor connection) if the interrupt pin enable bit ([MII Register 25.15](#)) is set.

17 Parallel LED Interface

The VSC8224 contains dedicated pins to drive 5 LEDs directly for each PHY port.

For power savings, all LED outputs can be configured to pulse at 5kHz with a 20% duty cycle by setting LED pulsing enable (MII Register 27.4 = 1). All LED outputs are active-low, and driven with 3.3V from the VDD33 power supply.

Four different functions have been assigned to each LED pin. Selection is done through CMODE hardware configuration (see [Section 24.3](#)), or through [Register 27 \(1Bh\) – LED Control Register](#). The functions are assigned according to the following table:

Table 17-1. LED Function Assignments

LED Configuration Bits	MII Register Bit	Value	LED Function Selection
LED Pin 4 Config [1:0]	27.15:14	11	Link/Activity
		10	Fault
		01	Activity
		00	Duplex/Collision
LED Pin 3 Config [1:0]	27.13:12	11	RX
		10	Serial Media (such as Fiber)
		01	Duplex/Collision
		00	Collision
LED Pin 2 Config [1:0]	27.11:10	11	TX
		10	Link/Activity
		01	Duplex/Collision
		00	Link10/Activity
LED Pin 1 Config [1:0]	27.9:8	11	Link100/1000/Activity
		10	Link/Activity
		01	Link10/100/Activity
		00	Link100/Activity
LED Pin 0 Config [1:0]	27.7:6	11	RX
		10	Fault
		01	Link/Activity (with serial output on LED pins 1 and 2)
		00	Link1000/Activity

For flexibility, 14 LED output functions can be selected for each PHY port. These functions are summarized in the following table:

Table 17-2. LED Functions

Function LED	LED State	Description
Link1000/Activity	1	No link in 1000BASE-T or 1000BASE-X
	0	Valid 1000BASE-T link or 1000BASE-X link
	Pulse-stretch/Blink ^{1,2}	(optional) Valid 1000BASE-T link and activity present
Link100/Activity	1	No link in 100BASE-Tx
	0	Valid 100BASE-Tx link
	Pulse-stretch/Blink ^{1,2}	(optional) Valid 100BASE-Tx link and activity present

Table 17-2. LED Functions (continued)

Function LED	LED State	Description
Link10/Activity	1	No link in 10BASE-T
	0	Valid 10BASE-T link
	Pulse-stretch/Blink ^{1,2}	(optional) Valid 10BASE-T link and activity present
Link10/100/Activity	1	No link in 10BASE-T or 100BASE-Tx
	0	Valid 10BASE-T link or valid 100BASE-Tx link
	Pulse-stretch/Blink ^{1,2}	(optional) Valid 10BASE-T link or valid 100BASE-Tx link and activity present
Link100/1000/Activity	1	No link in 100BASE-Tx or 1000BASE-T
	0	Valid 100BASE-Tx link or valid 1000BASE-T link
	Pulse-stretch/Blink ^{1,2}	(optional) Valid 100BASE-Tx link or valid 1000BASE-T link and activity present
Link/Activity	1	No link in any speed
	0	Valid link in any speed
	Pulse-stretch/Blink ^{1,2}	Valid link in any speed and activity present
Collision	1	No collision detected
	Pulse-stretch/Blink ²	Collision detected
Activity	1	No activity present
	Pulse-stretch/Blink ²	Activity present
Serial Media	1	No valid 1000BASE-X link established
	0	Serial media detected on SerDes interface and valid 1000BASE-X link established
Fault	1	No IEEE Clause 37/28 autonegotiation fault
	0	IEEE Clause 37/28 autonegotiation fault
Serial	**	See Section 18: "Serial LED Output"
Duplex/Collision	1	Link established in half-duplex mode, or no link established
	0	Link established in full-duplex mode
	Pulse-stretch/Blink ^{2,3}	(optional) Link established in half duplex mode and collision present
Rx	1	No activity on Rx side
	Pulse-stretch/blink ²	Activity present on Rx side
Tx	1	No activity on Tx side
	Pulse-stretch/blink ²	Activity present on Tx side

¹ Link functions can be combined with Activity function using an option bit below.² Function can either blink or be pulse-stretched when active. This behavior is selected using an option bit below.³ Duplex function can be combined with Collision function using an option bit below.

In addition to function selection, several option bits (found in MII Register 27) are available for the LED outputs. These are summarized below:

Table 17-3. LED Output Options

LED Option Bits	II Register Bit	Value	LED Function Selection
LED Blink/Pulse-Stretch Rate	27.5	1	10Hz blink rate/ 100ms pulse-stretch
		0	5Hz blink rate/ 200ms pulse-stretch
LED Pulsing Enable	27.4	1	When active, LED outputs will be pulsed at 5KHz, 20% duty cycle for power savings
		0	When active, LED outputs will remain at a static low
LED Pulse-Stretch/Blink Select	27.3	1	Collision, Activity, Rx and Tx LED outputs will be pulse-stretched when active
		0	Collision, Activity, Rx and Tx LED outputs will blink when active
LED combine LINK status with Activity	27.2	1	Link LEDs indicate link status only
		0	Link LEDs will blink or flash when activity is present. Blink/flash behavior is selected by Pulse-Stretch Enable bit.
LED combine LINK10/100/1000 status with Activity	27.1	1	Link10, Link100, Link1000, Link10/100, Link 100/1000 LEDs indicate link status only
		0	Link10, Link100, Link1000, Link10/100, Link 100/1000 LEDs will blink or pulse-stretch when activity is present. Blink/pulse-stretch behavior is selected by Blink/Pulse-Stretch option bit.
LED combine Collision with Duplex status	27.0	1	Duplex LED indicates duplex status only
		0	Duplex LED will blink or pulse-stretch when collision is present. Blink/pulse-stretch behavior is selected by Blink/Pulse-Stretch option bit.

18 Serial LED Output

A serial output option is available which allows access to all LED signals through two pins. This option is selected by setting LED Pin 0 configuration bits to 01 on PHY0. In this mode, LED[1]_0 acts as the serial data pin and LED[2]_0 acts as the serial clock pin. These two pins will then output LED status for all 4 PHYs. The serial mode will clock out the 44 LED status bits on the rising edge of the serial clock.

The serial bitstream outputs each LED signal as shown by the table below, beginning with PHY0 and ending with PHY3. The behavior of each LED signal is described in [Table 17-2: "LED Functions"](#). The individual signals shall be clocked out in the following order:

Table 18-1. Serial LED Output Data

PHY0	PHY1	PHY2	PHY3
1. Link1000/Activity	12. Link1000/Activity	23. Link1000/Activity	34. Link1000/Activity
2. Link/Activity	13. Link/Activity	24. Link/Activity	35. Link/Activity
3. Link100/Activity	14. Link100/Activity	25. Link100/Activity	36. Link100/Activity
4. Activity	15. Activity	26. Activity	37. Activity
5. Link10/Activity	16. Link10/Activity	27. Link10/Activity	38. Link10/Activity
6. Duplex/Collision	17. Duplex/Collision	28. Duplex/Collision	39. Duplex/Collision
7. Tx	18. Tx	29. Tx	40. Tx
8. Collision	19. Collision	30. Collision	41. Collision
9. Rx	20. Rx	31. Rx	42. Rx
10. Fault	21. Fault	32. Fault	43. Fault
11. Serial Media Link	22. Serial Media Link	33. Serial Media Link	44. Serial Media Link

19 Test Mode Interface (JTAG)

The VSC8224 supports the Test Access Port and Boundary Scan Architecture IEEE 1149.1 standards. The device includes an IEEE 1149.1 conformant test interface, often referred to as a “JTAG TAP Interface”. IEEE 1149.1 defines test logic to provide standardized test methodologies for:

- testing the interconnections between integrated circuits once they have been assembled onto a printed circuit board or other substrate,
- testing the integrated circuit itself during IC and systems manufacture, and
- observing or modifying circuit activity during the component’s normal operation.

The JTAG Test interface logic on the VSC8224, accessed through a Test Access Port (TAP) interface, consists of a boundary-scan register and other logic control blocks. The TAP controller includes all IEEE-required signals (TMS, TCK, TDI, and TDO), in addition to the optional asynchronous reset signal $\overline{\text{TRST}}$. Refer to [JTAG TAP Signal Descriptions](#) section for additional information about these pins.

The following figure diagrams the TAP and Boundary Scan Architecture.

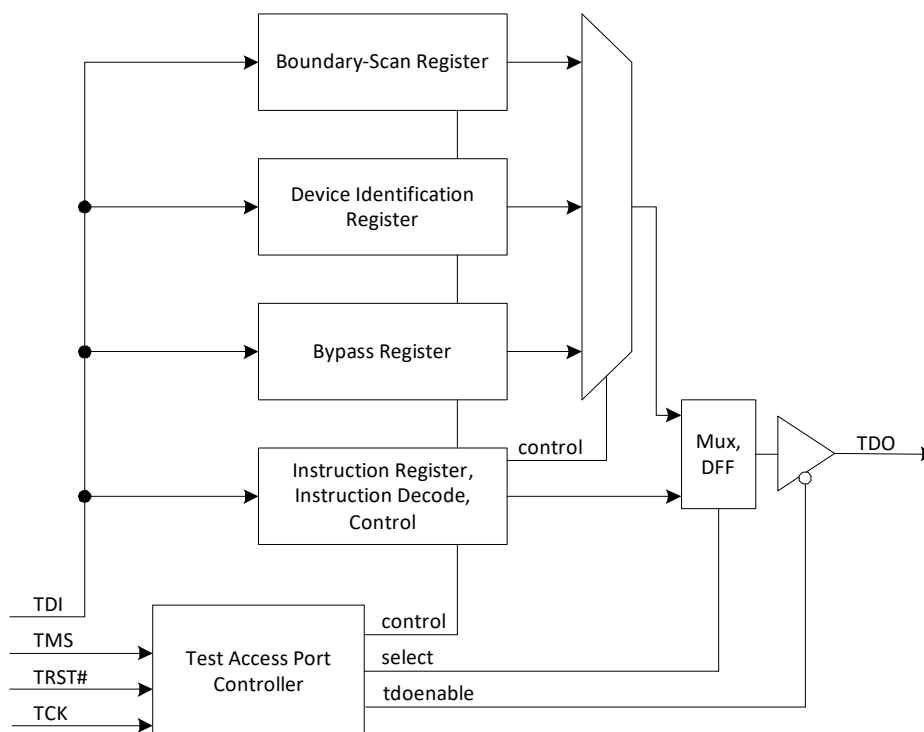


Figure 19-1. Test Access Port and Boundary Scan Architecture

The VSC8224 also includes the optional Device Identification Register, shown in the following table, which allows the manufacturer, part number, and version number of the device to be determined through the TAP Controller. See Chapter 11 of

the IEEE 1149.1-1990 specifications for more details. Also, note that some of the information in the identification register is duplicated in the IEEE-specified bit fields in [MII Register 3 \(PHY Identifier Register #2\)](#).

Table 19-1. JTAG Device Identification Register Description

Description	Device Version Number (or Revision Code)	Part Number (or Model Number)	Microsemi's Manufacturer Identity	LSB
Bit Field	31 - 28	27 - 12	11 - 1	0
Binary Value	Silicon revision C = 0010	1000 0010 0010 0100	001 1001 1000	1

19.1 Supported Instructions and Instruction Codes

After a TAP reset, the Device Identification Register is serially connected between TDI and TDO by default. The TAP Instruction Register is loaded either from a shift register (when a new instruction is shifted in), or, if there is no new instruction in the shift register, a hard-wired default value of 0110 (IDCODE) is loaded. Using this method, there is always a valid code in the instruction register, and the problem of toggling instruction bits during a shift is avoided. Unused codes are mapped to the BYPASS instruction.

The VSC8224 supports the instruction codes listed in the following table and described below.

Table 19-2. JTAG Interface Instruction Codes

Instruction	Code	Selected Register	Register Width	Specification
EXTEST	0000	Boundary-Scan Register	196	Mandatory IEEE 1149.1
SAMPLE/PRELOAD	0001	Boundary-Scan Register	196	Mandatory IEEE 1149.1
IDCODE	0110	Device Identification Register	32	Optional IEEE 1149.1
CLAMP	0010	Bypass Register	1	Optional IEEE 1149.1
HIGHZ	0011	Bypass Register	1	Optional IEEE 1149.1
BYPASS	0111	Bypass Register	1	Mandatory IEEE 1149.1
NANDTEST	0101	Bypass Register	1	Optional IEEE 1149.1
Reserved	0100, 1000-1111			

EXTEST

The mandatory EXTEST instruction allows testing of off-chip circuitry and board-level interconnections by sampling input pins and loading data onto output pins. Outputs are driven by the contents of the boundary-scan cells, which have to be updated with valid values (with the PRELOAD instruction) prior to the EXTEST instruction.¹

SAMPLE/PRELOAD

The mandatory SAMPLE/PRELOAD instruction allows a snapshot of inputs and outputs during normal system operation to be taken and examined. It also allows data values to be loaded into the boundary-scan cells prior to the selection of other boundary-scan test instructions.

IDCODE

The optional IDCODE instruction provides the version number (bits 31:28), part number (bits 27:12), and Microsemi's manufacturer identity (bits 11:1) to be serially read from the **VSC8224**. See [Table 19-1: "JTAG Device Identification Register Description"](#) for the **VSC8224**-specific values for this instruction.

¹Following the use of this instruction, the on-chip system logic may be in an indeterminate state that will persist until a system reset is applied. Therefore, the on-chip system logic must be reset on return to normal (i.e., non-test) operation.

CLAMP

The optional CLAMP instruction allows the state of the signals driven from the component pins to be determined from the Boundary-Scan Register while the Bypass Register is selected as the serial path between TDI and TDO. While the CLAMP instruction is selected, the signals driven from the component pins will not change.¹

HIGHZ

The optional HIGHZ instruction places the component in a state in which *all* of its system logic outputs are placed in a high impedance state. In this state, an in-circuit test system may drive signals onto the connections normally driven by a component output without incurring a risk of damage to the component. This makes it possible to use a board where not all of the components are compatible with the IEEE 1149.1 standard.¹

BYPASS

The Bypass Register contains a single shift-register stage and is used to provide a minimum-length serial path (one TCK clock period) between TDI and TDO to bypass the device when no test operation is required.

NANDTEST

NANDTEST is an internal command used to activate the NAND Tree test mode.

19.2 Boundary-Scan Register Cell Order

All inputs and outputs are observed in the Boundary-Scan Register cells. All outputs are additionally driven by the contents of Boundary-Scan Register cells. Bidirectional pins have all three related Boundary-Scan Register cells: the input, the output, and the control. The full boundary scan cell order is available as a .BSD file format.

¹Following the use of this instruction, the on-chip system logic may be in an indeterminate state that will persist until a system reset is applied. Therefore, the on-chip system logic must be reset on return to normal (i.e., non-test) operation.

20 VeriPHY Cable Diagnostics

The VSC8224 includes a comprehensive suite of cable diagnostic functions that are available using SMI reads and writes. These functions enable a variety of cable operating conditions and status to be accessed and checked. The VeriPHY® suite has the ability to identify the cable length and operating conditions and to isolate common faults that can occur on Cat5 twisted pair cabling. For functional details of the VeriPHY® suite and the operating instructions, see the ENT-AN0125 PHY, Integrated PHY-Switch VeriPHY - Cable Diagnostics application note.

21 ActiPHY Power Management

In addition to the IEEE-specified power-down control bit (MII Register 0.11), the VSC8224 implements an ActiPHY™ power management mode. This mode enables support for power-sensitive applications such as laptop computers with Wake-on-LAN™ capability. It utilizes a signal-detect function that monitors the media interface for the presence of a link to determine when to automatically power-down the PHY. The PHY ‘wakes up’ at a programmable interval and attempts to ‘wake-up’ the link partner PHY by sending either a fast link pulse (FLP) over copper media or a Clause 37 restart signal over optical media¹.

The ActiPHY™ power management mode can be set at any time on a per port basis during normal operation by setting MII Register 28.6 = 1. When ActiPHY™ is enabled and the PHY is in the “Low Power” or “LP Wake-up” states, by default a 25MHz clock signal is sent out on the RX_CLK pin. This function can be disabled by setting MII Register Bit 23.5 = 0.

21.1 Operation in ActiPHY Mode

There are three PHY operating states when Enhanced ActiPHY™ mode is enabled:

- Low power state
- LP Wake up state
- Normal operating state (link up state)

The PHY switches between the low power state and LP wake up state at a programmable rate (sleep timer) until signal energy has been detected on the media interface pins. When signal energy is detected, the PHY enters the normal operating state. When the PHY is in the normal operating state and link is lost, the PHY returns to the low power state after the link status time-out timer has expired. After reset, the PHY enters the low power state.

When autonegotiation is enabled in the PHY, the ActiPHY™ state machine will operate as described above. If autonegotiation is disabled and the link forced to 10BT or 100BTX modes while the PHY is in the low power state, the PHY continues to transition between the low power and LP Wake up states until signal energy is detected on the media pins. At that time, the PHY transitions to the normal operating state and stays in that state even when the link is dropped. If autonegotiation is disabled while the PHY is in the normal operation state, the PHY stays in that state when the link is dropped and does not transition back to the low power state.

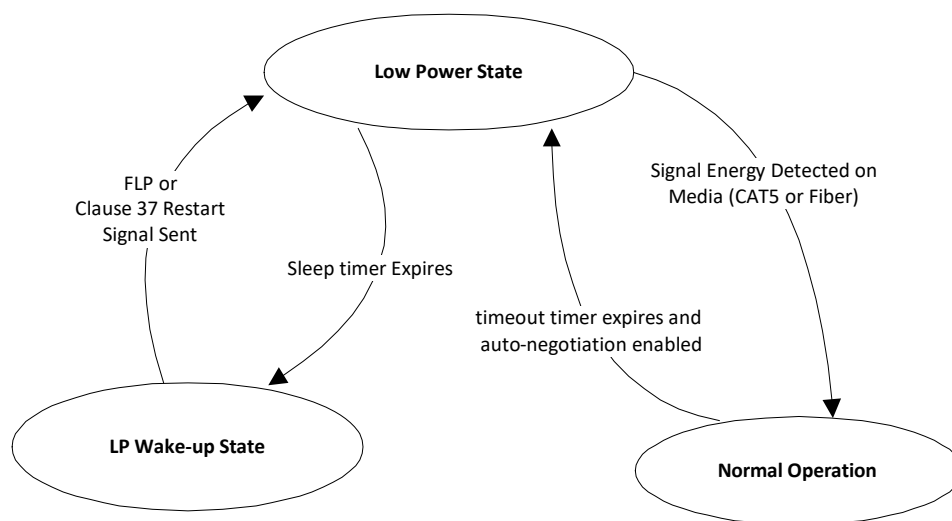


Figure 21-1. ActiPHY™ State Diagram

¹The ActiPHY is primarily designed for use with copper media. While it can be enabled for optical media modes (RGMII-to-Fiber or RGMII-to-AMS), some optical devices may not be able to respond to the Clause 37 restart signal. This ability—or the lack thereof—of the link partner to respond to the restart is the most significant factor in determining whether ActiPHY can be enabled for optical media modes.

21.2 Low power state

In the low power state, all major digital blocks are powered down. However the following functionality is provided:

- SMI interface (MDC, MDIO, $\overline{\text{MDINT_n}}$)
- CLK125_{MAC} and CLK125_{MICRO}

In this state, the PHY monitors the media interface pins for signal energy. The PHY comes out of low power state and transitions to the Normal operating state when signal energy is detected on the media. This happens when the PHY is connected to one of the following:

- Auto-negotiation capable link partner
- Auto-negotiation incapable (blind/forced) 100BTX only link partner
- Auto-negotiation incapable (blind/forced) 10BT only link partner
- Auto-negotiation capable optical link partner over fiber
- Auto-negotiation incapable (blind/forced) 1000BASE-X optical link partner over fiber
- Another PHY in Enhanced ActiPHY LP Wake Up state

In the absence of signal energy on the media pins, the PHY will transition from the low power state to the LP Wake up state periodically based on the programmable sleep timer. Two register bits (MII Register Bits 28.1:0) are provided to program the value of the sleep timer. The sleep timer can be programmed to 00 (1second), 01 (2 seconds), 10 (3 seconds) or 11 (4 seconds). The default value is 2 seconds. The actual sleep time duration is randomized by -80ms to +60ms to avoid two linked PHYs in ActiPHY™ mode from entering a lock-up state.

21.3 LP Wake up state

In this state, the PHY attempts to wake up the link partner. One complete FLP (Fast Link Pulse) is sent on both pairs A and B of the CAT5 media. For the optical Media, a base page of all zeros (Clause 37 restart signal) is sent for 30ms.

In this state the following functionality is provided-

- SMI interface (MDC, MDIO, $\overline{\text{MDINT_n}}$)
- CLK125_{MAC} and CLK125_{MICRO}

After sending signal energy on the relevant media, the PHY returns to the Low power state.

21.4 Normal operating state

In this state, the PHY establishes a link with a link partner. When the media is unplugged or the link partner is powered down, the PHY waits for the duration programmed through a link status time-out timer and then enters the low power state. The Link Status Time-out timer can be programmed to 00 (1second), 01 (2 seconds), 10 (3 seconds) or 11 (4 seconds). The default value for this timer is 2 seconds.

22 Ethernet In-line Powered Device Support

22.1 Cisco In-Line Powered Device Detection

This feature is used for detecting in-line powered devices in Ethernet network applications. The VSC8224's in-line powered device detection mode can be part of a system that allows for IP-phone and other devices such as wireless access points to receive power from an Ethernet cable, similar to office digital phones receiving power from a PBX (Private Branch Exchange) office switch via the phone cable. This can eliminate the need for an IP-Phone to have an external power supply since the Ethernet cable provides power. It also enables the in-line powered device to remain active during a power outage (assuming the Ethernet switch is connected to an uninterrupted power supply, battery, back-up power generator, etc.). Each of the 4 PHYs can independently perform in-line power detection. This mode is disabled by default and must be enabled for each PHY in order to perform in-line powered device detection. Please refer to additional information at http://www.cisco.com/en/US/products/hw/phones/ps379/products_tech_note09186a00801189b5.shtml.

22.2 In-Line Power Ethernet Switch Diagram

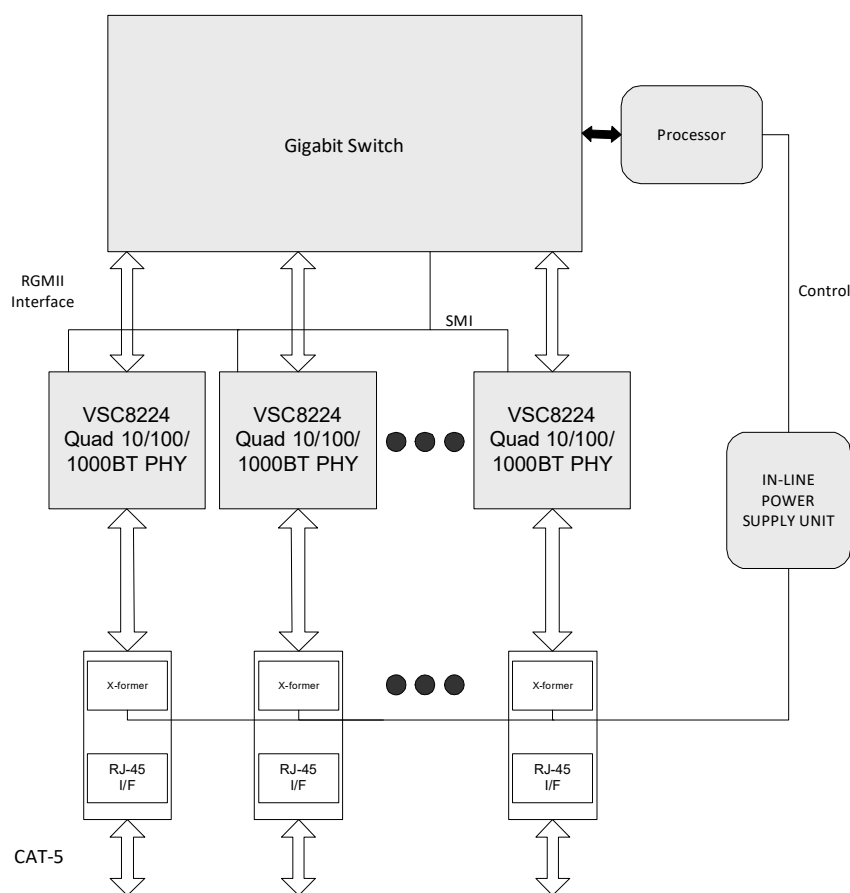


Figure 22-1. In-line Powered Ethernet Switch Diagram

22.3 In-Line Powered Device Detection (Cisco Method)

This section describes the flow process an Ethernet switch must perform in order to process in-line power requests made by a link partner (LP) capable of receiving in-line power.

1. The in-line powered device detection mode is enabled on each PHY through the serial management interface by setting MII Register bit 23E.10 = 1 and ensuring Auto-Negotiation Enable Bit (MII Register 0.12) = 1. The PHY will then start sending a special Fast Link Pulse (FLP) signal to the LP. MII Register 23E.9:8 will equal 00 during the search for devices needing in-line power.
2. The PHY monitors for the special FLP signal looped back by the LP. An LP device capable of receiving in-line power will loop back the special FLP pulses when it is in a powered-down state. This is reported when MII Register 23E.9:8 = 01. This can be verified as an in-line power detection interrupt by reading MII Register 26.9 = 1, which will subsequently be cleared and the interrupt de-asserted after the read. If an LP device does not loopback the special FLP after a specific time, then MII Register 23E.9:8 = 10.
3. If the PHY reports that the LP needs in-line power then the Ethernet switch needs to enable in-line power on this port externally of the PHY.
4. The PHY automatically disables in-line powered device detection after Event #4 above and now changes to the normal Auto-negotiation process. A link is then auto-negotiated and established when the Link status is set (MII Register bit 1.2 = 1)
5. In the event of a link down event (MII Register bit 1.2 = 0), the in-line power should be disabled to the in-line powered device external to the PHY. The PHY will disable the normal auto-negotiation process and re-enable in-line powered device detection mode.
6. An interrupt can also be asserted on the MDINT_n pin when in-line power is needed. This is set by MII Register 25.9 = 1 and ensuring MII Register 25.15 = 1 in order to enable the MDINT_n pin. As a result, any change of state of MII Register 23E.9:8 will cause an interrupt.

22.4 IEEE 802.3af (DTE Power via MDI)

The VSC8224 is fully compatible with switch designs which are intended for use in systems that supply power to the DTE (Data Terminal Equipment) via the MDI (Media Dependent Interface, or twisted pair cable), as specified by IEEE 802.3af standard (Clause 33).

23 Advanced Test Modes

23.1 Ethernet Packet Generator (EPG)

For system-level debugging and in-system production testing, the VSC8224 includes an Ethernet packet generator for 1000BASE-T testing. This can be used to isolate problems between the MAC and PHY and between a local PHY and remote link partner. It is intended for use with lab testing equipment or in-system test equipment only, and should not be used when the VSC8224 is connected to a live network.

To use the EPG, it must be enabled by writing a “1” to MII Register 29E.15. This effectively disables all MAC-interface transmit pins and selects the EPG as the source for all data transmitted onto the VSC8224 twisted pair interface. For this reason, packet loss will occur if the EPG is enabled during transmission of packets from MAC to PHY. The MAC receive pins will still be active when the EPG is enabled, however. If it is necessary to disable the MAC receive pins as well, this can be done by writing a “1” to MII Register bit 0.10.

When a “1” is written to [MII Register Bit 29E.14](#), the VSC8224 will begin transmitting IEEE802.3 layer-2 compliant packets with a data pattern of repeating 16-bit words set by [MII Register 30E](#). The source and destination addresses for each packet, packet size, interpacket gap, FCS state and transmit duration can all be controlled through [MII Register 29E](#). Note that if [MII Register Bit 29E.13](#) is cleared, [MII Register Bit 29E.14](#) will be cleared automatically after 30,000,000 packets have been transmitted.

23.2 CRC Counter

A bad-CRC counter is also available for all incoming packets for 1000BASE-T mode. This counter is available in [MII Register Bits 23E.7:0 - 1000BT CRC Counter](#) and is automatically cleared when read.

23.3 Far-end Loopback

Far-end loopback mode when enabled (MII Register bit 23.3 = 1) forces incoming data from a link partner on the current media interface to be retransmitted back to the link partner on the media interface as shown in [Figure 23-1](#). In addition, the incoming data will also appear on the receive data pins of the MAC interface. Data present on the transmit data pins of the MAC interface are ignored in this mode. This loopback mode is available in both serial and parallel MAC operating modes. For more information, please refer to [MII Register 23](#).

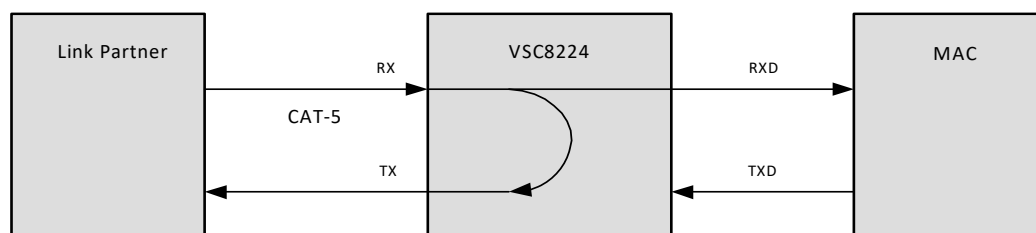


Figure 23-1. Far-end Loopback Block Diagram

23.4 Near-end Loopback

When Near-end loopback is set (MII Register bit 0.14 = 1), the Transmit Data (TXD) on the MAC interface is looped back onto the Receive Data (RXD) pins to the MAC as shown in [Figure 23-2](#). In this mode, no signal is transmitted over the network media. This loopback mode is available in both serial and parallel MAC operating modes.

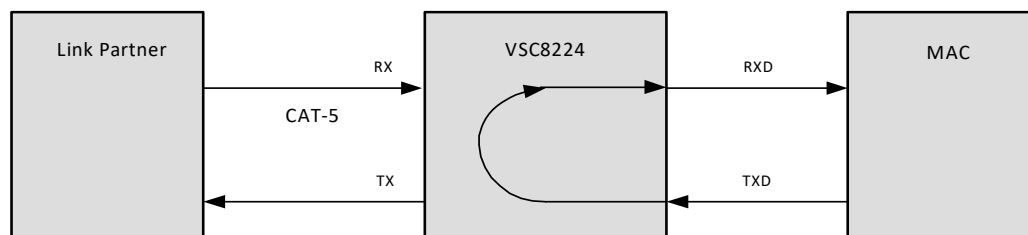


Figure 23-2. Near-end Loopback Block Diagram

23.5 Connector Loopback

Connector Loopback allows for the media interface to be looped back externally. In this mode, the PHY must be connected to a loopback connector or a loopback cable. For twisted pair media, pair A should be connected to pair B and pair C to pair D. For serial media the transmit pair is connected to the receive pair. This loopback mode is available in both serial and parallel MAC operating modes. This loopback will work in all speeds selected for the interface.

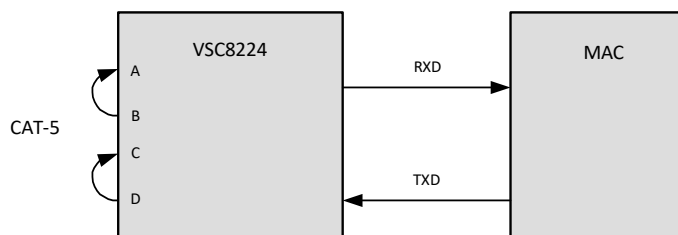


Figure 23-3. Connector Loopback for Twisted Pair Media

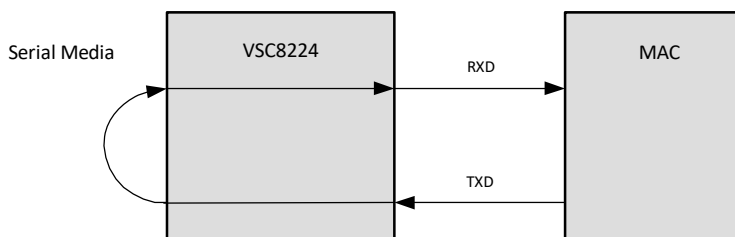


Figure 23-4. Connector Loopback for Serial Pair Media

The autonegotiation, speed, and duplex can be configured using MII registers 0, 4, and 9. For 1000BT connector loopback only the following additional writes are required in the specified order.

1. Master/Slave configuration forced to master (MII Register Bits 9.9:8 = 11)
2. Enable 1000BT connector loopback (MII Register Bit 24.0 = 1)
3. Disable pair swap correction (MII Register Bit 18.5 = 1)
4. Disable autonegotiation and force 1000BT link (MII Register Bit 0.12 = 0, MII Register Bit 0.6 = 1, and MII Register Bit 0.13 = 0) and force either full or half duplex (MII Register Bit 0.8 = 0 or 1).

24 Initialization and Configuration

24.1 Resets

There are four conditions which can cause a reset of some or all parts of the VSC8224:

Device Power-up: On device power-up, the VSC8224 first reads the status of the CMODE hardware configuration and sets the appropriate MII register bits. All MII register bits not associated to a CMODE hardware configuration are then reset to their default values. The last step in power-up before the device becomes active is a read of EEPROM configuration, if an EEPROM is present. Note that because it is the last step in the reset sequence, it is possible for the EEPROM to overwrite MII register bits previously set by CMODE hardware configuration.

Device Hardware Reset: A complete hardware reset of all four PHYs in the VSC8224 occurs on the rising edge of the $\overline{\text{RESET}}$ pin. This functions identically to device power-up, above.

Device Software Reset: A complete software reset of all four PHYs in the VSC8224 occurs on the rising edge of the SOFT_RESET pin. When this occurs, all MII register bits not marked as “sticky” will be reset to their default values. If [MII Register Bit 21E.14](#) is set to a “1”, the EEPROM configuration data will be read next, if one is present.

PHY Software Reset through MII Register Bit 0.15: An individual PHY reset can be initiated by writing a “1” to [MII Register Bit 0.15](#). This functions identically to device software reset, except that it only affects a single PHY in the VSC8224.

24.2 Power-Up Sequence

The power supply sequence to the VSC8224 may be powered in any order.

24.3 CMODE Pin Configuration

Eight CMODE (configuration mode) pins are used by the device to provide a flexible method of hardware configuration without the need for a microcontroller or station manager. Each CMODE pin maps to four configuration bits giving one pin control of 16 possible default settings. This is controlled by connecting the CMODE pins to either VDD33 or VSSS (ground) through an external 1% resistor as shown in Table 24-2. As a result, 32 total configuration bits settings at power-up are possible within the 8 CMODE pins as shown in Table 24-1.

The resistors used on the CMODE pins can be considered optional for designs that have access to the VSC8224's management interface. In this manner all configurations present in CMODE can be altered via MII register settings and the CMODE pins can be pulled to VSSS (ground). However, the only feature that still requires CMODE configuration is the $\text{PHYADDR}[4:2]$ selection. This can be set by either tying these pins to VDD33 or VSSS.

24.3.1 CMODE Hardware Configuration Bits

32 CMODE hardware configuration bits are mapped to the 8 CMODE pins as shown in the following table:

Table 24-1. CMODE Hardware Configuration Bits

CMODE pin #	Bit 3 Function (MSB)	Bit 2 Function	Bit 1 Function	Bit 0 Function (LSB)
7	RGMII Clock Skew[1]	SIGDET pin direction	ActiPHY™	Link Speed Downshift
6	RGMII Clock Skew[0]	Remote Fault Control[1]	LED Combine Link/Act	LED Pulse-stretch/Blink
5	PHY Address [4]	Remote Fault Control[0]	LED Combine Link10/ 100/1000/Act	LED Combine COL/DUP
4	PHY Address [3]	Speed/Dup modes [1]	LED4[1]	LED4[0]
3	PHY Address[2]	Speed/Dup modes [0]	LED3[1]	LED3[0]
2	MAC interface [2]	Always set to logical "0"	LED2[1]	LED2[0]
1	MAC interface [1]	Pause Control[1]	LED1[1]	LED1[0]
0	MAC interface [0]	Pause Control[0]	LED0[1]	LED0[0]

24.3.2 Setting the CMODE Configuration Bits

The CMODE pins are set by connecting the CMODE pins to either VDD33 or VSSS (ground) through an external 1% resistor. To set the CMODE pins to utilize the 32 CMODE configuration bits, please refer to the following combination table below:

Table 24-2. CMODE Pin Combinations

CMODE bit 3 value	CMODE bit 2 value	CMODE bit 1 value	CMODE bit 0 value	CMODE Resistor Value	Tied to VDD or GND
0	0	0	0	0	GND
0	0	0	1	2.26k	GND
0	0	1	0	4.02k	GND
0	0	1	1	5.90k	GND
0	1	0	0	8.25k	GND
0	1	0	1	12.1k	GND
0	1	1	0	16.9k	GND
0	1	1	1	22.6k	GND
1	0	0	0	0	VDD33
1	0	0	1	2.26k	VDD33
1	0	1	0	4.02k	VDD33
1	0	1	1	5.90k	VDD33
1	1	0	0	8.25k	VDD33
1	1	0	1	12.1k	VDD33
1	1	1	0	16.9k	VDD33
1	1	1	1	22.6k	VDD33

24.3.3 Hardware Configuration Bit Description

The function for each CMODE configuration bit shown in Table 24-1 is described in the following table:

Table 24-3. CMODE Configuration Bits

Name	Sets MII Register	Values	Description
MAC-side interface select [2:0]	23.[15:12], 23.[2:1]	111	RGMII to CAT5
		110	Reserved
		101	Reserved
		100	Reserved
		011	Reserved
		010	Reserved
		001	RTBI to CAT5 Clause 37 autonegotiation enabled
		000	RGMII with Auto CAT5/Serial Media Sense (fiber preferred)
PHY Address [4:2]	N/A	xxx	3 MSBs of PHY address
ActiPHY™	28.6	1	Enable ActiPHY™ power management
		0	Disable ActiPHY™ power management
LEDn[1:0]	27[15:6]	xx	Mapped directly to the two function selection bits for each LED pin. (see MII Register 27 for more information)
LED pulse-stretch/blink	27.3	1	Collision, Activity, Rx and Tx LED outputs will be pulse-stretched when active
		0	Collision, Activity, Rx and Tx LED outputs will blink when active
LED combine Link with Activity	27.2	1	Link LEDs indicate link status only
		0	Link LEDs will blink or flash when activity is present. Blink/flash behavior is selected by Pulse-Stretch Enable bit.
LED combine Link10/100/1000 with Activity	27.1	1	Link10, Link100, Link1000, Link10/100, Link100/1000 LEDs indicate link status only
		0	Link10, Link100, Link1000, Link10/100, Link100/1000 LEDs will blink or flash when activity is present. Blink/flash behavior is selected by Pulse-Stretch Enable bit.
LED combine Collision with Duplex	27.0	1	Duplex LED indicates duplex status only
		0	Duplex LED will blink or flash when collision is present. Blink/flash behavior is selected by Pulse-Stretch Enable bit.
Speed/Duplex autonegotiation advertisement	4.[8:5], 9.[9:8] ¹	11	10/100BASE-T, HDX, FDX
		10	1000BASE-T, FDX; 1000BASE-X, FDX
		01	10/100/1000BASE-T, FDX; 10/100BASE-T HDX; 1000BASE-X, FDX
		00	10/100/1000BASE-T, HDX, FDX; 1000BASE-X, HDX, FDX
Link Speed Downshift	20E.4	1	Enable link speed downshift capability on 2-pair cable or after 3 failed autonegotiation attempts
		0	Link only according to autonegotiation resolution
Pause control [1:0]	4.[11:0] ²	xx	Pause Control autonegotiation advertisement
Remote Fault Control[1:0]	16E2.1	xx	Remote Fault Control
SIGDET_[3:0] pin direction	19E.1	1	SIGDET_[3:0] pins are an output
		0	SIGDET_[3:0] pins are an input

Table 24-3. CMODE Configuration Bits (continued)

Name	Sets MII Register	Values	Description
RGMII Skew Control[1:0] ³	23.[11:8]	11	2.5ns skew on RX_CLK and TX_CLK
		10	2ns skew on RX_CLK and TX_CLK
		01	1.5ns skew on RX_CLK and TX_CLK
		00	No skew on RX_CLK and TX_CLK

¹ For Clause 37 register view, this setting affects MII Register Bits 4.[6:5] and MII Register Bits 15.[15:12]² For Clause 37 register view, this setting affects MII Register Bits 4.[8:7]³ To independently control the RX_CLK and TX_CLK RGMII skew, please refer to MII Register 23 for more information.

24.4 EEPROM Interface

The EEPROM interface on the VSC8224 provides the PHY with the ability to self configure its internal registers. The EEPROM is read on powerup or deassertion of RESET. The EEPROM can also be accessed through MII registers for field configurability.

The EEPROM must have a two-wire interface such as Atmel "AT24CXXX" in order to interface to the VSC8224. As defined by this interface, data is clocked from the VSC8224 on the falling edge of EECLK. The VSC8224 determines that an external EEPROM is present by monitoring the EEDAT pin at powerup or when RESET is de-asserted. If EEDAT is connected to a 4.7kΩ external pull-up resistor, the VSC8224 assumes an EEPROM is present. The EEDAT pin can be left floating or grounded to indicate no EEPROM. If the VSC8224 detects an EEPROM present, then MII Register Bit 23.0 = 1 otherwise it will be cleared.

24.4.1 EEPROM Contents Description

If an EEPROM is present, the start-up control block looks for a "Microsemi Header" 0xBDBD at address 0 and 1 of the EEPROM. The address is incremented by 256 until the Microsemi Header is found. If the Microsemi Header is not found, or no EEPROM is connected, the VSC8224 bypasses the EEPROM read step.

Once the 'header value' is found, then the following two byte address values indicates the EEPROM word address where the configuration contents for the VSC8224 are located. At the base address location the next 10 bytes indicate where the configuration data contents to be programmed into the VSC8224 are located. The first address points to the data common to all PHYs. Each subsequent address location points to each individual PHY's configuration contents. At each programming location the two bytes represent the total number of bytes (11 bits long, with MSB first) where Total_Number_Bytes[10:0] = number of SMI writes x 3 (1 byte for SMI port and register address and 2 bytes for data). Refer to table below. Data is read from the EEPROM sequentially (at 50 KHz, or 50 kbits/s) until all SMI write commands are completed.

If an EEPROM is present, but the EEPROM does not acknowledge (according to the ATMEL EEPROM protocol), the VSC8224 waits for an acknowledge for approximately 3 seconds. If there is no acknowledge for 3 seconds, the VSC8224 will abort and continue into normal operation.

Table 24-4. EEPROM Configuration Contents

10-bit Address	Contents (bits 7:0)
0	0xBD
1	0xBD
2	PHY_ADDR[4:2], 00, Base_Address_Location[10:8]
3	Base_Address_Location[7:0] (K)
-----	-----
-----	-----
K	00000, Common_Config_Base_Address[10:8]

Table 24-4. EEPROM Configuration Contents

10-bit Address	Contents (bits 7:0)
K+1	Common_Config_Base_Address[7:0] (X)
K+2	00000, PHY0_Specific_Config_Base_Address[10:8]
K+3	PHY0_Specific_Config_Base_Address[7:0] (Y)
K+4	00000, PHY1_Specific_Config_Base_Address[10:8]
K+5	PHY1_Specific_Config_Base_Address[7:0]
K+6	00000, PHY2_Specific_Config_Base_Address[10:8]
K+7	PHY2_Specific_Config_Base_Address[7:0]
K+8	00000, PHY3_Specific_Config_Base_Address[10:8]
K+9	PHY3_Specific_Config_Base_Address[7:0]
-----	-----
-----	-----
X	00000, Total_Number_Bytes[10:8]
X+1	Total_Number_Bytes[7:0] (M)
X+2	Register Address a
X+3	Data [15:8] to be written to Register Address a
X+4	Data [7:0] to be written to Register Address a
X+5	Register Address b
X+6	Data [15:8] to be written to Register Address b
X+7	Data [7:0] to be written to Register Address b
-----	-----
X+(M-2)	Register Address x
X+(M-1)	Data [15:8] to be written to Register Address x
X+M	Data [7:0] to be written to Register Address x
-----	-----
-----	-----
Y	00000, Total_Number_Bytes[10:8]
Y+1	Total_Number_Bytes[7:0] (N)
Y+2	Register Address a
Y+3	Data [15:8] to be written to Register Address a
Y+4	Data [7:0] to be written to Register Address a
-----	-----
Y+(N-2)	Register Address x
Y+(N-1)	Data [15:8] to be written to Register Address x
Y+N	Data [7:0] to be written to Register Address x
-----	-----
-----	-----
Max Address	-----

24.4.2 Programming Multiple VSC8224 using the same EEPROM

When the same EEPROM is used to initialize multiple VSC8224 devices, to prevent contention on the 2 wire bus, the EEPROM start-up block of each VSC8224 will monitor the bus for $(\text{PhyAddress}[4:2] + 1) * 9$ clock cycles for no bus activity and only then attempt to access the bus. $\text{PhyAddress}[4:2]$ is chosen because these are the PhyAddress bits that are unique to each VSC8224. (i.e VSC8224s with lower PhyAddress get priority in the bus.)

NOTE: It is important that multiple VSC8224's REFCLK pins use the same clock. In addition, all VSC8224's $\overline{\text{RESET}}$ pins be asserted and deasserted simultaneously to ensure that the reference clock modes within each device are correctly set. This prevents having one VSC8224 use the output of a $\text{CLK125}_{\text{MAC}}$ or $\text{CLK125}_{\text{micro}}$ pin from another VSC8224 as a clock reference if the devices are sharing the same EEPROM.

Note: The above scheme for preventing bus contention will work only when multiple VSC8224 devices accessing the EEPROM have unique $\text{PhyAddress}[4:2]$ values.

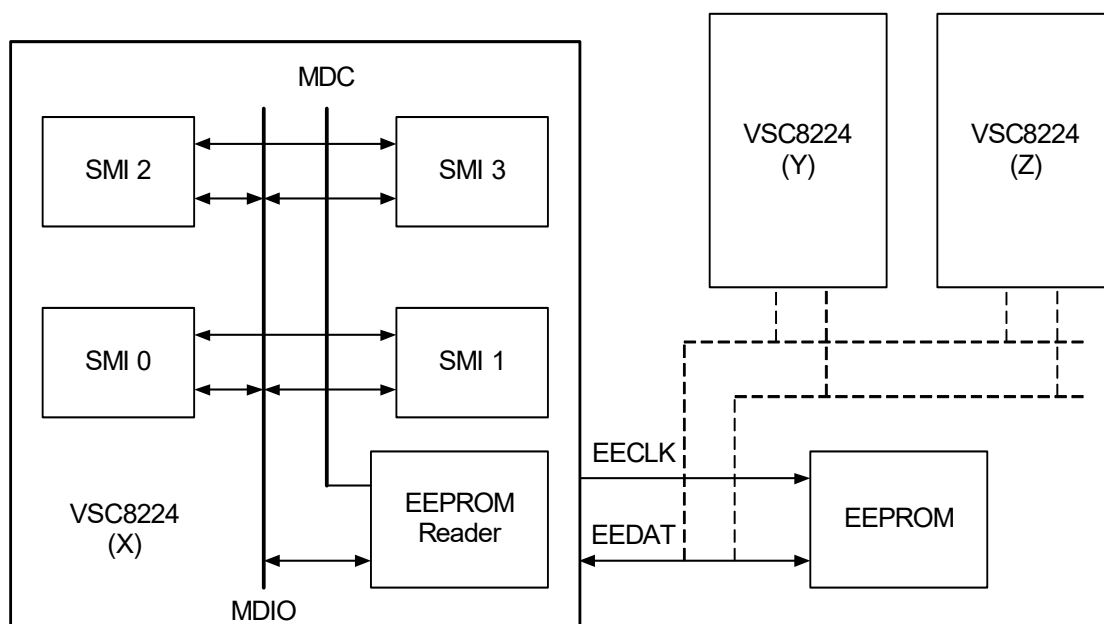


Figure 24-1. VSC8224 devices using the same EEPROM Block Diagram

Table 24-5. EEPROM Configuration Contents for Multiple VSC8224

10-bit Address	Contents (bits 7:0)
0	0xBD
1	0xBD
2	PHY_ADDR[4:2], 00, Base_Address_Location[10:8]
3	Base_Address_Location[7:0] (For VSC8224 A)
4	PHY_ADDR[4:2], 00, Base_Address_Location[10:8]
5	Base_Address_Location[7:0] (For VSC8224 B)
6	PHY_ADDR[4:2], 00, Base_Address_Location[10:8]
7	Base_Address_Location[7:0] (For VSC8224 C)
-----	-----
-----	-----
A	00000, Common_A_Config_Base_Address[10:8]

Table 24-5. EEPROM Configuration Contents for Multiple VSC8224 (continued)

10-bit Address	Contents (bits 7:0)
A+1	Common_A_Config_Base_Address[7:0] (X)
A+2	00000, PHY0_A_Specific_Config_Base_Address[10:8]
A+3	PHY0_A_Specific_Config_Base_Address[7:0]
A+4	00000, PHY1_A_Specific_Configuration_Address[10:8]
A+5	PHY1_A_Specific_Config_Base_Address[7:0]
A+6	00000, PHY2_A_Specific_Config_Base_Address[10:8]
A+7	PHY2_A_Specific_Config_Base_Address[7:0]
A+8	00000, PHY3_A_Specific_Config_Base_Address[10:8]
A+9	PHY3_A_Specific_Config_Base_Address[7:0]
-----	-----
-----	-----
B	00000, Common_B_Config_Base_Address[10:8]
B+1	Common_B_Config_Base_Address[7:0] (Y)
B+2	00000, PHY0_B_Specific_Config_Base_Address[10:8]
B+3	PHY0_B_Specific_Config_Base_Address[7:0]
B+4	00000, PHY1_B_Specific_Configuration_Address[10:8]
B+5	PHY1_B_Specific_Config_Base_Address[7:0]
B+6	00000, PHY2_B_Specific_Config_Base_Address[10:8]
B+7	PHY2_B_Specific_Config_Base_Address[7:0]
B+8	00000, PHY3_B_Specific_Config_Base_Address[10:8]
B+9	PHY3_B_Specific_Config_Base_Address[7:0]
-----	-----
-----	-----
C	00000, Common_C_Config_Base_Address[10:8]
C+1	Common_C_Config_Base_Address[7:0] (Z)
C+2	00000, PHY0_C_Specific_Config_Base_Address[10:8]
C+3	PHY0_C_Specific_Config_Base_Address[7:0]
C+4	00000, PHY1_C_Specific_Configuration_Address[10:8]
C+5	PHY1_C_Specific_Config_Base_Address[7:0]
C+6	00000, PHY2_C_Specific_Config_Base_Address[10:8]
C+7	PHY2_C_Specific_Config_Base_Address[7:0]
C+8	00000, PHY3_C_Specific_Config_Base_Address[10:8]
C+9	PHY3_C_Specific_Config_Base_Address[7:0]
-----	-----
-----	-----
X	00000, Total_Number_Bytes[10:8]
X+1	Total_Number_Bytes[7:0] (N)
X+2	Register Address a
X+3	Data [15:8] to be written to Register Address a

Table 24-5. EEPROM Configuration Contents for Multiple VSC8224 (continued)

10-bit Address	Contents (bits 7:0)
X+4	Data [7:0] to be written to Register Address a
X+5	Register Address b
X+6	Data [15:8] to be written to Register Address b
X+7	Data [7:0] to be written to Register Address b
-----	-----
X+(N-2)	Register Address x
X+(N-1)	Data [15:8] to be written to Register Address x
X+N	Data [7:0] to be written to Register Address x
-----	-----
-----	-----
Y	00000, Total_Number_Bytes[10:8]
Y+1	Total_Number_Bytes[7:0] (M)
Y+2	Register Address a
Y+3	Data [15:8] to be written to Register Address a
Y+4	Data [7:0] to be written to Register Address a
Y+5	Register Address b
Y+6	Data [15:8] to be written to Register Address b
Y+7	Data [7:0] to be written to Register Address b
-----	-----
Y+(M-2)	Register Address x
Y+(M-1)	Data [15:8] to be written to Register Address x
Y+M	Data [7:0] to be written to Register Address x
-----	-----
-----	-----
Z	00000, Total_Number_Bytes[10:8]
Z+1	Total_Number_Bytes[7:0] (P)
Z+2	Register Address a
Z+3	Data [15:8] to be written to Register Address a
Z+4	Data [7:0] to be written to Register Address a
Z+5	Register Address b
Z+6	Data [15:8] to be written to Register Address b
Z+7	Data [7:0] to be written to Register Address b
-----	-----
Z+(P-2)	Register Address x
Z+(P-1)	Data [15:8] to be written to Register Address x
Z+P	Data [7:0] to be written to Register Address x
-----	-----
-----	-----
Max Address	-----

With the above scheme for EEPROM contents, if multiple VSC8224 devices are initialized in a similar way, the base address locations can each point to the same address location from the EEPROM. If they have to be initialized differently, then each base location will differ for each device and the data contents to be configured for each will be unique.

24.4.3 Read/Write Access to the EEPROM

The VSC8224 has the ability to read and write to an EEPROM (such as an ATMEL AT24CXXX) connected to the EECLK and EEDAT pins of the device. If it is required to be able to write to the EEPROM, please refer to the EEPROM's specific datasheet to ensure that write protection on the EEPROM is not set.

To read a value from a specific address of the EEPROM, first read MII Register Bit 21E.11 and ensure that it is set. After confirming this bit is set, write the address to be read to MII Register Bits 21E.10:0, set MII Register Bit 21E.12 = 1, and then set MII Register Bit 21E.13 = 1. Wait until 21E.11 = 1 and then read the 8-bit data value found at 22E.15:8 that contains the contents of the address just read by the PHY.

To write a value to a specific address of the EEPROM, first read MII Register Bit 21E.11 and ensure that it is set. After confirming this bit is set, write the address to be written to MII Register Bits 21E.10:0, set MII Register Bit 21E.12 = 0, the 8-bit value to be written to MII Register Bits 22E.7:0, and then set MII Register Bit 21E.13 = 1.

For successful read and write transactions always wait until 21E.11 = 1 before performing another EEPROM read or write operation.

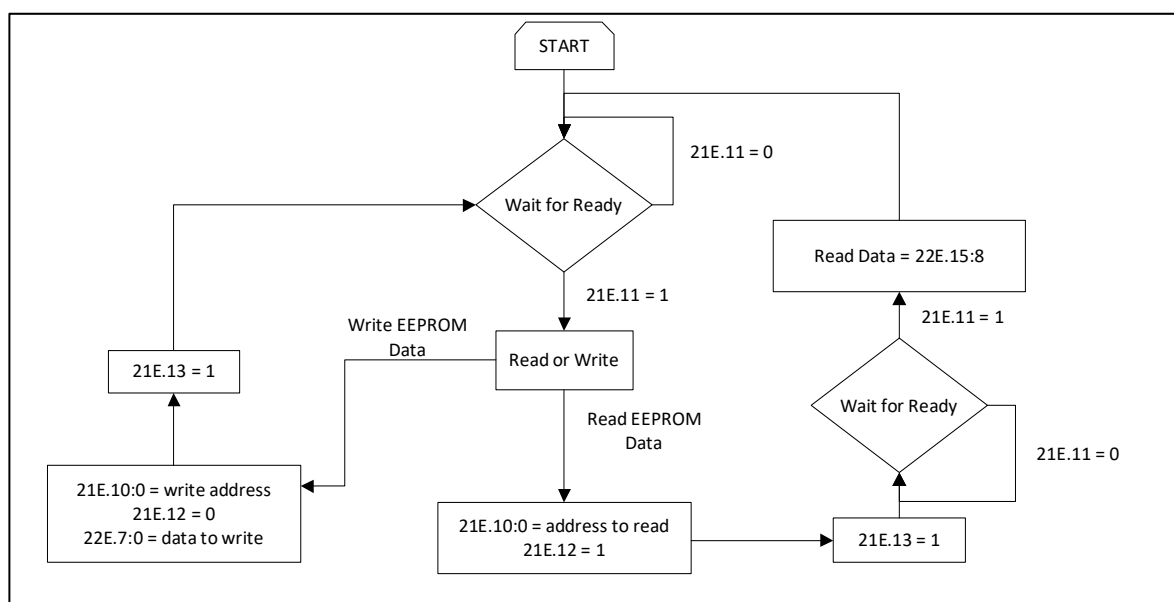


Figure 24-2. EEPROM Read/Write Register Flow

25 MII Register Set

The MII register map quick reference is listed on the following two pages:

Table 25-1. MII Register Bit Modes

Register Bit Type	Description
S	"Sticky" ¹ - this bit will retain value after a software reset and if MII Register 22.9 = 1
SS	"Super Sticky" ¹ - this bit will retain value after a software reset
R/W	Read/Write bit
RO	Read Only bit
SC	Self-clearing bit
LL	This bit will latch the bit on low. The bit self-clears on read
LH	This bit will latch the bit on high. The bit self-clears on read
CMODE	Defined by CMODE pin settings

¹ "Sticky" refers to the behavior of the register bit(s) after a software reset. If an "S" appears in the sticky column, the corresponding bit(s) will retain their values after a software reset, as long as MII Register bit [22.9 - Sticky Reset Enable](#) is set. If an "SS" appears in the sticky column, the corresponding bit(s) will retain their values after a software reset, regardless of the state of MII Register bit [22.9 - Sticky Reset Enable](#).

NOTE: For MII Registers 16-31 and Extended MII Registers 16E-30E, any bits marked as "Reserved" should be processed as read only and their states as undefined. In writing to registers with these reserved bits, one must perform a technique known commonly as "ready-modify write" where the entire register is read and only the intended bits to be changed are modified. These reserved bits cannot be changed and their read state cannot be considered static or unchanging.

25.1 IEEE803.3 Clause 28/37 MII Register View

The IEEE802.3 Ethernet standard contains two specifications for MII registers 4, 5, 6, 9, 10 and 15. Clause 28 in this standard specifies the MII registers for twisted pair CAT-5 media (10/100/1000BASE-T). Clause 37 in this standard specifies the MII registers for serial media (1000BASE-X). The VSC8224 supports both register standards. By default, the VSC8224 is designed for CAT-5 twisted pair media, so the Clause 28 register "view" is the default mode. The Clause 28 and Clause 37 register views are selected via MII Register bit 23.4. Changing between Clause 28 and Clause 37 register view is only supported in RGMII modes set by Register 23. Please refer to [Section 26.1: "Clause 28 Register View for Registers 0-15"](#) and to [Section 26.49: "Clause 37 Register View for Registers 0-15"](#) for each register view.

The MII register view selection bit (MII Register bit 23.4) only changes the manner the functionality of the PHY is represented by the MII registers described above, but does not cause functional changes to the operation of the PHY. Therefore, it is completely valid for a link to be established on copper media using Clause 28 autonegotiation or on serial media using Clause 37 autonegotiation, regardless of the MII register view currently selected. However, depending on the current setting of MII Register bit 23.4, not all PHY operating parameters may be viewed or changed.

25.2 IEEE802.3 Clause 28/37 Remote Fault Indication Support

The VSC8224 is capable of both Clause 28 and Clause 37 autonegotiation. In addition, the VSC8224 can be configured for a register view corresponding to Clause 28 or Clause 37. However, in IEEE802.3, Clause 37 provides for two remote fault bits, while Clause 28 provides only a single remote fault bit. A third remote fault status bit is also located in MII Register bit 1.4, which is independent of the register view.

In the instances where the register view is configured for a different IEEE clause than the current autonegotiation advertisement, MII Register bits 16E.2:0 handle the mapping between autonegotiation and register view. These bits also control the result of MII Register bit 1.4 if a remote fault is detected in the link partner.

There are 4 possible combinations of register view and autonegotiation. In each case, remote fault conditions are both transmitted by the local PHY and received from the link partner. Remote fault conditions in each of these are described below:

1. Clause-28 autonegotiation with Clause-28 register view- One remote fault bit is received from the link partner and one bit is transmitted from the local PHY to the link partner. No special handling of registers 4/5, or MII Register bit 1.4 is necessary, as the two modes are identical.
2. Clause-28 autonegotiation with Clause-37 register view- One remote fault bit is received from the link partner and must be mapped to two MII register bits 5.13:12, as well as MII Register bit 1.4. Two remote fault MII Register bits 4.13:12 must be mapped to a single bit to transmit from the local PHY to the link partner.
3. Clause-37 autonegotiation with Clause-28 register view- Two remote fault bits are received from the link partner and must be mapped to one MII register bit 5.13, as well as MII Register bit 1.4. One remote fault MII Register bit 4.13 must be mapped to two bits to transmit from the local PHY to the link partner.
4. Clause-37 autonegotiation with Clause-37 register view- Two remote fault bits are received from the link partner and two remote fault bits are transmitted from the local PHY to the link partner. No special handling of MII Registers 4/5 is necessary. MII Register bits 5.13:12 must be mapped to MII Register bit 1.4.

MI register 16E handles the remote fault mapping. The functionality of these bits is summarized in the following tables:

Table 25-2. Clause-28 Register View Remote Fault Transmitted to Link Partner

Bit 4.13, Local Remote Fault	Value Transmitted to LP during Clause-28 Autonegotiation (combination 1, above)	Value Transmitted to LP during Clause-37 Autonegotiation (combination 3, above)
0	0	00
1	1	Equal to bits 16E.2:1 (Remote Fault Mask)

Table 25-3. Clause-37 Register View Remote Fault Transmitted to Link Partner

Bits 4.13:12, Local Remote Fault	Bit 16E.0, Remote Fault OR	Bits 16E.2:1, Remote Fault Mask	Value Transmitted during Clause-28 Autonegotiation (combination 2, above)	Value Transmitted during Clause-37 Autonegotiation (com- bination 4, above)
00	0	00	0	00
01, 10 or 11	0	01, 10 or 11	1, if bits 4.13:12 equal bits 16E.2:1 0, if bits 4.13:12 do not equal bits 16E.2:1	Equal to bits 4.13:12
01, 10 or 11	1	xx	1	Equal to bits 4.13:12

Table 25-4. Clause-28 Autonegotiation Link Partner Remote Fault

LP Remote Fault Bit ¹	Bit 16E.0, Remote Fault OR	Bits 16E.2:1, Remote Fault Mask	Value Displayed in Clause-28 View Register Bit 1.4	Value Displayed in Clause-37 View Register Bit 1.4	Value Displayed in Clause-28 View Register Bit 5.13 (combination 1, above)	Value Displayed in Clause-37 View Register Bits 5.13:12 (combination 2, above)
0	x	xx	0	0	0	00
1	x	00	1	0	1	00
1	x	01, 10 or 11	1	1	1	Equal to bits 16E.2:1

¹ This is the remote fault bit sent by the link partner during Clause-28 autonegotiation

Table 25-5. Clause-37 Autonegotiation Link Partner Remote Fault

LP Remote Fault Bits ¹	Bit 16E.0, Remote Fault OR	Bits 16E.2:1, Remote Fault Mask	Value Displayed in Register Bit 1.4	Value Displayed in Clause-28 View Register Bit 5.13 (combination 3, above)	Value Displayed in Clause-37 View Register Bits 5.13:12 (combination 4, above)
00	x	xx	0	0	00
01, 10 or 11	0	xx	1, if LP remote fault bits equal bits 16E.2:1 0, if LP remote fault bits do not equal bits 16E.2:1	1, if LP remote fault bits equal bits 16E.2:1 0, if LP remote fault bits do not equal bits 16E.2:1	Equal to LP remote fault bits
01, 10 or 11	1	xx	1	1	Equal to LP remote fault bits

¹ These are the remote fault bits sent by the link partner during Clause-37 autonegotiation

25.3 MII Extended Page Registers

In order to provide additional functionality beyond the IEEE802.3 specified 32 MII registers, the VSC8224 contains an extended page register mode that allows an additional 15 registers. Access to the extended page registers (Registers 16E - 30E) is enabled by writing a "0001" to [MII Register 28](#). When extended page register access is enabled, read/writes to MII Registers 16 through 30 will affect the extended MII Registers 16E through 30E. MII Registers 0 through 15 are not affected by the state of the extended page register access. Writing a "0000" to [MII Register 28](#) will restore normal MII register access.

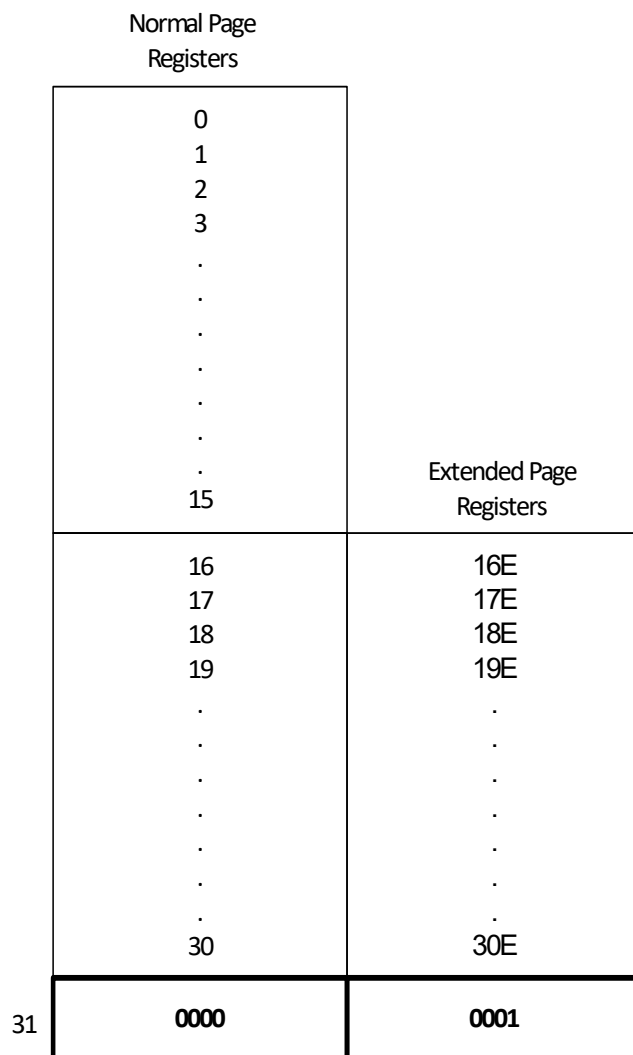


Figure 25-1. Extended Page Register Diagram

25.4 MII Register Quick Reference - Clause 28 View

Register	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Register 0 (00h) Mode Control Register	Software Reset	Loopback	Forced Speed Select[0]	Auto-Neg Enable	Power-Down	Isolate	Restart Auto-Neg	Duplex Mode	Collision Test	Forced Speed Select[1]	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 1 (01h) Mode Status Register	100B-T4	100B-X FDX	100B-X HDX	10B-T FDX	10B-T HDX	100B-T2 FDX	100B-T2 HDX	Extended Status	Reserved	Preamble Suppression	Auto-Neg Complete	Remote Fault	Auto-Neg Capability	Link Status	Jabber Detect	Extended Capability
Register 2 (02h) PHY Identifier #1	OUI_MSB[3]	OUI_MSB[4]	OUI_MSB[5]	OUI_MSB[6]	OUI_MSB[7]	OUI_MSB[8]	OUI_MSB[9]	OUI_MSB[10]	OUI_MSB[11]	OUI_MSB[12]	OUI_MSB[13]	OUI_MSB[14]	OUI_MSB[15]	OUI_MSB[16]	OUI_MSB[17]	OUI_MSB[18]
Register 3 (03h) PHY Identifier #2	OUI_LSB[19]	OUI_LSB[20]	OUI_LSB[21]	OUI_LSB[22]	OUI_LSB[23]	OUI_LSB[24]	Vendor Model Number[5]	Vendor Model Number[4]	Vendor Model Number[3]	Vendor Model Number[2]	Vendor Model Number[1]	Vendor Model Number[0]	Vendor Rev Number[3]	Vendor Rev Number[2]	Vendor Rev Number[1]	Vendor Rev Number[0]
Register 4 (04h) Auto-Neg Advertisement Register	Next Page	Reserved	Remote Fault	Reserved	Asymmetric Pause	Symmetric Pause	100B-T4	100B-X FDX	100B-X HDX	10B-T FDX	10B-T HDX	Selector Field[4]	Selector Field[3]	Selector Field[2]	Selector Field[1]	Selector Field[0]
Register 5 (05h) Auto-Neg Link Partner Ability Register	Next Page	ACK	Remote Fault	Reserved	Asymmetric Pause	Symmetric Pause	100B-T4	100B-X FDX	100B-X HDX	10B-T FDX	10B-T HDX	Selector Field[4]	Selector Field[3]	Selector Field[2]	Selector Field[1]	Selector Field[0]
Register 6 (06h) Auto-Neg Expansion Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Parallel Detect Fault	LP NP Able	NP Able	Page Received	LP Auto-Neg Able
Register 7 (07h) Auto-Neg NP Transmit Register	Next Page	Reserved	Message Page	ACK2	Toggle	Message/ Unformatted[0]	Message/ Unformatted[9]	Message/ Unformatted[8]	Message/ Unformatted[7]	Message/ Unformatted[6]	Message/ Unformatted[5]	Message/ Unformatted[4]	Message/ Unformatted[3]	Message/ Unformatted[2]	Message/ Unformatted[1]	Message/ Unformatted[0]
Register 8 (08h) Auto-Neg Link Partner NP Receive Register	LP Next Page	LP ACK	LP Message Page	LP ACK2	LP Toggle	LP Message/ Unformatted[0]	LP Message/ Unformatted[9]	LP Message/ Unformatted[8]	LP Message/ Unformatted[7]	LP Message/ Unformatted[6]	LP Message/ Unformatted[5]	LP Message/ Unformatted[4]	LP Message/ Unformatted[3]	LP Message/ Unformatted[2]	LP Message/ Unformatted[1]	LP Message/ Unformatted[0]
Register 9 (09h) 100BASE-T Control Register	Transmit Test[1]	Transmit Test[2]	Transmit Test[3]	M/S Config Enable	M/S Config Value	Port Type	1000B-T FDX	1000B-T HDX	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 10 (0Ah) 100BASE-T Status Register	M/S Config Fault	M/S Config Resolution	Local Receiver Status	Remote Receiver Status	LP 1000B-T FDX	LP 1000B-T HDX	CMODE Reserved	CMODE Reserved	Idle Error Count[7]	Idle Error Count[6]	Idle Error Count[5]	Idle Error Count[4]	Idle Error Count[3]	Idle Error Count[2]	Idle Error Count[1]	Idle Error Count[0]
Register 11 (0Bh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 12 (0Ch) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 13 (0Dh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 14 (0Eh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 15 (0Fh) 100BASE-T Status Extension Register	1000B-X FDX	1000B-X HDX	1000B-T FDX	1000B-T HDX	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved

Bit Name
(Read Only)
Reset Value

Bit Name
(Read/Writeable)

Key:

25.5 MII Register Quick Reference

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Register 16 (10h) 100BASE-TX Status Extension Register	100B-TX Descrambler Locked 0	100B-TX Lock Error Detected 0	100B-TX Disconnect State 0	100B-TX Current Link Status 0	100B-TX Receive Error Detected 0	100B-TX Transmit Error Detected 0	100B-TX SSD Error Detected 0	100B-TX ESD Error Detected 0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 17 (11h) 100BASE-T Status Extension Register #2	100B-T Descrambler Locked 0	100B-T Lock Error Detected 0	100B-T Disconnect State 0	100B-T Current Link Status 0	100B-T Receive Error Detected 0	100B-T Transmit Error Detected 0	100B-T SSD Error Detected 0	100B-T ESD Error Detected 0	100B-T Carrier Extension Error Detected 0	Non-compliant BCM5400 Detected 0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 18 (12h) Bypass Control Register	Transmit Disable 0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	100B-T Transmitter Test Clock Enable 0	Reserved	Reserved	Disable Automatic Pair Swap Correction 0	Disable Polarity Correction 0	Parallel-Detect Control 0	Reserved	Disable Auto 100B-T NP Exchange 0	125MHz MAC Clock Output Enable 1
Register 19 (13h) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 20 (14h) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 21 (15h) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 22 (16h) Extended Control & Status Register	Force 10BT Link High 0	Jabber Detect Disable 0	Disable 10BT Echo 1	Reserved	Squelch[1] 0	Squelch[0] 0	Sticky Reset Enable 1	EOF Error Detected 0	10B-T Disconnect 0	10B-T Link Status 0	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 23 (17h) Extended PHY Control Register #1	MAC IF Mode[3] CMODE	MAC IF Mode[2] 0	MAC IF Mode[1] CMODE	MAC IF Mode[0] CMODE	RGMIII TX CLK Slew Selection 0	RGMIII TX CLK Slew Selection 0	RGMIII RX CLK Slew Selection 0	RGMIII RX CLK Slew Selection 0	Reserved	Reserved	RX Idle Clock Enable 1	Register View Enable 1	Far End Loopback Mode Enable 0	MAC/Media Mode Select CMODE	MAC/Media Mode Select CMODE	EEPROM Status 0
Register 24 (18h) Extended PHY Control Register #2	100/1000B-TX Edge Rate[2] 0	100/1000B-TX Edge Rate[1] 0	100/1000B-TX Edge Rate[0] 0	Enable P10MG Reduced Power Mode 0	Reserved	Reserved	TX FIFO Depth[2] 1	TX FIFO Depth[1] 0	TX FIFO Depth[0] 0	RX FIFO Depth[2] 0	RX FIFO Depth[1] 0	RX FIFO Depth[0] 0	Reserved	CMODE	Reserved	100B-T Connector Loopback 0
Register 25 (19h) Interrupt Mask Register	Interrupt Pin Enable 0	Speed State- Change Interrupt Mask 0	Link State- Change Interrupt Mask 0	Duplex State- Change Interrupt Mask 0	Auto-Neg Error Interrupt Mask 0	Auto-Neg Done Interrupt Mask 0	In-line Powered Device Detected 0	Symbol Error Interrupt Mask 0	Descrambler Lock-Lost Interrupt Mask 0	TX FIFO Interrupt Mask 0	RX FIFO Interrupt Mask 0	AMS Media Change Interrupt Mask 0	False Carrier Interrupt Mask 0	Cable Impaired- Detect Interrupt Mask 0	MASTER/ SLAVE Interrupt Mask 0	RX_ER Interrupt Mask 0
Register 26 (1Ah) Interrupt Status Register	Interrupt Status 0	Speed State- Change Interrupt Status 0	Link State- Change Interrupt Status 0	FDX State- Change Interrupt Status 0	Auto-Neg Error Interrupt Status 0	Auto-Neg Done Interrupt Status 0	In-line Powered Device Detected 0	Symbol Error Interrupt Status 0	Descrambler Lock-Lost Interrupt Status 0	TX FIFO Interrupt Status 0	RX FIFO Interrupt Status 0	AMS Media Change Interrupt Status 0	False Carrier Interrupt Status 0	Cable Impaired- Detect Interrupt Mask 0	MASTER/ SLAVE Interrupt Status 0	RX_ER Interrupt Status 0
Register 27 (1Bh) LED Control Register	LED Pin 4 Config CMODE	LED Pin 3 Config CMODE	LED Pin 3 Config CMODE	LED Pin 3 Config CMODE	LED Pin 2 Config CMODE	LED Pin 2 Config CMODE	LED Pin 1 Config CMODE	LED Pin 1 Config CMODE	LED Pin 0 Config CMODE	LED Pin 0 Config CMODE	LED Pulse- stretch Rate/ Blink Rate 0	LED Pulse- stretch Rate/ Blink Rate 0	LED Pulse- stretch/Blink Select CMODE	LED Link Pulsing Behavior CMODE	LED Link Activity Behavior CMODE	LED Duplex/ Collision Behavior CMODE
Register 28 (1Ch) Auxiliary Control & Status Register	Auto-Neg Complete 0	Auto-Neg Disabled 0	MDI/MDI-X Xover Indication 0	CD Pair Swap CMODE	A Polarity Inversion CMODE	B Polarity Inversion CMODE	C Polarity Inversion CMODE	D Polarity Inversion CMODE	Reserved	Enhanced AcPiPHY Enable 0	FDX Status CMODE	Speed Status[1] 0	Speed Status[0] 0	Reserved	AdiPHY Sleep Timer[1] 0	AdiPHY Sleep Timer[0] 1
Register 29 (1Dh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 30 (1Eh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 31 (1Fh) Extended Page Access Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Extended Page Access 0

Key:

Bit Name
(Read/
Writable)Bit Name
(Read Only)
Reset Value

25.6 MII Register Quick Reference - Extended Page Mode

Register	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Register 10E (10h) Fiber Media Clause 37 Autoneg Control & Status	Reserved	Reserved	Fiber Remote Fault	Fiber Remote Fault	Fiber Asymmetric Pause	Fiber Symmetric Pause	Reserved	Fiber Full Duplex	Fiber Half Duplex	Reserved	Clause 37 Autoneg Complete	Clause 37 Autoneg Disable	Reserved	Remote Fault Mapping Mask	Remote Fault Mapping Mask	Remote Fault Mapping OR
Register 17E (11h) CLK125micro Clock Enable	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	CLK125micro Enable
Register 18E (12h) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 19E (13h) SIGDET Control	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	SIGDET Pin Polarity
Register 20E (14h) Extended PHY Control Register #3	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	CLK125micro Frequency	Media Mode Status	Media Mode Status	SetDes Line Impedance	Enable Link Speed Auto- downshift	Link Speed Auto-downshift Control	Link Speed Auto-downshift Control	Link Speed Auto-downshift Status	Reserved
Register 21E (15h) EEPROM Status & Control Register	Reserved	EEPROM on software reset	EEPROM Access Enable	EEPROM Read/Write	EEPROM Ready	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address	EEPROM Address
Register 22E (16h) EEPROM Data Read/Write Register	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Read Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data	EEPROM Write Data
Register 23E (17h) Extended PHY Control Register #4	PHY Address	PHY Address	PHY Address	PHY Address	PHY Address	Enable Device Detection	Device Detection Status	Device Detection Status	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter	1000BT CRC Counter
Register 24E (18h) Reserved Register	CMODE	CMODE	CMODE	CMODE	CMODE	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 25E (19h) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 26E (1Ah) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 27E (1Bh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 28E (1Ch) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 29E (1Dh) 100BASE-T EPG Register #1	EPG Enable	EPG Run/Stop	Transmission Duration	Packet Length	Packet Length	Inter-packet Gap	Destination Address	Destination Address	Destination Address	Destination Address	Source Address	Source Address	Source Address	Source Address	Source Address	Bad FCS Generation
Register 30E (1Eh) 100BASE-T EPG Register #2	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload	EPG Packet Payload

Key:

Bit Name
(Read/
Writable)Bit Name
(Read Only)
Reset Value

25.7 MII Register Quick Reference - Clause 37 View

Register	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Register 0 (00h) Mode Control Register	Software Reset	Loopback	Forced Speed Select[0]	Auto-Neg Enable	Power-Down	Isolate	Restart Auto-Neg	Duplex Mode	Collision Test	Forced Speed Select[1]	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 1 (01h) Mode Status Register	100B-T4	100B-X FDX	100B-X HDX	10B-T FDX	10B-T HDX	100B-T2 FDX	100B-T2 HDX	Extended Status	Reserved	Preamble Suppression	Auto-Neg Complete	Remote Fault	Auto-Neg Capability	Link Status	Jabber Detect	Extended Capability
Register 2 (02h) PHY Identifier #1	OUI_MSB[3]	OUI_MSB[4]	OUI_MSB[5]	OUI_MSB[6]	OUI_MSB[7]	OUI_MSB[8]	OUI_MSB[9]	OUI_MSB[10]	OUI_MSB[11]	OUI_MSB[12]	OUI_MSB[13]	OUI_MSB[14]	OUI_MSB[15]	OUI_MSB[16]	OUI_MSB[17]	OUI_MSB[18]
Register 3 (03h) PHY Identifier #2	OUI_LSB[19]	OUI_LSB[20]	OUI_LSB[21]	OUI_LSB[22]	OUI_LSB[23]	OUI_LSB[24]	Vendor Model Number[5]	Vendor Model Number[4]	Vendor Model Number[3]	Vendor Model Number[2]	Vendor Model Number[1]	Vendor Model Number[0]	Vendor Rev Number[3]	Vendor Rev Number[2]	Vendor Rev Number[1]	Vendor Rev Number[0]
Register 4 (04h) Auto-Neg Advertisement Register	Next Page	Reserved	Remote Fault	Remote Fault	Reserved	Reserved	Reserved	Asymmetric Pause	Symmetric Pause	1000B-X HDX	1000B-X FDX	Reserved	Reserved	Reserved	Reserved	Reserved
Register 5 (05h) Auto-Neg Link Partner Ability Register	Next Page	ACK	Remote Fault	Remote Fault	Reserved	Reserved	Reserved	CMODE Asymmetric Pause	CMODE Symmetric Pause	1000B-X HDX	CMODE 1000B-X FDX	Reserved	Reserved	Reserved	Reserved	Reserved
Register 6 (06h) Auto-Neg Expansion Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	NP Able	Page Received	Reserved
Register 7 (07h) Auto-Neg NP Transmit Register	Next Page	Reserved	Message Page	ACK2	Toggle	Message/ Unformatted[1] 0j	Message/ Unformatted[9]	Message/ Unformatted[8]	Message/ Unformatted[7]	Message/ Unformatted[6]	Message/ Unformatted[5]	Message/ Unformatted[4]	Message/ Unformatted[3]	Message/ Unformatted[2]	Message/ Unformatted[1]	Message/ Unformatted[0]
Register 8 (08h) Auto-Neg Link Partner NP Receive Register	LP Next Page	LP ACK	LP Message Page	LP ACK2	LP Toggle	LP Message/ Unformatted[1] 0j	LP Message/ Unformatted[9]	LP Message/ Unformatted[8]	LP Message/ Unformatted[7]	LP Message/ Unformatted[6]	LP Message/ Unformatted[5]	LP Message/ Unformatted[4]	LP Message/ Unformatted[3]	LP Message/ Unformatted[2]	LP Message/ Unformatted[1]	LP Message/ Unformatted[0]
Register 9 (09h) 1000BASE-T Control Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 10 (0Ah) 1000BASE-T Status Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 11 (0Bh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 12 (0Ch) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 13 (0Dh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 14 (0Eh) Reserved Register	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
Register 15 (0Fh) 1000BASE-T Status Extension Register	1000B-X FDX	1000B-X HDX	1000B-T FDX	1000B-T HDX	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved

Key:

Bit Name
(Read/
Writable)Bit Name
(Read Only)
Reset Value

26 MII Register Descriptions

Registers 0-15 comply with the IEEE 802.3 standard. Enhancements beyond the specification are noted within each of these registers. For more information on normal operation of registers 0-15, please consult with the IEEE standard.

26.1 Clause 28 Register View for Registers 0-15

The following 16 registers are compliant with IEEE 802.3 standard and comply with Clause 28. To change the register view to Clause 37 where the MAC is configured to RGMII mode, please refer to [Section 25.1: "IEEE803.3 Clause 28/37 MII Register View"](#).

26.2 Register 0 (00h) – Mode Control Register

Register 0 (00h) – Mode Control Register				
Bit	Name	Access	States	Reset Value
15	Software Reset ¹	R/W SC	1 = Reset asserted 0 = Reset de-asserted	0
14	Loopback ²	R/W	1 = Loopback on 0 = Loopback off	0
6, 13	Forced Speed Selection	R/W	00 = 10Mbps 01 = 100Mbps 10 = 1000Mbps 11 = Reserved	10
12	Auto-Negotiation Enable	R/W	1 = Auto-Negotiation enabled 0 = Auto-Negotiation disabled	1
11	Power-Down	R/W	1 = Power-down 0 = Power-up	0
10	Isolate	R/W	1 = Disable RGMII/RTBI outputs 0 = Normal Operation	0
9	Restart Auto-Negotiation	R/W SC	1 = Restart MII 0 = Normal operation	0
8	Duplex Mode	R/W	1 = Full duplex 0 = Half duplex	0
7	Collision Test Enable	R/W	1 = Collision test enabled 0 = Collision test disabled	0
6	MSB for Speed Selection (see bit 13 above)	-	-	1
5:0	Reserved	-	-	000000

¹ A soft reset restores all SMI registers to their default states, except for registers marked with an "S" or "SS" in the sticky column. After setting this bit, the user needs to wait 4 microseconds to initiate the next SMI access.

² The loopback mechanism works in the current speed and duplex mode of operation. If the link is down the operating mode is determined by bits 0.13 and 0.6 (forced speed selection) and 0.8. If the MAC/Media Interface select bits 23.15:12,2:1 are equal to a mode with fiber active, and 0.14 = 1, then the link partner may not drop the link.

26.3 Register 1 (01h) – Mode Status Register**Register 1 (01h) – Mode Status Register**

Bit	Name	Access	States	Reset Value
15	100BASE-T4 Capability	RO	1 = 100BASE-T4 capable	0
14	100BASE-TX FDX Capability	RO	1 = 100BASE-TX FDX capable	1
13	100BASE-TX HDX Capability	RO	1 = 100BASE-TX HDX capable	1
12	10BASE-T FDX Capability	RO	1 = 10BASE-T FDX capable	1
11	10BASE-T HDX Capability	RO	1 = 10BASE-T HDX capable	1
10	100BASE-T2 FDX Capability	RO	1 = 100BASE-T2 FDX capable	0
9	100BASE-T2 HDX Capability	RO	1 = 100BASE-T2 HDX capable	0
8	Extended Status Enable	RO	1 = Extended status information present in R15	1
7	Reserved	RO		0
6	Preamble Suppression Capability	RO	1 = MF preamble may be suppressed 0 = MF preamble always required	1
5	Auto-Negotiation Complete	RO	1 = Auto-Negotiation complete 0 = Auto-Negotiation not complete	0
4	Remote Fault	RO LH	1 = Far-end fault detected 0 = No fault detected	0
3	Auto-Negotiation Capability	RO	1 = Auto-Negotiation capable	1
2	Link Status ¹	RO LL	1 = Link is up 0 = Link is down	0
1	Jabber Detect	RO LH	1 = Jabber condition detected 0 = No jabber condition detected	0
0	Extended Capability	RO	1 = Extended register capable	1

¹ If the Link Status bit is equal to '1' and subsequently power-down is set, the Link Status bit may not clear. To clear the bit in this scenario, write MII Register 0.11 = 1, MII Register 0.11 = 0, and finally MII Register 0.11 = 1. This ensures that the Link Status bit is cleared when power-down is enabled.

26.4 Register 2 (02h) – PHY Identifier Register #1**Register 2 (02h) – Mode Control Register**

Bit	Name	Access	States	Reset Value
15:0	Organizationally Unique Identifier	RO	OUI most significant bits (Microsemi OUI bits 3:18)	0000000000001111 or (000Fh)

26.5 Register 3 (03h) – PHY Identifier Register #2**Register 3 (03h) – PHY Identifier Register #2**

Bit	Name	Access	States	Reset Value
15:10	Organizationally Unique Identifier	RO	OUI least significant bits (Microsemi OUI bits 19:24)	110001
9:4	Vendor Model Number	RO	Vendor's model number (IC)	011000 = VSC8224
3:0	Vendor Revision Number	RO	Vendor's revision number (IC)	0010 = Silicon Revision C

26.6 Register 4 (04h) – Auto-Negotiation Advertisement Register**Register 4 (04h) – Auto-Negotiation Advertisement Register**

Bit	Name	Access	States	Reset Value
15	Next-Page Transmission Request	R/W	1 = Next-Page transmission request	0
14	Reserved	RO		0
13	Transmit Remote Fault	R/W	1 = Transmit remote fault	0
12	Reserved technologies	R/W		0
11	Advertise Asymmetric Pause	R/W	1 = Advertise Asymmetric Pause capable	CMODE
10	Advertise Symmetric Pause	R/W	1 = Advertise Symmetric Pause capable	CMODE
9	Advertise 100BASE-T4 Capability	R/W	1 = 100BASE-T4 capable	0
8	Advertise 100BASE-TX FDX	R/W	1 = 100BASE-TX FDX capable	CMODE
7	Advertise 100BASE-TX HDX	R/W	1 = 100BASE-TX HDX capable	CMODE
6	Advertise 10BASE-T FDX	R/W	1 = 10BASE-T FDX capable	CMODE
5	Advertise 10BASE-T HDX	R/W	1 = 10BASE-T HDX capable	CMODE
4:0	Advertise Selector Field	R/W		00001

26.7 Register 5 (05h) – Auto-Negotiation Link Partner Ability Register**Register 5 (05h) – Auto-Negotiation Link Partner Ability Register**

Bit	Name	Access	States	Reset Value
15	LP Next-Page Transmit Request	RO	1 = LP NP transmit request	0
14	LP Acknowledge	RO	1 = LP acknowledge	0
13	LP Remote Fault ¹	RO	1 = LP remote fault	0
12	Reserved	RO	-	0
11	LP Asymmetric Pause Capability	RO	1 = LP Advertise Asymmetric Pause capable	0
10	LP Symmetric Pause Capability	RO	1 = LP Advertise Symmetric Pause capable	0
9	LP Advertise 100BASE-T4 Capability	RO	1 = LP Advertise 100BASE-T4 capable	0
8	LP Advertise 100BASE-TX FDX	RO	1 = LP 100BASE-TX FDX capable	0
7	LP Advertise 100BASE-TX HDX	RO	1 = LP 100BASE-TX HDX capable	0
6	LP Advertise 10BASE-T FDX	RO	1 = LP 10BASE-T FDX capable	0
5	LP Advertise 10BASE-T HDX	RO	1 = LP 10BASE-T HDX capable	0
4:0	LP Advertise Selector Field	RO	LP Advertise Selector Field	00000

¹ Refer to Extended MII Register 16E**26.8 Register 6 (06h) – Auto-Negotiation Expansion Register****Register 6 (06h) – Auto-Negotiation Expansion Register**

Bit	Name	Access	States	Reset Value
15:5	Reserved	RO		000000000000
4	Parallel Detection Fault	RO LH	1 = Parallel detection fault	0
3	LP Next-Page Able	RO	1 = LP Next-Page capable	0
2	Local PHY Next-Page Able	RO	1 = Next-Page capable	1
1	Page Received	RO LH	1 = New page has been received	0
0	LP Auto-Negotiation Able	RO	1 = LP Auto-Negotiation capable	0

26.9 Register 7 (07h) – Auto-Negotiation Next-Page Transmit Register¹**Register 7 (07h) – Auto-Negotiation Next-Page Transmit Register**

Bit	Name	Access	States	Reset Value
15	Next Page	R/W	1 = More pages follow 0 = Last page	0
14	Reserved	RO		0
13	Message Page	R/W	1 = Message page 0 = Unformatted page	1
12	Acknowledge2	R/W	1 = Will comply with request 0 = Cannot comply with request	0
11	Toggle	RO	1 = Previous transmitted LCW == 0 0 = Previous transmitted LCW == 1	0
10:0	Message/Unformatted Code	R/W		00000000001

26.10 Register 8 (08h) – Auto-Negotiation Link Partner Next-Page Receive Register¹**Register 8 (08h) – Auto-Negotiation Link Partner Next-Page Receive Register**

Bit	Name	Access	States	Reset Value
15	LP Next Page	RO	1 = More pages follow 0 = Last page	0
14	LP Acknowledge	RO	1 = LP acknowledge	0
13	LP Message Page	RO	1 = Message page 0 = Unformatted page	0
12	LP Acknowledge2	RO	1 = LP will comply with request	0
11	LP Toggle	RO	1 = Previous transmitted LCW == 0 0 = Previous transmitted LCW == 1	0
10:0	LP Message/Unformatted Code	RO		00000000000

¹This register is only valid for CAT-5 copper media

26.11 Register 9 (09h) – 1000BASE-T Control Register

Register 9 (09h) – 1000BASE-T Control Register - Clause 28 View

Bit	Name	Access	States	Reset Value
15:13	Transmitter Test Mode	R/W	Described below, per IEEE 802.3, 40.6.1.1.2	000
12	MASTER/SLAVE Manual Configuration Enable	R/W	1 = Enable MASTER/SLAVE Manual Configuration value 0 = Disable MASTER/SLAVE Manual Configuration value	0
11	MASTER/SLAVE Manual Configuration Value	R/W	1 = Configure PHY as MASTER during MASTER/SLAVE negotiation, only when bit 9.12 is set to logical one. 0 = Configure PHY as SLAVE during MASTER/SLAVE negotiation, only when bit 9.12 is set to logical one.	0
10	Port Type	R/W	1 = Multi-port device 0 = Single-port device	1
9	1000BASE-T FDX Capability	R/W	1 = PHY is 1000BASE-T FDX capable	CMODE
8	1000BASE-T HDX Capability	R/W	1 = PHY is 1000BASE-T HDX capable	CMODE
7:0	Reserved	R/W		00000000

9.15:13 Transmitter/Receiver Test Mode¹

This test is valid only in 1000BASE-T mode. Refer to IEEE 802.3-2002, section 40.6.1.1.2 for more information.

Table 26-1. Transmitter/Receiver Test Mode

Bit 1 (9.15)	Bit 2 (9.14)	Bit 3 (9.13)	Test Mode
0	0	0	Normal operation
0	0	1	Test Mode 1 – Transmit waveform test
0	1	0	Test Mode 2 – Transmit jitter test in MASTER mode
0	1	1	Test Mode 3 – Transmit jitter test in SLAVE mode
1	0	0	Test Mode 4 – Transmitter distortion test
1	0	1	Reserved; operation not defined
1	1	0	Reserved; operation not defined
1	1	1	Reserved; operation not defined

- **Test Mode 1:** The PHY repeatedly transmits the following sequence of data symbols from all four transmitters: {"+2" followed by 127 "0" symbols}, {"-2" followed by 127 "0" symbols}, {"+1" followed by 127 "0" symbols}, {"-1" followed by 127 "0" symbols}, {128 "+2" symbols, 128 "-2" symbols, 128 "+2" symbols, 128 "-2" symbols}, {1024 "0" symbols}. The transmitter should use a 125.00 MHz $\pm$ 0.01% clock and should operate in MASTER timing mode.
- **Test Mode 2:** The PHY transmits the data symbol sequence {+2, -2} repeatedly on all channels. The transmitter should use a 125.00 MHz $\pm$ 0.01% clock in the MASTER timing mode.
- **Test Mode 3:** The PHY transmits the data symbol sequence {+2, -2} repeatedly on all channels. The transmitter should use a 125.00 MHz $\pm$ 0.01% clock and should operate in SLAVE timing mode.

- **Test Mode 4:** The PHY transmits the sequence of symbols generated by the following scrambler generator polynomial, bit generation, and level mappings:

The maximum-length shift register used to generate the sequences defined by this polynomial is updated once per symbol interval (8ns). The bits stored in the shift register delay line at a particular time n are denoted by $\text{Scrn}[10:0]$. At each symbol period, the shift register is advanced by one bit, and one new bit represented by $\text{Scrn}[0]$ is generated. Bits $\text{Scrn}[8]$ and $\text{Scrn}[10]$ are exclusive-OR'd together to generate the next $\text{Scrn}[0]$ bit. The bit sequences, $x0_n$, $x1_n$, and $x2_n$, generated from combinations of the scrambler bits as shown in the following equations, shall be used to generate the quinary symbols, s_n , as shown in the following table. The transmitter should use a 125.00 MHz $\pm$ 0.01% clock and should operate in MASTER timing mode.

Table 26-2. Quinary Symbols

$x2_n$	$x1_n$	$x0_n$	Quinary Symbol, s_n
0	0	0	0
0	0	1	1
0	1	0	2
0	1	1	-1
1	0	0	0
1	0	1	1
1	1	0	-2
1	1	1	-1

26.12 Register 10 (0Ah) – 1000BASE-T Status Register

Register 10 (0Ah) – 1000BASE-T Status Register				
Bit	Name	Access	States	Reset Value
15	MASTER/SLAVE Configuration Fault	RO LH	1 = MASTER/SLAVE configuration fault detected 0 = No MASTER/SLAVE configuration fault detected	0
14	MASTER/SLAVE Configuration Resolution	RO	1 = Local PHY configuration resolved to MASTER 0 = Local PHY configuration resolved to SLAVE	1
13	Local Receiver Status	RO	1 = Local receiver OK (loc_rcvr_status == OK) 0 = Local receiver not OK (loc_rcvr_status == NOT_OK)	0
12	Remote Receiver Status	RO	1 = Remote receiver OK (rem_rcvr_status == OK) 0 = Remote receiver not OK (rem_rcvr_status == NOT_OK)	0
11	LP 1000BASE-T FDX Capability	RO	1 = LP 1000BASE-T FDX capable 0 = LP not 1000BASE-T FDX capable	0
10	LP 1000BASE-T HDX Capability	RO	1 = LP is 1000BASE-T HDX capable 0 = LP is not 1000BASE-T HDX capable	0
9:8	Reserved	RO		00
7:0	Idle Error Count	RO SC		00000000

26.13 Register 11 (0Bh) – Reserved Register

Register 11 (0Bh) – Reserved Register				
Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.14 Register 12 (0Ch) – Reserved Register

Register 12 (0Ch) – Reserved Register				
Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.15 Register 13 (0Dh) – Reserved Register

Register 13 (0Dh) – Reserved Register				
Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.16 Register 14 (0Eh) – Reserved Register**Register 14 (0Eh) – Reserved Register**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.17 Register 15 (0Fh) – 1000BASE-T Status Extension Register #1**Register 15 (0Fh) – 1000BASE-T Status Extension Register #1**

Bit	Name	Access	States	Reset Value
15	1000BASE-X FDX Capability	RO	1 = PHY is 1000BASE-X FDX capable 0 = PHY is not 1000BASE-X FDX capable	0
14	1000BASE-X HDX Capability	RO	1 = PHY is 1000BASE-X HDX capable 0 = PHY is not 1000BASE-X HDX capable	0
13	1000BASE-T FDX Capability	RO	1 = PHY is 1000BASE-T FDX capable 0 = PHY is not 1000BASE-T FDX capable	1
12	1000BASE-T HDX Capability	RO	1 = PHY is 1000BASE-T HDX capable 0 = PHY is not 1000BASE-T HDX capable	1
11:0	Reserved	RO		000000000000

26.18 Register 16 (10h) – 100BASE-TX Status Extension Register**Register 16 (10h) – 100BASE-TX Status Extension Register**

Bit	Name	Access	States	Reset Value	Sticky
15	100BASE-TX Descrambler Locked	RO	1 = Descrambler locked 0 = Descrambler not locked	0	
14	100BASE-TX Lock Error Detected	RO LH	1 = Lock error detected since last read 0 = Lock error not detected since last read	0	
13	100BASE-TX Disconnect State	RO LH	1 = PHY 100BASE-TX link disconnected 0 = PHY 100BASE-TX link not disconnected	0	
12	100BASE-TX Current Link Status	RO	1 = PHY 100BASE-TX link active 0 = PHY 100BASE-TX link inactive	0	
11	100BASE-TX Receive Error Detected	RO LH	1 = Receive error detected since last read 0 = Receive error not detected since last read	0	
10	100BASE-TX Transmit Error Detected	RO LH	1 = Transmit error detected since last read 0 = Transmit error not detected since last read	0	
9	100BASE-TX SSD (Start-of-Stream Delimiter error) Error Detected	RO LH	1 = SSD error detected since last read 0 = SSD error not detected since last read	0	
8	100BASE-TX ESD (End-of-Stream Delimiter error) Error Detected	RO LH	1 = ESD error detected since last read 0 = ESD error not detected since last read	0	
7:0	Reserved	RO		--	

26.19 Register 17 (11h) – 1000BASE-T Status Extension Register #2

Register 17 (11h) – 1000BASE-T Status Extension Register #2					
Bit	Name	Access	States	Reset Value	Sticky
15	1000BASE-T Descrambler Locked	RO	1 = Descrambler locked 0 = Descrambler not locked	0	
14	1000BASE-T Lock Error Detected	RO LH	1 = Lock error detected since last read 0 = Lock error not detected since last read	0	
13	1000BASE-T Disconnect State	RO LH	1 = PHY 1000BASE-T link disconnected 0 = PHY 1000BASE-T link not disconnected	0	
12	1000BASE-T Current Link Status	RO	1 = PHY 1000BASE-T link active 0 = PHY 1000BASE-T link inactive	0	
11	1000BASE-T Receive Error Detected	RO LH	1 = Receive error detected since last read 0 = Receive error not detected since last read	0	
10	1000BASE-T Transmit Error Detected	RO LH	1 = Transmit error detected since last read 0 = Transmit error not detected since last read	0	
9	1000BASE-T SSD (Start-of-Stream Delimiter error) Error Detected	RO LH	1 = SSD error detected since last read 0 = SSD error not detected since last read	0	
8	1000BASE-T ESD (End-of-Stream Delimiter error) Error Detected	RO LH	1 = ESD error detected since last read 0 = ESD error not detected since last read	0	
7	1000BASE-T Carrier Extension Error Detected	RO LH	1 = Carrier extension error detected since last read 0 = Carrier extension error not detected since last read	0	
6	Non-compliant BCM5400 Detected ¹	RO	1 = Non-compliant BCM5400 detected 0 = Non-compliant BCM5400 not detected	0	
5:0	Reserved	RO		000000	

¹ This bit is set to "1" if the VSC8224 detects a non-compliant BCM5400 as its link partner; otherwise, this bit is set to "0". This bit is valid only when the 1000BASE-T descrambler has achieved a locked state.

26.20 Register 18 (12h) – Bypass Control Register

Register 18 (12h) – Bypass Control Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Transmit Disable	R/W	1 = Transmitter disabled in PHY 0 = Transmitter enabled	0	
14:9	Reserved	RO		--	
8	1000BT Transmitter Test Clock Enable	R/W	1 = Enable TX_TCLK test output on CLK125 _{micro} pin 0 = Disable TX_TCLK test output on CLK125 _{micro} pin	0	
7:6	Reserved	RO		--	
5	Disable Automatic Pair Swap Correction	R/W	1 = Disable pair swap correction 0 = Enable pair swap correction	0	S
4	Disable Polarity Correction	R/W	1 = Disable polarity inversion correction 0 = Enable polarity inversion correction	0	S
3	Parallel-Detect Control	R/W	1 = Do not ignore advertised ability 0 = Ignore advertised ability	1	S
2	Reserved	RO		--	
1	Disable Automatic 1000BASE-T Next-Page Exchange	R/W	1 = Disable automatic 1000BASE-T Next-Page exchanges 0 = Enable automatic 1000BASE-T Next-Page exchanges	0	S
0	125MHz _{MAC} Clock Output Enable	R/W	1 = Enable 125MHz output clock pin CLK125 _{MAC} 0 = Disable 125MHz output clock pin CLK125 _{MAC}	1	S

18.15 – Transmit Disable

When bit 18.15 is set to “1”, the analog blocks are powered down and zeros are sent to the DAC.

18.8 – 1000BT Transmitter Test Clock Enable

When bit 18.8 is written to a “1”, the CLK125_{micro} output pin becomes a test pin for the transmit clock “TX_TCLK” of a particular PHY port. This capability is intended to enable measurement of transmitter timing jitter, as specified in IEEE Standard 802.3-2002, section 40.6.1.2.5. When in IEEE-specified transmitter test modes 2 or 3 (see IEEE 802.3-2002, section 40.6.1.1.2 and [MII Register bits 9.15:13](#)), the peak-to-peak jitter of the zero-crossings of the differential signal output at the MDI, relative to the corresponding edge of TX_TCLK, is measured. The corresponding edge of TX_TCLK is the edge of the transmit test clock, in polarity and time, that generates the zero-crossing transition being measured.

While transmitter test mode clocks TX_TCLK_n are intended only for characterization test purposes, CLK125_{micro} is intended, for example, to serve as a general purpose system or MAC reference clock.

Five distinct clock signals can be multiplexed onto the VSC8224's CLK125_{micro} pin, depending on a combination of the settings of [MII Register bits 9.15:13](#), MII Register bit 18.8, and [MII Register bit 18.0](#) (CLK125 Output Enable), as specified in the following table:

Table 26-3. Register Settings for Clock Signal Multiplexing

Signal Multiplexed onto CLK125 Pin	Enabled by MII Register States
TX_TCLK_0	PHY0, ((9.15:13 == 010) (9.15:13 == 011) (18.8 == 1))
TX_TCLK_1	PHY1, ((9.15:13 == 010) (9.15:13 == 011) (18.8 == 1))
TX_TCLK_2	PHY2, ((9.15:13 == 010) (9.15:13 == 011) (18.8 == 1))
TX_TCLK_3	PHY3, ((9.15:13 == 010) (9.15:13 == 011) (18.8 == 1))
CLK125 ¹	PHY0, 18.0 == 1

¹ Only PHY Port 0's bit 18.0 controls the operation of CLK125 (see [MII Register bit 18.0](#)).

18.5 – Disable Automatic Pair Swap Correction¹

When bit 18.5 is set to “0”, the PHY automatically corrects pair swaps between subchannels A and B, and between subchannels C and D, due to “MDI/MDI-X crossover”. It will also correct pair swaps between subchannels C and D due to cabling errors. When bit 18.5 is set to “1”, the PHY does not correct pair swaps.

18.4 – Disable Polarity Correction¹

When bit 18.4 is set to “0”, the PHY automatically corrects polarity inversion on all the subchannels. When bit 18.4 is set to “1”, the PHY does not compensate for polarity inversions.

18.2 – Disable Pulse Shaping Filter¹

When bit 18.2 is set to “1”, the 1000BASE-T two-tap digital transmit filter is disabled.

18.1 – Disable Automatic 1000BASE-T Next-Page Exchanges

Bit 18.1 is used to control the automatic exchange of 1000BASE-T Next-Pages defined in IEEE 802.3-2002 (Annex 40C). When this bit is set, the automatic exchange of these pages is disabled, and the control is returned to the user through the SMI after the base page has been exchanged. The user then has complete responsibility to:

- send the correct sequence of Next-Pages to the Link Partner, *and*
- determine common capabilities and force the device into the correct configuration following successful exchange of pages.

When bit 18.1 is reset to “0”, the 1000BASE-T related Next-Pages are automatically exchanged without user intervention. If the Next Page bit [4.15](#) was set by the user in the Auto-Negotiation Advertisement register at the time the Auto-Negotiation was restarted, control is returned to the user for additional Next-Pages following the 1000BASE-T Next-Page exchange.

If both 18.1 and [4.15](#) are reset when an Auto-Negotiation sequence is initiated, all Next-Page exchange is automatic, including sourcing of null pages. No user notification is provided until either Auto-Negotiation completes or fails. See the description of Register bit 4.15 for more details on standard Next-Page exchanges.

¹This bit applies only in 1000BASE-T mode

18.0 – Enable 125MHz MAC Free-Running Clock Output

When bit 18.0 is set to “1”, the VSC8224 provides a free-running, general-purpose 125MHz clock on the CLK125_{MAC} output pin. The electrical specifications for this clock corresponds to the current setting for VDDIO_{MAC}. This clock can be used by a MAC, a switch, or other synchronous logic. By default, this pin is enabled, which enables the clock output, independent of the status of any link, unless a hardware reset is active (which also powers down the PLL). When disabled, this pin is normally driven low. Note that only PHY Port 0’s bit 18.0 controls the operation of CLK125_{MAC}.

26.21 Register 19 (13h) – Reserved**Register 19 (13h) – Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO		--	

26.22 Register 20 (14h) – Reserved**Register 20 (14h) – Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO		--	

26.23 Register 21 (15h) – Reserved**Register 21 (15h) – Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO		--	

26.24 Register 22 (16h) – Extended Control & Status Register

Register 22 (16h) – Extended Control & Status Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Force 10BT Link High	R/W	1 = Disable link integrity test 0 = Enable link integrity test	0	S
14	Jabber Detect Disable	R/W	1 = Disable jabber detect 0 = Enable jabber detect	0	S
13	Disable 10BASE-T echo	R/W	1 = Disable 10BASE-T echo 0 = Enable 10BASE-T echo	1	S
12	Reserved	RO	-	--	
11:10	10BASE-T Squelch Control	R/W	00 = Normal squelch 01 = Low squelch 10 = High squelch 11 = Reserved	00	S
9	Sticky Reset Enable	R/W	1 = All bits marked as sticky will retain their values during software reset 0 = All bits marked as sticky will be changed to default values during software reset	1	SS
8	EOF Error Detected	RO SC	1 = EOF error detected since last read 0 = EOF error not detected since last read	0	
7	10BASE-T Disconnect State	RO SC	1 = 10BASE-T link disconnected 0 = 10BASE-T link connected	0	
6	10BASE-T Link Status	RO	1 = 10BASE-T link active 0 = 10BASE-T link inactive	0	
5:0	Reserved	RO	-	--	

22.15 – Force 10BT Link High¹

When bit 22.15 is set to “0”, the VSC8224 link integrity state machine runs automatically; it also controls link pass status. When bit 22.15 is set to “1”, the link integrity state machine is bypassed, and the PHY is forced into link pass status.

22.14 – Disable Jabber Detect¹

When bit 22.14 is set to “0”, the VSC8224 automatically shuts off the transmitter when a transmission request exceeds the IEEE-specified time limit. When bit 22.14 is set to “1”, transmission requests are allowed to be arbitrarily long without shutting down the transmitter.

22.13 – Disable 10BASE-T Echo Mode¹

When bit 22.13 is set to “1”, the logical state of the TX_EN pin will *not* echo onto the CRS pin, effectively disabling CRS from being asserted in half-duplex operation. When bit 22.13 is set to “0”, the TX_EN pin will be echoed onto the CRS pin. Data on TXD is echoed to RXD in 10BASE-T mode only.

22.11:10 – Squelch Control¹

When bits 22.11:10 are set to “00”, the VSC8224 uses the squelch threshold levels prescribed by the IEEE’s 10BASE-T specification. When bits 22.11:10 are set to “01”, the squelch level is decreased, which may improve the bit error rate performance on long loops. When bits 22.11:10 are set to “10”, the squelch level is increased, which may improve the bit error rate in high-noise environments.

¹This bit applies only in 10BASE-T mode.

22.9 - Sticky Reset Enable

When bit 22.9 is set, all MII register bits that are marked with an “S” in the “sticky” column will retain their values during a software reset. When cleared, all MII register bits that are marked with an “S” in the “sticky” column will be changed to their default values during a software reset. Note that bits marked with an “SS” retain their values across software reset regardless of the setting of bit 22.9.

22.8 – EOF Error¹

When bit 22.8 returns a “1”, a defective EOF (End-of-Frame) sequence has been received since the last time this bit was read. This bit is automatically set to “0” when it is read.

22.7 – 10BASE-T Disconnect State

Bit 22.7 is set to “1” if the 10BASE-T connection has been broken by the carrier integrity monitor since the last read of this bit; otherwise, this bit is set to “0”.

¹This bit applies only in 10BASE-T mode.

26.25 Register 23 (17h) – Extended PHY Control Register #1

Register 23 (17h) – Extended PHY Control Register #1					
Bit	Name	Access	States	Reset Value	Sticky
15:12	MAC/Media Interface Mode Select	R/W	See table in register description below. Important: To change operating modes, write bits 15:12 and 2:1 to their intended settings, write a 1 to register bit 0.15 for the change to take effect. This sequence should be completed first, before all other configuration writes to other registers are performed.	CMODE	SS
11:10	RGMII TX_CLK Skew Selection	R/W	00 = No skew on TX_CLK 01 = 1.5ns skew on TX_CLK 10 = 2ns skew on TX_CLK 11 = 2.5ns skew on TX_CLK	CMODE	S
9:8	RGMII RX_CLK Skew Selection	R/W	00 = No skew on RX_CLK 01 = 1.5ns skew on RX_CLK 10 = 2ns skew on RX_CLK 11 = 2.5ns skew on RX_CLK	CMODE	S
7:6	Reserved	RO	-	--	
5	RX Idle Clock Enable	R/W	1 = 25MHz clock on RX_CLK pin enabled in ActiPHY mode 0 = 25MHz clock on RX_CLK pin disabled in ActiPHY mode	1	SS
4	Register View ¹	R/W	1 = MII registers 0:15 correspond to the definition in IEEE802.3 clause 37.2.5 0 = MII registers 0:15 correspond to the definition in IEEE802.3 clause 28.2.4	0	SS
3	Far End Loopback Mode Enable	R/W	1 = Far end loopback is enabled 0 = Far end loopback is disabled	0	
2:1	MAC/Media Interface Mode Select	R/W	See table in register description below Important: To change operating modes, write bits 15:12 and 2:1 to their intended settings, write a 1 to register bit 0.15 for the change to take effect. This sequence should be completed first, before all other configuration writes to other registers are performed.	CMODE	SS
0	EEPROM Status	RO	1 = EEPROM is detected on EEPROM interface 0 = EEPROM is not detected on EEPROM interface	0	

¹ Register view setting is only supported when the MAC interface is set to an RGMII mode.

23.15:12, 2:1– MAC/Media Interface Mode Select

Bits 23.15:12 and 23.2:1 are used to select the MAC interface modes and media interface modes.

Important: To change operating modes, write bits 15:12 and 2:1 to their intended settings and write a 1 to register bit 0.15 for the change to take effect. This sequence should be completed first, before all other configuration writes to other registers are performed.

The reset value for these bits is dependent upon the state of the MAC Interface bits in the CMODE hardware configuration. Please note that all combinations of bits not indicated below are to be considered RESERVED settings:

Table 26-4. MAC/Media Interface Mode Select

Bits 23.15:12	Bits 23.2:1	CMODE ¹ MAC Inter- face [2:0]	MAC Interface	Media Interface	Options
0001	10	111	RGMII	CAT-5	
0001	11	-	RGMII	CAT-5	Clock recovery on SerDes interface enabled
0001	01	-	RGMII	SerDes/Fiber	
0000	00	-	RGMII	AMS	No AMS preference
0000	01	000	RGMII	AMS	AMS preference set to SerDes/Fiber
0000	10	-	RGMII	AMS	AMS preference set to CAT-5
0101	00	-	RTBI	CAT-5	Clause 37 autonegotiation disabled
0100	01	001	RTBI	CAT-5	Clause 37 autonegotiation enabled
0100	10	-	RTBI	CAT-5	Clause 37 autonegotiation enabled - media converter
0100	11	-	RTBI	CAT-5	Clause 37 autonegotiation enabled - interlock disabled
0100	00	-	RTBI	CAT-5	Clause 37 autonegotiation autosense
0101	11	-	RTBI	SerDes/Fiber	Transparent mode
0101	01	-	RTBI	SerDes/Fiber	Non-transparent mode (FIFO Mode)

¹ The CMODE pins set the reset value of these bits. Only 8 reset values are possible and are indicated in the CMODE MAC Interface column in the table. All other modes must be set by writing to these bits after reset.

23.11:10 – RGMII TX_CLK Skew Selection

Bits 23.11:10 specify the amount of clock delay added to the TX_CLK line inside the VSC8224 in RGMII and RTBI interfaces. By enabling this internal delay, a PCB “trombone” delay is not required as specified by the RGMII standard. Multiple values are provided to compensate for PCB trace skews. The default values of these bits are specified by the RGMII Skew bits in the CMODE hardware configuration.

23.9:8 – RGMII RX_CLK Skew Selection

Bits 23.9:8 specify the amount of clock delay added to the RX_CLK line inside the VSC8224 in RGMII and RTBI interfaces. By enabling this internal delay, a PCB “trombone” delay is not required as specified by the RGMII standard. Multiple values are provided to compensate for PCB trace skews. The default values of these bits are specified by the RGMII Skew bits in the CMODE hardware configuration.

23.5 – RX Idle Clock Enable

When bit 23.5 is set to “1”, a 25MHz clock is enabled on the RX_CLK pin when the VSC8224 is in ActiPHY mode. When bit 23.5 is cleared, the RX_CLK pin remains low during ActiPHY mode. This clock is enabled by default.

23.4 – Register View

When bit 23.4 is set to “1”, MII registers 0:15 correspond to the definition in IEEE802.3 clause 28.2.4. When bit 23.4 is cleared, MII registers 0:15 correspond to the definition in IEEE802.3 clause 37.2.5. Bit 23.4 is set to “1” by default. A software reset (MII Register bit 0.15 = 1) is required after this bit is set in order for the change to take effect.

23.3 – Far End Loopback Mode Enable

When bit 23.3 is set to “1”, all incoming data from the link partner on the current media interface is retransmitted back to the link partner on the media interface. In addition the incoming data will also appear on the RX pins of the MAC interface. Any data present on the TX pins of the MAC interface is ignored by the VSC8224 when bit 23.3 is set. In order to avoid loss of data, bit 23.3 should not be set while the VSC8224 is receiving data on the media interface. Bit 23.3 applies to all MAC interfaces and to all media interfaces in the VSC8224. When bit 23.3 is cleared, the VSC8224 resumes normal operation. This bit is cleared by default.

23.0 – EEPROM Status

When bit 23.0 is set to “1”, an EEPROM has been detected on the external EEPROM interface. When cleared, bit 23.0 indicates that no EEPROM has been detected.

26.26 Register 24 (18h) – Extended PHY Control Register #2

Register 24 (18h) – Extended PHY Control Register #2					
Bit	Name	Access	States	Reset Value	Sticky
15:13	100/1000BASE-T Edge Rate Control	R/W	011 = +3 edge rate (slowest) 010 = +2 edge rate 001 = +1 edge rate 000 = Nominal edge rate 111 = -1 edge rate 110 = -2 edge rate 101 = -3 edge rate 100 = -4 edge rate (fastest)	000	S
12	Enable PICMG Reduced Power Mode	R/W	1 = PICMG Reduced Power mode is enabled 0 = PICMG Reduced Power mode is disabled	0	S
11:10	Reserved	RO	-	--	
9:7	1000BT TX FIFO Depth Control	R/W	000 to 010 = Reserved 011 = Jumbo packet mode 100 = IEEE mode 101 to 111 = Reserved	100	S
6:4	1000BT RX FIFO Depth Control	R/W	000 to 010 = Reserved 011 = Jumbo packet mode 100 = IEEE mode 101 to 111 = Reserved	100	S
3:1	Reserved	RO	-	--	
0	1000BT connector loopback	R/W			

24.15:13 – 100/1000BASE-T Edge Rate Control

Bits 24.15:13 control the transmit DAC slew rate in 100BASE-TX and 1000BASE-T modes only, as shown above. The difference between each setting is approximately 200ps to 300ps, with the “+3” setting resulting in the slowest edge rate, and the “-4” setting resulting in the fastest edge rate. 24.12:10 – Reserved - Must write to 000

24.12 - Enable PICMG Reduced Power Mode

Setting bit 24.12 turns off unneeded portions of the PHY's DSP block and reduces the PHY's operating power. The DSP performance characteristics in this mode are configured to support the channel characteristics specified in the PICMG 2.16 and PICMG 3.0 specifications. The media interface must be configured for CAT-5 operation. See www.picmg.org for more information. This bit can be set in order to reduce power consumption in applications where the signal to noise ratio on the media is high, such as ethernet over the backplane, or where the cable length is short (<10m). This bit is applicable only to CAT-5 copper media, or backplanes, not fiber. PICMG Reduced Power Mode may be used in certain applications with capacitive

coupled media, rather than transformer coupled, to reduce PCB area and cost. For more information, refer to the Application Note "Transformerless Ethernet Concept and Applications".

24.9:7 – 1000BT TX FIFO Depth Control for RGMII

Bits 24.9:7 control symbol buffering for the transmit synchronization FIFO used in all 1000BT modes except for RTBI-Serdes/Fiber mode. An internal FIFO is used to synchronize the clock domains between the MAC transmit clock and the PHY's clock (e.g., REFCLK), used to transmit symbols on the local PHY's twisted pair interface.

The IEEE mode supports up to 1518-byte packet size with the minimum inter-packet gap (IPG). The jumbo packet mode adds latency to the path to support up to 9600-byte packets with the minimum inter-packet gap (IPG). When using jumbo packet mode, a larger IPG is recommended due to the possible compression of the IPG at the output of the FIFO.

24.6:4 – 1000BT RX FIFO Depth Control

Used in the RTBI modes only, bits 24.6:4 control symbol buffering as determined by the receive synchronization FIFO. An internal FIFO is used to synchronize the clock domains between the MAC receive clock and the PHY's clock (e.g., REFCLK), used to receive symbols on the local PHY's twisted pair interface.

The IEEE mode supports up to 1518-byte packet size with the minimum inter-packet gap (IPG). The jumbo packet mode adds latency to the path to support up to 9600-byte packets with the minimum inter-packet gap (IPG). When using jumbo packet mode, a larger IPG is recommended due to the possible compression of the IPG at the output of the FIFO.

26.27 Register 25 (19h) – Interrupt Mask Register

Register 25 (19h) – Interrupt Mask Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Interrupt Pin Enable	R/W	1 = Enable interrupt pin 0 = Disable interrupt pin	0	S
14	Speed State-Change Interrupt Mask	R/W	1 = Enable Speed interrupt 0 = Disable Speed interrupt	0	S
13	Link State-Change/ Energy Detect Interrupt Mask	R/W	1 = Enable Link State/ Energy Detect interrupt 0 = Disable Link State/ Energy Detect interrupt	0	S
12	FDX State-Change Interrupt Mask	R/W	1 = Enable FDX interrupt 0 = Disable FDX interrupt	0	S
11	Auto-Negotiation Error Interrupt Mask	R/W	1 = Enable Auto-Negotiation Error interrupt 0 = Disable Auto-Negotiation Error interrupt	0	S
10	Auto-Negotiation-Done/ Interlock Done Interrupt Mask	R/W	1 = Enable Auto-Negotiation-Done/ Interlock Done interrupt 0 = Disable Auto-Negotiation-Done/ Interlock Done interrupt	0	S
9	In-line Powered Device Detected Interrupt Mask	R/W	1 = Enable In-line Powered Device Detected interrupt 0 = Disable In-line Powered Device Detected interrupt	0	S
8	Symbol Error Interrupt Mask	R/W	1 = Enable Symbol Error interrupt 0 = Disable Symbol Error interrupt	0	S
7	Descrambler Lock-Lost Interrupt Mask	R/W	1 = Enable Lock-Lost interrupt 0 = Disable Lock-Lost interrupt	0	S
6	TX FIFO Interrupt Mask	R/W	1 = Enable TX FIFO interrupt 0 = Disable TX FIFO interrupt	0	S
5	RX FIFO Interrupt Mask	R/W	1 = Enable RX FIFO interrupt 0 = Disable RX FIFO interrupt	0	S
4	AMS Media Change Interrupt Mask	R/W	1 = Enable AMS Media Change interrupt 0 = Disable AMS Media Change interrupt	0	S
3	False Carrier Interrupt Mask	R/W	1 = Enable False Carrier interrupt 0 = Disable False Carrier interrupt	0	S
2	Cable Impairment Detect Interrupt Mask	R/W	1 = Enable Cable Impairment Detect interrupt 0 = Disable Cable Impairment Detect interrupt	0	S
1	MASTER/SLAVE Interrupt Mask	R/W	1 = Enable MASTER/SLAVE interrupt 0 = Disable MASTER/SLAVE interrupt	0	S
0	RX_ER Interrupt	R/W	1 = Enable RX_ER interrupt 0 = Disable RX_ER interrupt	0	S

25.15 – Interrupt Pin Enable

When bit 25.15 is set to “1”, the hardware interrupt is enabled, meaning that the state of the external interrupt pin (MDINT_n) can be influenced by the state of the [Interrupt Status bit \(26.15\)](#). When bit 25.15 is set to “0”, the interrupt status bits ([Register 26](#)) continue to be set in response to interrupts, but the interrupt hardware pin MDINT_n on the VSC8224 will not be influenced by this particular PHY.

26.28 Register 26 (1Ah) – Interrupt Status Register

Register 26 (1Ah) – Interrupt Status Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Interrupt Status	RO SC	1 = Interrupt pending 0 = No interrupt pending	0	
14	Speed State-Change Interrupt Status ¹	RO SC	1 = Speed interrupt pending	0	
13	Link State-Change/ Energy Detect Interrupt Status	RO SC	1 = Link State-Change/ Energy Detect interrupt pending	0	
12	FDX State-Change Interrupt Status ¹	RO SC	1 = FDX interrupt pending	0	
11	Auto-Negotiation Error Interrupt Status	RO SC	1 = Auto-Negotiation Error interrupt pending	0	
10	Auto-Negotiation-Done/ Interlock Done Interrupt Status	RO SC	1 = Auto-Negotiation-Done/ Interlock Done interrupt pending	0	
9	In-line Powered Device Interrupt Status	RO SC	1 = In-line Powered Device interrupt pending	0	
8	Symbol Error Interrupt Status	RO SC	1 = Symbol Error interrupt pending	0	
7	Descrambler Lock-Lost Interrupt Status	RO SC	1 = Lock-Lost interrupt pending	0	
6	TX FIFO Interrupt Status	RO SC	1 = TX FIFO interrupt pending	0	
5	RX FIFO Interrupt Status	RO SC	1 = RX FIFO interrupt pending	0	
4	AMS Media Change Interrupt Status	RO SC	1 = AMS Media Change interrupt pending	0	
3	False Carrier Interrupt Status	RO SC	1 = False Carrier interrupt pending	0	
2	Cable Impairment Detect Interrupt Status	RO SC	1 = Cable Impairment Detect interrupt pending	0	
1	MASTER/SLAVE Interrupt Status	RO SC	1 = MASTER/SLAVE Error interrupt pending	0	
0	RX_ER Interrupt Status	RO	1 = RX_ER interrupt pending 0 = No RX_ER interrupt pending	0	

¹ These bits are only valid when the MAC/media interface mode select (MII Register bits 23.15:12,2:1) is set to CAT-5 as the media interface. Example: RGMII-CAT5

26.15 – Interrupt Status

When bit 26.15 is set to "1", an unacknowledged interrupt is pending. The cause of the interrupt can be determined by reading the interrupt status bits in this register. This bit is automatically cleared when read.

26.14 – Speed State-Change Interrupt Status

When the operating speed of the PHY changes, bit 26.14 is set to "1" if bit 25.14 is set to "1" and if bit 0.12 is also set to "1". This bit is automatically cleared when read.

26.13 – Link State-Change/ Energy Detect Interrupt Status

When the link status of the PHY changes, or if ActiPHY mode is enabled, and energy is detected on the media, bit 26.13 is set to "1" if bit 25.13 is also set to "1". This bit is automatically cleared when read.

26.12 – FDX State-Change Interrupt Status

When the FDX/HDX status of the PHY changes, bit 26.12 is set to "1" if bit 25.12 is set to "1" and if bit 0.12 is also set to "1". This bit is automatically cleared when read.

26.11 – Auto-Negotiation Error Interrupt Status

When an error is detected by the Auto-Negotiation state machine, bit 26.11 is set to “1” if bit 25.11 is also set to “1”. This bit is automatically cleared when read.

26.10 – Auto-Negotiation-Done/Interlock Done Interrupt Status

When the Auto-Negotiation state machine finishes a negotiation process, bit 26.10 is set to “1” if bit 25.10 is also set to “1”. This bit is automatically cleared when read.

26.9 – In-line Powered Device Interrupt Status

When a device requiring in-line power over CAT-5 is detected, bit 26.9 is set to “1” if bit 25.9 is also set to “1”. This bit is automatically cleared when read.

26.8 – Symbol Error Interrupt Status

When a symbol error is detected by the descrambler, bit 26.8 is set to “1” if bit 25.8 is also set to “1”. This bit is automatically cleared when read.

26.7 – Descrambler Lock-Lost Interrupt Status

When the descrambler loses lock, bit 26.7 is set to “1” if bit 25.7 is also set to “1”. This bit is automatically cleared when read.

26.6 – TX FIFO Interrupt Status

When the TX FIFO enters an underflow or overflow condition, bit 26.6 is set to “1” if bit 25.6 is also set to “1”. This bit is automatically cleared when read.

26.5 – RX FIFO Interrupt Status

When the RX FIFO enters an underflow or overflow condition, bit 26.5 is set to “1” if bit 25.5 is also set to “1”. This bit is automatically cleared when read.

26.4 – AMS Media Change Interrupt Status

When the media type has changed as a result of AMS, bit 26.4 is set to “1” if bit 25.4 is also set to “1”. This bit is automatically cleared when read.

26.3 – False Carrier Detect Interrupt Status

When the PHY has detected a false carrier, bit 26.3 is set to “1” if bit 25.3 is also set to “1”. This bit is automatically cleared when read,

26.2 – Cable Impairment Detect Interrupt Status

When the PHY has detected an impairment on the CAT-5 media, bit 26.2 is set to “1” if bit 25.2 is also set to “1”. This bit is automatically cleared when read. This feature is disabled if MII register bits 4:8.5 are all set to “0”.

26.1 – MASTER/SLAVE Resolution Error Interrupt Status

When a MASTER/SLAVE resolution error is detected, bit 26.1 is set to “1” if bit 25.1 is also set to “1”. This bit is automatically cleared when read.

26.0 – RX_ER Interrupt Status

When an RX_ER condition occurs, bit 26.0 is set to “1”. This bit is automatically cleared when read.

26.29 Register 27 (1Bh) – LED Control Register

Register 27 (1Bh) – LED Control Register					
Bit	Name	Access	States	Reset Value	Sticky
15:14	LED Pin 4 Configuration	R/W	00 = Duplex/Collision 01 = Activity 10 = Link Fault 11 = Link/Activity	CMODE	S
13:12	LED Pin 3 Configuration	R/W	00 = Collision 01 = Duplex/Collision 10 = Fiber Media Selected 11 = Rx	CMODE	S
11:10	LED Pin 2 Configuration	R/W	00 = Link10/Activity 01 = Duplex/Collision 10 = Link/Activity 11 = Tx	CMODE	S
9:8	LED Pin 1 Configuration	R/W	00 = Link100/Activity 01 = Link10/100/Activity 10 = Link/Activity 11 = Link100/1000/Activity	CMODE	S
7:6	LED Pin 0 Configuration	R/W	00 = Link1000/Activity 01 = Link/Activity w/ Serial output on LED pins 1 and 2 10 = Fault 11 = Rx	CMODE	S
5	LED Pulse-stretch Rate/ Blink Rate	R/W	1 = 10Hz blink rate/ 100ms pulse-stretch 0 = 5Hz blink rate/ 200ms pulse-stretch	0	S
4	LED Pulsing Enable	R/W	1 = Enable 5KHz, 20% duty cycle LED pulsing for power savings 0 = LED pulsing disabled	0	S
3	LED Pulse-Stretch/ Blink Select	R/W	1 = Collision, Activity, Rx and Tx functions will pulse-stretch when active. 0 = Collision, Activity, Rx and Tx functions will blink when active.	CMODE	S
2	LED Link/Activity Behavior	R/W	1 = Link function indicates link status only 0 = Link function will blink or flash when activity is present. Blink/flash behavior is selected by Pulse-Stretch Enable and Blink/Pulse-Stretch Rate bits.	CMODE	S
1	LED Link10/100/1000/Activity Behavior	R/W	1 = Link10, Link 100, Link1000, Link10/100, and Link100/1000 LEDs indicates link status only 0 = Link10, Link 100, Link1000, Link10/100, and Link100/1000 LEDs will blink or flash when activity is present. Blink/flash behavior is selected by Pulse-Stretch Enable and Blink/Pulse-Stretch Rate bits.	CMODE	S
0	LED Duplex/Collision Behavior	R/W	1 = Duplex function indicates duplex status only 0 = Duplex function will blink or flash when collision is present	CMODE	S

27.15:6 – LED Pin Configuration

Each of the five LED pins on each port of the VSC8224 can be configured for one of four functions. These functions are different for each LED pin.¹ Bits 27.15:6 are used to select the function for each LED pin. The reset value of these bits is set by the LED configuration bits in the CMODE hardware configuration.

26.30 Register 28 (1Ch) – Auxiliary Control & Status Register

Register 28 (1Ch) – Auxiliary Control & Status Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Auto-Negotiation Complete ¹	RO	1 = Auto-Negotiation complete 0 = Auto-Negotiation not complete	0	
14	Auto-Negotiation Disabled ¹	RO	1 = Auto-Negotiation was disabled 0 = Auto-Negotiation is enabled	0	
13	MDI/MDI-X Crossover Indication ¹	RO	1 = MDI/MDI-X crossover detected 0 = MDI/MDI-X crossover not detected	0	
12	CD Pair Swap ¹	RO	1 = CD pairs are swapped 0 = CD pairs are not swapped	0	
11	A Polarity Inversion ¹	RO	1 = Polarity swapped on pair A 0 = Polarity not swapped on pair A	0	
10	B Polarity Inversion ¹	RO	1 = Polarity swapped on pair B 0 = Polarity not swapped on pair B	0	
9	C Polarity Inversion ¹	RO	1 = Polarity swapped on pair C 0 = Polarity not swapped on pair C	0	
8	D Polarity Inversion ¹	RO	1 = Polarity swapped on pair D 0 = Polarity not swapped on pair D	0	
7	Reserved	RO	-	--	
6	ActiPHY™ Mode Enable	R/W	1 = Enable ActiPHY™ power management 0 = Disable ActiPHY™ power management	CMODE	S
5	FDX Status ¹	RO	1 = Full Duplex 0 = Half Duplex	0	
4:3	Speed Status ¹	RO	00 = Speed is 10BASE-T 01 = Speed is 100BASE-TX 10 = Speed is 1000BASE-T 11 = Reserved	00	
2	Reserved	RO	-	--	
1:0	ActiPHY™ and AMS Sleep Timer	R/W	00 = 1 second 01 = 2 seconds 10 = 3 seconds 11 = 4 seconds	01	

¹ These bits are only valid when the MAC/media interface mode select (MII Register bits 23.15:12,2:1) is set to CAT-5 as the media interface. Example: RGMII-CAT5

28.15 – Auto-Negotiation Complete

This bit is a copy of [bit 1.5](#), duplicated here for convenience.

28.14 – Auto-Negotiation Disabled

When bit 28.14 is read as a “1”, this bit indicates that the Auto-Negotiation process has been disabled. This happens only when register [bit 0.12](#) is set to “0”.

28.13 – MDI/MDI-X Crossover Indication

When bit 28.13 returns a “1”, the Auto-Negotiation state machine has determined that crossover does not exist in the signal path. The crossover will therefore be performed internally to the PHY, as described by the MDI/MDI-X crossover specification.¹

¹Note that if bits 27.7:6 are set to “01”, LED pins 1 and 2 are used as serial output pins and the values of bits 27.11:8 are ignored

¹This bit is valid only after descrambler lock has been achieved and as long as bit 18.5 is set to “0”.

28.12 – CD Pair Swap¹

When bit 28.12 returns a “1”, the PHY has determined that subchannel cable pairs C and D have been swapped between the far-end transmitter and the receiver. When bit 28.12 returns a “1”, the PHY internally swaps pairs C and D (as long as [bit 18.5](#) is set to “0”).¹

28.11 – A Polarity Inversion

When bit 28.11 returns a “1”, the PHY has determined that the polarity of subchannel cable pair A has been inverted between the far-end transmitter and the near-end receiver. When bit 28.11 returns a “1”, the PHY internally corrects the pair inversion. Polarity-inversion correction runs in all three modes; as a result, the state of 28.11 is valid only when [bit 1.5](#) is set to “1”.

28.10 – B Polarity Inversion

When bit 28.10 returns a “1”, the PHY has determined that the polarity of subchannel cable pair B has been inverted between the far-end transmitter and the near-end receiver. When bit 28.10 returns a “1”, the PHY internally corrects the pair inversion. Polarity-inversion correction runs in all three modes; as a result, the state of 28.10 is valid only when [bit 1.5](#) is set to “1”.

28.9 – C Polarity Inversion²

When bit 28.9 returns a “1”, the PHY has determined that the polarity of subchannel cable pair C has been inverted between the far-end transmitter and the near-end receiver. When bit 28.9 returns a “1”, the PHY internally corrects the pair inversion. Polarity-inversion correction runs in all three modes; as a result, the state of 28.9 is valid only when [bit 1.5](#) is set to “1”.

28.8 – D Polarity Inversion¹

When bit 28.8 returns a “1”, the PHY has determined that the polarity of subchannel cable pair D has been inverted between the far-end transmitter and the near-end receiver. When bit 28.8 returns a “1”, the PHY internally corrects the pair inversion. Polarity-inversion correction runs in all three modes; as a result, the state of 28.8 is valid only when [bit 1.5](#) is set to “1”.

28.6 - Enable ActiPHY Mode

When bit 28.6 is set to a “1”, the ActiPHY power management mode is set in the VSC8224. The reset value for this bit is determined by the ActiPHY bit in the CMODE hardware configuration. Refer to [Section 21: "ActiPHY Power Management"](#) for more information. ActiPHY is automatically set if media interface is set to auto media sense. In this mode, this bit has no effect on enabling or disabling ActiPHY.

28.5 – FDX Status

Bit 28.5 indicates the actual FDX/HDX operating mode of the PHY.

28.4:3 – Speed Status

Bits 27.4:3 indicate the actual operating speed of the PHY.

28.1:0 – ActiPHY™ and AMS Sleep Timer

This sets the time period the PHY stays in ‘Low Power’ state when ActiPHY mode (MII Register Bit 28.6) is enabled before entering into the ‘LP Wake-up’ state. Refer to [Section 21: "ActiPHY Power Management"](#) for more information. This is also used when media interface is selected for auto media sense.

¹This bit applies only in 1000BASE-T mode.

²This bit applies only in 1000BASE-T mode.

26.31 Register 29 (1Dh) – Reserved**Register 29 (1Dh) – Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO			

26.32 Register 30 (1Eh) – Reserved**Register 30 (1Eh) – Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO			

26.33 Register 31 (1Fh) – Extended Page Access**Register 31 (1Fh) – Extended Page Access**

Bit	Name	Access	States	Reset Value	Sticky
15:1	Reserved	RO			
0	Extended Page Access	WO	1 = MII registers 16:30 will access extended register set 0 = MII registers 16:30 will access standard register set	0	

31.0 - Extended Page Access

To provide additional functionality beyond the IEEE802.3 specified 32 MII registers, the VSC8224 contains an extended register set, which supports an additional 15 registers. When bit 31.0 is set to a “1”, MII registers 16:30 access the extended set of registers. The state of bit 31.0 has no effect on MII registers 0:15. This bit is write-only and cannot be read back.

26.34 Register 16E (10h) - Fiber Media Clause 37 Autonegotiation Control & Status

Register 16E (10h) – Fiber Media Clause 37 Autonegotiation Control & Status					
Bit	Name	Access	States	Reset Value	Sticky
15:14	Reserved	RO	-	--	
13:12	Fiber Remote Fault	RO	Correspond to remote fault bits sent by fiber link partner during clause 37 autonegotiation	00	
11	Fiber Asymmetric Pause	RO	Corresponds to Asymmetric Pause bit sent by fiber link partner during clause 37 autonegotiation	0	
10	Fiber Symmetric Pause	RO	Corresponds to Symmetric Pause bit sent by fiber link partner during clause 37 autonegotiation	0	
9	Reserved	RO	-	--	
8	Fiber Full Duplex	RO	Corresponds to Full Duplex Ability bit sent by fiber link partner during clause 37 autonegotiation	0	
7	Fiber Half Duplex	RO	Corresponds to Half Duplex Ability bit sent by fiber link partner during clause 37 autonegotiation	0	
6	Reserved	RO	-	--	
5	Clause 37 Autonegotiation Complete	RO	1 = Clause 37 autonegotiation has completed successfully with fiber link partner 0 = Clause 37 autonegotiation has not completed with fiber link partner	0	
4	Clause 37 Autonegotiation Autosense Disable	R/W	1 = Clause 37 autonegotiation autosense is disabled 0 = Clause 37 autonegotiation autosense is enabled	1	S
3	Reserved	RO	-	--	
2:1	Remote Fault Mapping Mask	R/W	See table in register description	CMODE	S
0	Remote Fault Mapping OR	R/W	See table in register description	1	S

16E.4 - Clause 37 Autonegotiation Autosense Disable

When bit 16E.1 is cleared, the clause 37 autonegotiation autosensing ability is enabled. This bit is set to a "1" by default. For more information, see [Section 6.3: "IEEE802.3 Clause 28/37 Autonegotiation Interlocking Support"](#) for more information regarding clause 37 autonegotiation autosense.

16E.2:1 - Remote Fault Mapping Mask

These bits are used to map between Clause-37 remote fault and Clause-28 remote fault bits. See [Section 6.5: "IEEE802.3 Clause 28/37 Remote Fault Indication Support"](#) for information on bits 16E.2:1. The reset values for bits 16E.2:1 are determined by the remote fault bits in the CMODE hardware configuration.

16E.0 - Remote Fault Mapping OR

This bit is used to map between Clause-37 remote fault and Clause-28 remote fault bits. See [Section 6.5: "IEEE802.3 Clause 28/37 Remote Fault Indication Support"](#) for information on bit 16E.0.

26.35 Register 17E (11h) - CLK125_{micro} Clock Enable

Register 17E (11h) – CLK125 _{micro} Clock Enable					
Bit	Name	Access	States	Reset Value	Sticky
15:5	Reserved	RO	-	--	
4:2	SerDes Output Swing Control	R/W	000 = 400mV (peak-to-peak) 001 = 600mV (peak-to-peak) 010 = 800mV (peak-to-peak) 011 = 1000mV (peak-to-peak) 100 = 1200mV (peak-to-peak) 101 = 1400mV (peak-to-peak) 110/111 = 1600mV (peak-to-peak)	100	
1	Reserved	RO	–	–	
0	CLK125 _{micro} Clock Output Enable	R/W	1 = Enable CLK125 _{micro} output clock pin 0 = Disable CLK125 _{micro} output clock pin	0	S

17E.0 - Enable 125MHz_{micro} Free-Running Clock Output

When this bit is set to “1”, the VSC8224 provides a free-running, general-purpose clock on the CLK125_{micro} output pin. The electrical specifications for this clock corresponds to the current setting for VDDIO_{micro}. This clock can be used by a system manager CPU or other control logic. Please refer to [MII Register 20E.8](#) to set the CLK125_{micro} frequency. By default, this pin is disabled and must be set to a “1” in order to output a signal. When disabled, this pin is normally driven low. Note that only PHY Port 0's bit 17E.0 controls the operation of CLK125_{micro}.

26.36 Register 18E (12h) - Reserved

Register 18E (12h) – Reserved					
Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.37 Register 19E (13h) - SIGDET Control

Register 19E (13h) – SIGDET Control					
Bit	Name	Access	States	Reset Value	Sticky
15:2	Reserved	RO	-	--	
1	SIGDET pin direction	R/W	1 = Output 0 = Input	CMODE	
0	SIGDET pin polarity	R/W	1 = Active Low 0 = Active High	0	

26.38 Register 20E (14h) - Extended PHY Control Register #3

Register 20E (14h) – Extended PHY Control Register #3					
Bit	Name	Access	States	Reset Value	Sticky
15:9	Reserved	RO	-	--	
8	CLK125 _{micro} Frequency	R/W	1 = 125MHz clock output on CLK125 _{micro} 0 = 4MHz clock output on CLK125 _{micro}	0	S
7:6	Media Mode Status	RO	00 = No media selected 01 = Copper media selected 10 = Fiber media selected 11 = Reserved	0	
5	SerDes Interface Line Impedance	R/W	1 = 75 ohm impedance 0 = 50 ohm impedance	0	S
4	Enable Link Speed Auto-Downshift	R/W	1 = Enable auto link speed downshift 0 = Disable auto link speed downshift	CMODE	S
3:2	Link Speed Auto-Downshift Control	R/W	00 = Downshift after 2 failed attempts 01 = Downshift after 3 failed attempts 10 = Downshift after 4 failed attempts 11 = Downshift after 5 failed attempts	01	S
1	Link Speed Auto-Downshift Status	RO	0 = No downshift 1 = Downshift is required or has occurred	0	
0	Reserved	RO	-	--	

20E.8 - Clock Frequency Mode

The frequency of the CLK125_{micro} pin can be changed by using bit 20E.8. This bit is only valid in PHY0.

20E.7:6 - Media Mode Status

Bits 20E.7:6 reflect the currently active media interface. These bits are most useful for determining the interface currently selected by the Auto Media Sense function. If no link is established, these bits are cleared.

20E.5 - SerDes Line Impedance

The internal termination impedance of the high speed serial interface inside the VSC8224 can be selected using bit 20E.5. This applies to the SerDes pins on the device. The reset value of this bit is determined by the SerDes Line Impedance bit in the CMODE hardware configuration.

20E.4 - Enable Link Speed Auto-Downshift

When bit 20E.4 is set to a “1”, the VSC8224 will “downshift” the autonegotiation advertisement to the next lower available speed after the number of failed 1000BASE-T autonegotiation attempts specified in bits 20E.3:2. The reset value of this bit is determined by the Link Speed Downshift bit in the CMODE hardware configuration.

20E.3:2 - Link Speed Auto-Downshift Control

Bits 20E.3:2 determine the number of unsuccessful 1000BASE-T autonegotiation attempts that are required before the autonegotiation advertisement is “downshifted” to the next lower available speed. These bits are valid only if bit 20E.4 is set.

20E.1 - Link Speed Auto-Downshift Status

When bit 20E.1 is set to a “1” and bit 20E.4 is set to a “1”, the current link speed is the result of a “downshift”. When bit 20E.1 is set to a “1” and bit 20E.4 is cleared, the current link requires a “downshift” in order to be established.

26.39 Register 21E (15h) - EEPROM Interface Status and Control Register

Register 21E (15h) - EEPROM Interface Status and Control Register					
Bit	Name	Access	States	Reset Value	Sticky
15	Reserved	RO	-	--	
14	Re-read EEPROM on Software Reset	R/W	1 = Contents of EEPROM should be re-read on software reset 0 = Contents of EEPROM should not be re-read on software reset	0	SS
13	EEPROM Access Enable	R/W SC	1 = Execute read or write to EEPROM	0	
12	EEPROM Read/Write	R/W	1 = Read from EEPROM 0 = Write to EEPROM	1	
11	EEPROM Ready	RO	1 = EEPROM is ready for read/write 0 = EEPROM is busy	1	
10:0	EEPROM Address	R/W	EEPROM address to read/write	0	

21E.14 - Re-Read EEPROM on Software Reset

When bit 21E.14 is set to a “1”, the contents of the EEPROM will be re-read and reloaded into the MII registers upon software reset.

21E.13 - EEPROM Access Enable

When bit 21E.13 is set to a “1”, the EEPROM address in bits 21E.10:0 is written to or read from, based on the state of bit 21E.12. The data to read/write resides in register 22E.

21E.12 - EEPROM Read/Write

When bit 21E.12 is set to a “1”, the VSC8224 will read from the EEPROM when bit 21E.13 is set. When bit 21E.12 is cleared, the VSC8224 will write to the EEPROM when bit 21E.13 is set.

21E.11 - EEPROM Ready

When the VSC8224 is busy reading/writing to the EEPROM, bit 21E.11 will be cleared. Bit 21E.13 should not be set while bit 21E.11 is cleared.

21E.10:1 - EEPROM Address

These bits contain the EEPROM address that the VSC8224 will read from or write to when bit 21E.13 is set.

26.40 Register 22E (16h) - EEPROM Data Read/Write Register**Register 22E (16h) - EEPROM Data Read/Write Register**

Bit	Name	Access	States	Reset Value	Sticky
15:8	EEPROM Read Data	RO	8-bit data read from EEPROM	0	
7:0	EEPROM Write Data	R/W	8-bit data to write to EEPROM	0	

22E.15:18 - EEPROM Read Data

After an EEPROM read has occurred by setting bits 21E.13 and 21E.12 to a “1”, the data read from the EEPROM is placed in these bits.

22E.7:0 - EEPROM Write Data

When an EEPROM write is initiated by setting bits 21E.13 to a “1” and clearing bit 21E.12, the data from these bits is written to the EEPROM.

26.41 Register 23E (17h) - Extended PHY Control Register #4**Register 23E (17h) - Extended PHY Control Register #4**

Bit	Name	Access	States	Reset Value	Sticky
15:11	PHY Address	RO	PHY address latched on reset	CMODE	
10	Enable In-line Powered Device Detection	R/W	1 = In-line powered device detection is enabled 0 = In-line powered device detection is disabled	0	S
9:8	In-line Powered Device Detection Status	RO	00 = Searching for devices 01 = Device found which requires in-line power 10 = Device found which does not require in-line power 11 = Reserved	0	
7:0	1000BT CRC Counter	RO SC	CRC counter for Ethernet packet generator	0	

23E.15:11 - PHY Address

These bits contain the PHY address of the current PHY port. The reset value of these bits is determined by the PHY Address bits in the CMODE hardware configuration.

23E.10 - Enable In-line Powered Device Detection

When bit 23E.10 = 1, the VSC8224 will search for devices requiring CAT-5 in-line power as part of the autonegotiation process.

23E.9:8 - In-line Powered Device Detection Status

Bits 23E.9:8 are used by the station manager to determine if a device is connected to the VSC8224 which requires in-line power. These bits are only valid if bit 23E.10 = 1.

23E.7:0 - 1000BT CRC Counter

In 1000BT mode, these bits count the number of packets received that contain a CRC error. This counter will saturate at 0FFh and is cleared when read.

26.42 Register 24E (18h) - Reserved**Register 24E (18h) - Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.43 Register 25E (19h) - Reserved**Register 25E (19h) - Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.44 Register 26E (1Ah) - Reserved**Register 26E (1Ah) - Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.45 Register 27E (1Bh) - Reserved**Register 27E (1Bh) - Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.46 Register 28E (1Ch) - Reserved**Register 28E (1Ch) - Reserved**

Bit	Name	Access	States	Reset Value	Sticky
15:0	Reserved	RO	-	--	

26.47 Register 29E (1Dh) - 1000BASE-T Ethernet Packet Generator (EPG) Register #1

Register 29E (1Dh) - 1000BASE-T Ethernet Packet Generator (EPG) Register #1					
Bit	Name	Access	States	Reset Value	Sticky
15	EPG Enable	R/W	1 = Enable EPG 0 = Disable EPG	0	
14	EPG Run/Stop	R/W	1 = Run EPG 0 = Stop EPG	0	
13	Transmission Duration	R/W	1 = Continuous 0 = Send 30,000,000 packets and stop	0	
12:11	Packet Length	R/W	00 = 125 bytes 01 = 64 bytes 10 = 1518 bytes 11 = 10,000 bytes (jumbo packet)	0	
10	Inter-packet Gap	R/W	1 = 8,192 ns 0 = 96 ns	0	
9:6	Destination Address	R/W	MSB's lower nibble of the 6-byte destination address	0001	
5:2	Source Address	R/W	MSB's lower nibble of the 6-byte destination address	0000	
1	Reserved	RO	-	0	
0	Bad FCS Generation	R/W	1 = Generate packets with bad FCS 0 = Generate packets with good FCS	0	

29E.15 - EPG Enable

When bit 29E.15 is set to a “1”, the EPG is selected as the driving source for the PHY transmit signals, and the MAC transmit pins are disabled. When bit 29E.15 is cleared, the MAC has full control of the PHY transmit signals.

29E.14 - EPG Run/Stop

Bit 29E.14 controls the beginning and end of packet transmission. When this bit is set to a “1”, the EPG begins the transmission of packets. When this bit is cleared, the EPG ends the transmission of packets, after the current packet is transmitted. Bit 29E.14 is valid only if bit 29E.15 is set to a “1”.

29E.13 - Transmission Duration

When bit 29E.13 is set to a “1”, the EPG will continuously transmit packets as long as bit 29E.14 is set to a “1”. If bit 29E.13 is cleared, the EPG will begin transmission of 30,000,000 packets when bit 29E.14 is set to a “1”, after which time, bit 29E.14 is automatically cleared. If bit 29E.13 changes during packet transmission, the new value will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a “1” again.

29E.12:11 - Packet Length

Bits 29E.12:11 select the length of the packets to be generated by the EPG. Note that when these bits are set to “11”, a 10,000-byte “jumbo” packet is sent, which may not be compatible with all Ethernet equipment. If bits 29E.12:11 change during packet transmission, the new values will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a “1” again.

29E.10 - Inter-packet Gap

Bit 29E.10 selects the inter-packet gap for packets generated by the EPG. If bit 29E.10 changes during packet transmission, the new value will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a “1” again.

29E.9:6 - Destination Address

The 6-byte destination address for packets generated by the EPG is assigned one of 16 values in the range 0xF0 FF FF FF FF FFh through 0xFF FF FF FF FF FFh. The most significant byte's lower nibble bits of the destination address are selected by bits 29E.9:6. If bits 29E.9:6 change during packet transmission, the new values will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a "1" again.

29E.5:2 - Source Address

The 6-byte source address for packets generated by the EPG is assigned one of 16 values in the range 0xF0 FF FF FF FF FFh through 0xFF FF FF FF FF FFh. The most significant byte's lower nibble bits of the source address are selected by bits 29E.9:6. If bits 29E.5:2 change during packet transmission, the new values will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a "1" again.

29E.0 - Bad FCS Generation

When bit 29E.0 is set to a "1", the EPG will generate packets containing an invalid Frame Check Sequence (FCS). When this bit is cleared, the all EPG packets will contain a valid Frame Check Sequence. If bit 29E.0 changes during packet transmission, the new value will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a "1" again.

26.48 Register 30E (1Eh) - 1000BASE-T Packet Generator Register #2

Register 30E (1Eh) - 1000BASE-T Packet Generator Register #2					
Bit	Name	Access	States	Reset Value	Sticky
15:0	EPG Packet Payload	R/W	Data for packets generated by EPG	0	

30E.15:0 - EPG Packet Payload

Each packet generated by the EPG contains a repeating sequence of bits 30E.15:0 as the data payload. If bits 30E.15:0 change during packet transmission, the new values will not take effect until the EPG Run/Stop bit (29E.14) has been cleared and set to a "1" again.

26.49 Clause 37 Register View for Registers 0-15

The following 16 registers are compliant with IEEE 802.3 standard and comply with Clause 37. To change the register view to Clause 28 where the MAC is configured to RGMII mode, please refer to [Section 25.1: "IEEE803.3 Clause 28/37 MII Register View"](#).

26.50 Register 0 (00h) – Mode Control Register - Clause 37 View

Register 0 (00h) – Mode Control Register - Clause 37 View				
Bit	Name	Access	States	Reset Value
15	Software Reset ¹	R/W SC	1 = Reset asserted 0 = Reset de-asserted	0
14	Loopback ²	R/W	1 = Loopback on 0 = Loopback off	0
6, 13	Forced Speed Selection	R/W	00 = 10Mbps 01 = 100Mbps 10 = 1000Mbps 11 = Reserved	10
12	Auto-Negotiation Enable	R/W	1 = Auto-Negotiation enabled 0 = Auto-Negotiation disabled	1
11	Power-Down	R/W	1 = Power-down 0 = Power-up	0
10	Isolate	R/W	1 = Disable RGMII/RTBI outputs 0 = Normal Operation	0
9	Restart Auto-Negotiation	R/W SC	1 = Restart MII 0 = Normal operation	0
8	Duplex Mode	R/W	1 = Full duplex 0 = Half duplex	0
7	Collision Test Enable	R/W	1 = Collision test enabled 0 = Collision test disabled	0
6	MSB for Speed Selection (see bit 13 above)	-	-	1
5:0	Reserved	-	-	000000

¹ A soft reset restores all SMI registers to their default states, except for registers marked with an "S" or "SS" in the sticky column. After setting this bit, the user needs to wait 4 microseconds to initiate the next SMI access.

² The loopback mechanism works in the current speed and duplex mode of operation. If the link is down the operating mode is determined by bits 0.13 and 0.6 (forced speed selection) and 0.8. If the MAC/Media Interface select bits 23.15:12.2:1 are equal to a mode with fiber active, and 0.14 = 1, then the link partner may not drop the link.

26.51 Register 1 (01h) – Mode Status Register - Clause 37 View**Register 1 (01h) – Mode Status Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	100BASE-T4 Capability	RO	1 = 100BASE-T4 capable	0
14	100BASE-X FDX Capability	RO	1 = 100BASE-X FDX capable	1
13	100BASE-X HDX Capability	RO	1 = 100BASE-X HDX capable	1
12	10BASE-T FDX Capability	RO	1 = 10BASE-T FDX capable	1
11	10BASE-T HDX Capability	RO	1 = 10BASE-T HDX capable	1
10	100BASE-T2 FDX Capability	RO	1 = 100BASE-T2 FDX capable	0
9	100BASE-T2 HDX Capability	RO	1 = 100BASE-T2 HDX capable	0
8	Extended Status Enable	RO	1 = Extended status information present in R15	1
7	Reserved	RO		0
6	Preamble Suppression Capability	RO	1 = MF preamble may be suppressed 0 = MF preamble always required	1
5	Auto-Negotiation Complete	RO	1 = Auto-Negotiation complete 0 = Auto-Negotiation not complete	0
4	Remote Fault	RO LH	1 = Far-end fault detected 0 = No fault detected	0
3	Auto-Negotiation Capability	RO	1 = Auto-Negotiation capable	1
2	Link Status	RO LL	1 = Link is up 0 = Link is down	0
1	Jabber Detect	RO LH	1 = Jabber condition detected 0 = No jabber condition detected	0
0	Extended Capability	RO	1 = Extended register capable	1

26.52 Register 2 (02h) – PHY Identifier Register #1 - Clause 37 View**Register 2 (02h) – Mode Control Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Organizationally Unique Identifier	RO	OUI most significant bits (Microsemi OUI bits 3:18)	0000000000001111 or (000Fh)

26.53 Register 3 (03h) – PHY Identifier Register #2 - Clause 37 View**Register 3 (03h) – PHY Identifier Register #2 - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:10	Organizationally Unique Identifier	RO	OUI least significant bits (Microsemi OUI bits 19:24)	110001
9:4	Vendor Model Number	RO	Vendor's model number (IC)	011000 = VSC8224
3:0	Vendor Revision Number	RO	Vendor's revision number (IC)	0001 = Silicon Revision A1 0010 = Silicon Revision A2

26.53.1 Register 4 (04h) – Auto-Negotiation Advertisement Register - Clause 37 View**Register 4 (04h) – Auto-Negotiation Advertisement Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	Next-Page Transmission Request	R/W	1 = Next-Page transmission request	0
14	Reserved	RO		0
13:12	Transmit Remote Fault ¹	R/W	Remote fault transmission to link partner	00
11:9	Reserved	RO		0
8	Advertise Asymmetric Pause	R/W	1 = Advertise Asymmetric Pause capable	CMODE
7	Advertise Symmetric Pause	R/W	1 = Advertise Symmetric Pause capable	CMODE
6	Advertise 1000BASE-X HDX	R/W	1 = 1000BASE-X FDX capable	CMODE
5	Advertise 1000BASE-X FDX	R/W	1 = 1000BASE-X HDX capable	CMODE
4:0	Reserved	RO		0

¹ Refer to Extended MII Register 16E**26.53.2 Register 5 (05h) – Auto-Negotiation Link Partner Ability Register - Clause 37 View****Register 5(05h) – Auto-Negotiation Link Partner Ability Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	LP Next-Page Transmit Request	RO	1 = LP next-page transmission request	0
14	LP Acknowledge	RO	1 = LP acknowledge	0
13:12	LP Remote Fault ¹	RO	LP remote fault	00
11:9	Reserved	RO		0
8	LP Advertise Asymmetric Pause	RO	1 = LP Advertise Asymmetric Pause	0
7	LP Advertise Symmetric Pause	RO	1 = LP Advertise Symmetric Pause	0
6	LP Advertise 1000BASE-X HDX	RO	1 = 1000BASE-X HDX capable	0
5	LP Advertise 1000BASE-X FDX	RO	1 = 1000BASE-X FDX capable	0
4:0	Reserved	RO		0

¹ Refer to Extended MII Register 16E**26.53.3 Register 6 (06h) – Auto-Negotiation Expansion Register - Clause 37 View****Register 6 (06h) – Auto-Negotiation Expansion Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:3	Reserved	RO		0
2	Local PHY Next-Page Able	RO	1 = Next-Page capable	0
1	Page Received	RO LH	1 = New page has been received	0
0	Reserved	RO		0

26.54 Register 7 (07h) – Auto-Negotiation Next-Page Transmit Register - Clause 37 View¹**Register 7 (07h) – Auto-Negotiation Next-Page Transmit Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	Next Page	R/W	1 = More pages follow 0 = Last page	0
14	Reserved	RO		0
13	Message Page	R/W	1 = Message page 0 = Unformatted page	1
12	Acknowledge2	R/W	1 = Will comply with request 0 = Cannot comply with request	0
11	Toggle	RO	1 = Previous transmitted LCW == 0 0 = Previous transmitted LCW == 1	0
10:0	Message/Unformatted Code	R/W		00000000001

26.55 Register 8 (08h) – Auto-Negotiation Link Partner Next-Page Receive Register - Clause 37 View¹**Register 8 (08h) – Auto-Negotiation Link Partner Next-Page Receive Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	LP Next Page	RO	1 = More pages follow 0 = Last page	0
14	LP Acknowledge	RO	1 = LP acknowledge	0
13	LP Message Page	RO	1 = Message page 0 = Unformatted page	0
12	LP Acknowledge2	RO	1 = LP will comply with request	0
11	LP Toggle	RO	1 = Previous transmitted LCW == 0 0 = Previous transmitted LCW == 1	0
10:0	LP Message/Unformatted Code	RO		00000000000

26.56 Register 9 (09h) – Reserved Register - Clause 37 View**Register 9 (09h) – Reserved Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.57 Register 10 (0Ah) – Reserved Register - Clause 37 View**Register 10 (0Ah) – Reserved Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

¹This register is only valid for CAT-5 copper media

26.58 Register 11 (0Bh) – Reserved Register - Clause 37 View**Register 11 (0Bh) – Reserved Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.59 Register 12 (0Ch) – Reserved Register - Clause 37 View**Register 12 (0Ch) – Reserved Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.60 Register 13 (0Dh) – Reserved Register - Clause 37 View**Register 13 (0Dh) – Reserved Register**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.61 Register 14 (0Eh) – Reserved Register - Clause 37 View**Register 14 (0Eh) – Reserved Register - Clause 37 View**

Bit	Name	Access	States	Reset Value
15:0	Reserved	RO		00000000 00000000

26.61.1 Register 15 (0Fh) – 1000BASE-T Status Extension Register #1 - Clause 37 View**Register 15 (0Fh) – 1000BASE-T Status Extension Register #1 - Clause 37 View**

Bit	Name	Access	States	Reset Value
15	1000BASE-X FDX Capability	RO	1 = PHY is 1000BASE-X FDX capable 0 = PHY is not 1000BASE-X FDX capable	1
14	1000BASE-X HDX Capability	RO	1 = PHY is 1000BASE-X HDX capable 0 = PHY is not 1000BASE-X HDX capable	1
13	1000BASE-T FDX Capability	RO	1 = PHY is 1000BASE-T FDX capable 0 = PHY is not 1000BASE-T FDX capable	0
12	1000BASE-T HDX Capability	RO	1 = PHY is 1000BASE-T HDX capable 0 = PHY is not 1000BASE-T HDX capable	0
11:0	Reserved	RO		000000000000

27 Electrical Specifications

27.1 Absolute Maximum Ratings

Temporary or prolonged operating conditions beyond those listed below may result in device failure and/or compromise long-term device reliability.

Table 27-1. Absolute Maximum Ratings

Symbol	Min	Max	Unit	Parameter Description & Conditions
P_D		3.4	W	Worst case power dissipation.
$T_{Storage}$	-65	150	°C	Storage temperature range.
T_J		+125	°C	Absolute maximum junction temperature.
$V_{DD(Analog)}$	-0.5	4.0	V	DC voltage on analog I/O supply pin.
$V_{DD(IO)}$	-0.5	4.0	V	DC voltage on any digital I/O supply pin.
$V_{DD(5V)}$	-0.5	5.5	V	DC voltage on any 5V-tolerant digital input pin.
$V_{DD(Dig-Core)}$	-0.5	1.5	V	DC voltage on any digital core supply pin.
$V_{DD(Analog-Core)}$	-0.5	1.5	V	DC voltage on any analog core supply pin.
$V_{Pin(DC)}$	-0.5	$V_{DD} + 0.5$	V	DC voltage on any non-supply pin.
CESD	2		kV	Cable-sourced ESD tolerance, per event, at 200 meters.
$I_{LATCHUP}$	-200	+200	mA	$T = +85^{\circ}\text{C}$, valid for all I/O signal pins.

Stresses listed under the Absolute Maximum Ratings may be applied to devices one at a time without causing permanent damage. Functionality at or above the values listed is not implied. Exposure to these values for extended periods may affect device reliability.



ELECTROSTATIC DISCHARGE

This device can be damaged by ESD. Microsemi recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures may adversely affect reliability of the device.

27.2 Recommended Operating Conditions

Table 27-2. Recommended Operating Conditions

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
VDD33	3.0	3.3	3.6	V	DC voltage on VDD33 pins
VDDIO _{MAC}	3.0 2.3 1.4	3.3 2.5 1.5	3.6 2.7 1.6	V	DC voltage on VDDIO _{MAC} pins ¹
V _{REF} (HSTL)	.68	.75	.90	V	HSTL I/O reference voltage
VDDIO _{micro}	3.0 2.3 1.4	3.3 2.5 1.5	3.6 2.7 1.6	V	DC voltage on VDDIO _{micro} pins ¹
VDDIO _{ctl}	3.0 2.3	3.3 2.5	3.6 2.7	V	DC voltage on VDDIO _{ctl} pins ¹
VDD12	1.14	1.2	1.26	V	DC voltage on VDD12 pins
VDDDIG	1.14	1.2	1.26	V	Digital core logic DC power supply voltage.
F _{REFCLK}		25 125		MHz	Local reference clock (REFCLK) nominal frequency. Refer to F _{TOL} for min and max values.
F _{TOL} (REFCLK)	-100		+100	ppm	Reference clock frequency offset tolerance over specified temperature range (25MHz or 125MHz). ²
F _{TOL} (LINK)	-1500		+1500	ppm	Link partner frequency offset tolerance (for any link speed). ²
R _{EXT}		2.00		kΩ	External reference circuit bias resistor (1% tolerance).
C _{REF_FILT}		1.0		μF	External reference generator filter capacitor (10% tolerance).
T _{OPER}	0		100	°C	Operating temperature. Lower limit of specification is ambient temperature, and upper limit is case temperature.

¹ On-chip I/O calibration only valid within these recommended operating conditions.² For more information about clocking and frequency offset tolerance specifications when jumbo packet support is required, see the application note *Using Jumbo Packets with SimpliPHYS*.

27.3 Thermal Application Data

Table 27-3. PCB and Environment Conditions

Printed Circuit Board Conditions (JEDEC JESD51-9)		
PCB layers	6	4
PCB dimensions (mm x mm)	101.6 x 114.3	101.6 x 114.3
PCB thickness (mm)	1.6	1.6
Environment Conditions		
Maximum operation junction temperature (°C)	125	125
Ambient free-air operating temperature (°C)	70	70
Worst case power dissipation (W)	3.4	3.4

Table 27-4. Thermal Resistance

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
θ_{JA} (0 m/s air-flow)		17.5 20.2		°C/W	Junction-to-ambient thermal resistance 6-layer 4-layer
θ_{JA} (1 m/s air-flow)		14.8 17.5		°C/W	Junction-to-ambient thermal resistance 6-layer 4-layer
θ_{JA} (2 m/s air-flow)		13.8 16.2		°C/W	Junction-to-ambient thermal resistance 6-layer 4-layer

27.4 Package Thermal Specifications - 260 HS-PBGA

Table 27-5. Thermal Specifications - 260 ball HSBGA 19mm package

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
T_A			70	°C	Ambient free-air operating temperature
T_J			125	°C	Maximum operating junction temperature
θ_{JC}		5.1 5.2		°C/W	Junction-to-case thermal resistance 6-layer 4-layer
Ψ_{JT}		4.47 4.61		°C/W	Junction-to-top center of case thermal resistance 6-layer 4-layer
θ_{JB}		10.4 12.2		°C/W	Junction-to-board thermal resistance 6-layer 4-layer

27.5 Current and Power Consumption Estimates

Typical power supply current and power consumption information is provided as an estimate for PCB design targets. All typical data below is based on engineering measurements at nominal voltages, with 1000BASE-T RGMII 64-byte random data pattern under 100% utilization in full-duplex mode. A maximum margin of +20% should be included to account for variations in the specified power supply voltage ranges, as well as for variations due to normal silicon process spread and temperature conditions.

27.5.1 RGMII/RTBI-CAT5 Operation

Table 27-6. Current and Power Consumption Estimates - HSTL @ 1.5V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		397		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		50		mA	Digital I/O supply current into VDDIO _{MAC} @ 1.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		136		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		821		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		636		mW	Power dissipation per port (no LEDs)

Table 27-7. Current and Power Consumption Estimates - 2.5V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		397		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		98.6		mA	Digital I/O supply current into VDDIO _{MAC} @ 2.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		136		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		821		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		679		mW	Power dissipation per port (no LEDs)

Table 27-8. Current and Power Consumption Estimates - 3.3V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		397		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		149		mA	Digital I/O supply current into VDDIO _{MAC} @ 3.3V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V

Table 27-8. Current and Power Consumption Estimates - 3.3V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD12}		136		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		821		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		740		mW	Power dissipation per port (no LEDs)

27.5.2 RGMII/RTBI-SerDes/Fiber Operation

Table 27-9. Current and Power Consumption Estimates - HSTL @ 1.5V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		75		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		50		mA	Digital I/O supply current into VDDIO _{MAC} @ 1.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		135		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		135		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		164		mW	Power dissipation per port (no LEDs)

Table 27-10. Current and Power Consumption Estimates - 2.5V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		75		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		98.6		mA	Digital I/O supply current into VDDIO _{MAC} @ 2.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		135		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		135		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		207		mW	Power dissipation per port (no LEDs)

Table 27-11. Current and Power Consumption Estimates - 3.3V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		75		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		149		mA	Digital I/O supply current into VDDIO _{MAC} @ 3.3V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V

Table 27-11. Current and Power Consumption Estimates - 3.3V, RGMII mode, no LEDs, no CLK125 (*continued*)

Symbol	Min	Typ	Max	Unit	Description
I_{VDD12}		135		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		135		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		269		mW	Power dissipation per port (no LEDs)

27.5.3 RGMII/RTBI-CAT5 PICMG Backplane Operation (with MII Register Bit 24.12 = 1)

Table 27-12. Current and Power Consumption Estimates -
HSTL @ 1.5V, RGMII mode, no LEDs, no CLK125

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		397		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		50		mA	Digital I/O supply current into VDDIO _{MAC} @ 1.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		136		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		544		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		553		mW	Power dissipation per port (no LEDs)

27.5.4 RGMII/RTBI-CAT5 Backplane Operation (with MII Register Bit 24.12 = 1) ¹Table 27-13. Current and Power Consumption Estimates -
HSTL @ 1.5V, RGMII mode, no LEDs, no CLK125, and additional reduced power optimizations set

Symbol	Min	Typ	Max	Unit	Description
I_{VDD33}		319		mA	Analog 3.3V power supply current into VDD33 pins
$I_{VDDIOMAC}$		50		mA	Digital I/O supply current into VDDIO _{MAC} @ 1.5V
$I_{VDDIOmicro}$		0.3		mA	Digital I/O supply current into VDDIO _{micro} @ 3.3V
$I_{VDDIOctl}$		2.5		mA	Digital I/O supply current into VDDIO _{ctl} @ 3.3V
I_{VDD12}		136		mA	Analog 1.2V power supply current into VDD12 pins (includes SerDes)
I_{VDDDIG}		544		mA	Digital 1.2V core power supply current into VDDDIG pins
P_D		489		mW	Power dissipation per port (no LEDs)

¹With additional reduced power optimization settings asserted. Please refer to [Section 12: "Transformerless Ethernet Operation for PICMG 2.16 and 3.0 IP-based Backplanes"](#) for more information on how to configure the device for this operation.

28 DC Specifications

28.1 Digital Pins Referenced to VDDIO = 3.3V

The following specifications are valid only when $T_{\text{Ambient}} = 25^{\circ}\text{C}$, $V_{\text{DDIO}} = 3.3\text{V}$, $V_{\text{DDDIOG}} = 1.2\text{V}$, $V_{\text{DD33}} = 3.3\text{V}$, $V_{\text{SSIO}} = 0\text{V}$, and $V_{\text{SSS}} = 0\text{V}$.

Table 28-1. Digital Pins Specifications (VDDIO = 3.3V)

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
V_{OH}	2.1		$V_{\text{DDIO}} + 0.3$	V	Output high voltage. $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OH}} = -1.5\text{mA}$
V_{OL}	GND		0.5	V	Output low voltage. $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OL}} = 1.5\text{mA}$
V_{IH}	2.0			V	Input high voltage.
V_{IL}			0.9	V	Input low voltage.
I_{ILeak}	-10		10	μA	Input leakage current.
I_{OLeak}	-10		10	μA	Output leakage current.
I_{OL}			12	mA	Output low current drive strength
I_{OH}	-12			mA	Output high current drive strength
Z_{O}		50		Ω	Output driver impedance

28.2 Digital Pins Referenced to VDDIO = 2.5V

The following specifications are valid only when $T_{\text{Ambient}} = 25^{\circ}\text{C}$, $V_{\text{DDIO}} = 2.5\text{V}$, $V_{\text{DDDIOG}} = 1.2\text{V}$, $V_{\text{DD33}} = 3.3\text{V}$, $V_{\text{SSIO}} = 0\text{V}$, and $V_{\text{SSS}} = 0\text{V}$.

Table 28-2. Digital Pins Specifications (VDDIO = 2.5V)

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
V_{OH}	2.0		$V_{\text{DDIO}} + 0.3$	V	Output high voltage. $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OH}} = -1.0\text{mA}$
V_{OL}	GND - 0.3		0.4	V	Output low voltage. $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OL}} = 1.0\text{mA}$
V_{IH}	1.7			V	Input high voltage. $V_{\text{DDIO}} = \text{MIN}$
V_{IL}			0.7	V	Input low voltage. $V_{\text{DDIO}} = \text{MIN}$
I_{ILeak}	-10		10	μA	Input leakage current.
I_{OLeak}	-10		10	μA	Output leakage current.
I_{OL}			12	mA	Output low current drive strength
I_{OH}	-12			mA	Output high current drive strength
Z_{O}		50		Ω	Output driver impedance

28.3 Digital Pins Referenced to VDDIO = 1.5V (HSTL)

The following specifications are valid only when $T_{\text{Ambient}} = 25^{\circ}\text{C}$, $V_{\text{DDIO}} = 1.5\text{V}$, $V_{\text{DDDIG}} = 1.2\text{V}$, $V_{\text{DD33}} = 3.3\text{V}$, $V_{\text{SSIO}} = 0\text{V}$, and $V_{\text{SSS}} = 0\text{V}$.

Table 28-3. Digital Pins Specifications (VDDIO = 1.5V)

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
V_{OH}	$V_{\text{DDIO}} - 0.4$			V	Output high voltage $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OH}} = -1.0\text{mA}$
V_{OL}			0.4	V	Output low voltage $V_{\text{DDIO}} = \text{MIN}$, $I_{\text{OL}} = 1.0\text{mA}$
V_{IH}	$V_{\text{REF}} + 0.12$		$V_{\text{DDIO}} + 0.3$	V	Input high voltage $V_{\text{DDIO}} = \text{MIN}$
V_{IL}	- 0.3		$V_{\text{REF}} - 0.12$	V	Input low voltage $V_{\text{DDIO}} = \text{MIN}$
I_{ILeak}		10		μA	Input leakage current
I_{OLeak}		10		μA	Output leakage current
I_{OL}			12	mA	Output low current drive strength
I_{OH}	-12			mA	Output high current drive strength
Z_{O}		50		Ω	Output driver impedance

28.4 LED Output Pins (LED[4:0]_n)

The following specifications are valid over a over a voltage range of 2.3V to 1.3V applied to the LED pins.

Table 28-4. LED Output Pins Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description & Conditions
I_{ILeak}		10		μA	Input leakage current
I_{OLeak}		10		μA	Output leakage current
I_{OL}			18	mA	Output low current drive strength
I_{OH}	-18			mA	Output high current drive strength
Z_{O}		50		Ω	Output driver impedance

29 Clocking Specifications

29.1 Reference Clock Option

The following component specifications should be used to select a clock reference for use with the VSC8224. For more information about clocking and frequency offset tolerance specifications when jumbo packet support is required, see the application note *Using Jumbo Packets with SimpliPHYS*.

Table 29-1. Reference Clock Option Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
$F_{TOL-25MHZ}$	-100 ppm	25	+100 ppm	MHz	Total frequency offset tolerance (25MHz clock option), including, initial offset, stability over temperature.
T_{R1}, T_{F1}			4	ns	Rise and fall time (20% to 80%), 25MHz clock option.
T_{R2}, T_{F2}			0.8	ns	Rise and fall time (20% to 80%), 125MHz clock option.
DUTY	45		55	%	Duty cycle (25MHz and 125MHz clock options).

29.2 Crystal Option

The following component specifications should be used to select a crystal for use with the VSC8224. The crystal clocking option is supported only for copper media (10/100/1000BASE-T) applications or, in other words, when 1000BASE-X fiber media is not required. For more information about clocking and frequency offset tolerance specifications when jumbo packet support is required, see the application note *Using Jumbo Packets with SimpliPHYS*.

Table 29-2. Crystal Option Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
F_{REF}		25		MHz	Fundamental mode, AT-cut type, parallel resonant crystal reference frequency.
$F_{TOL(TOTAL)}$	-50		+50	ppm	Fundamental mode, AT-cut type, parallel resonant crystal total frequency offset, including, initial offset, stability over temperature, aging and capacitive loading
C_L	18		20	pF	Crystal parallel load capacitance.
C_{L-EXT}		33		pF	Crystal external load capacitors (C1 and C2) to GND ¹
ESR		10	30	Ω	Equivalent Series Resistance of crystal.
P_D			0.5	mW	Crystal oscillator drive level.

¹ These values can depend on board parasitics.

30 SerDes Specifications

This section pertains to pins TDP_n, TDN_n, RDP_n, RDN_n, TCP_n, and TCN_n. All specifications valid for $T_{\text{Ambient}} = 0^{\circ}\text{C}$ to 70°C .

Table 30-1. SerDes Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_lock		500		uS	Frequency Lock Time
Vidiff	100		2400	mV	Peak to peak differential voltage (TDP_n-TDN_n) terminated with a 100 Ω (differential) Load
Vodiff	350	1200	1400	mV	Peak to peak differential voltage (RDP_n-RDN_n), 100 Ω (differential) termination in the module, recommended voltage range is 500mV-1200mV. For more information on how to modify the output swing of the SerDes output differential pair, see Table 26.35, "Register 17E (11h) - CLK125micro Clock Enable," on page 99.
Vicm	$0.437 \times \text{VDD12}$	$.45 \times \text{VDD12}$	$0.464 \times \text{VDD12}$	V	Input common mode voltage
Vocm	$0.4 \times \text{VDD12}$	$.45 \times \text{VDD12}$	$0.5 \times \text{VDD12}$	V	Output common mode voltage
Tr_HS / Tf_HS			300	ps	20%-80% Transition time. Trise / Tfall of high speed output driver.
RJ		14		ps RMS	Random Jitter (1 sigma) as per 802.3 Standard. Random Jitter component at RDP_n, RDN_n.
DJ		30		ps pk-pk	With a K28.5+/K28.5- Pattern. Deterministic Jitter at RDP_n, RDN_n.
SerDes Data Rate	1249.375	1250	1250.625	Mbps	SerDes data rate. (+/- 500ppm).
I _{OL}			8	mA	Output low current drive strength
I _{OH}	-8			mA	Output high current drive strength
Z _O		50 or 75		Ω	Output driver impedance per pin. Please refer to MII Register Bit 20E.5

30.1 TCP/N_n Clock Specifications

All specifications valid for $T_{\text{Ambient}} = 0^{\circ}\text{C}$ to 70°C .

Table 30-2. TCP/N_n Clock Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T _{TCP/N}		1600		ps	TCP_n, TCN_n clock period
F _{stability}			50	ppm	Clock frequency stability
T _r /T _f		100		ps	Clock rise and fall time
T _{DUTY}	40	50	60	%	Clock duty cycle
J _{CLK}			44	ps RMS	Total output jitter RMS

31 System Timing Specifications

31.1 RGMII Mode Timing

For RGMII mode, the following specifications are valid when the I/O power supply ($VDDIO_{MAC}$) is 1.5V, 2.5V, or 3.3V, $\pm 5\%$, per the RGMII v2.0 specification, and the MAC I/F selection bits have been set to RGMII mode. See [MII Register bit 23.8](#) and the RGMII specification for more information.

Table 31-1. RGMII Mode AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_{skewT}	-500	0	500	ps	Data to clock output skew (at PHY) – uncompensated mode.
T_{skewR}	1	1.8	2.6	ns	Data to clock output skew (at receiver) – uncompensated mode. ¹
T_{setupT}	1.2	2.0	0	ns	Data to clock output Setup (at PHY integrated delay) ²
T_{holdT}	1.2	2.0	0	ns	Data to clock output Setup (at transmitter integrated delay) ²
T_{setupR}	1.0	2.0	0	ns	Data to clock output Setup (at receiver integrated delay) ²
T_{holdR}	1.0	2.0	0	ns	Data to clock output Setup (at PHY integrated delay) ²
$T_{CYC1000}$ T_{CYC100} T_{CYC10}	7.2 36 360	8 40 400	8.8 44 440	ns	Clock cycle duration.
Duty ₁₀₀₀	45	50	55	%	Duty cycle for 1000BASE-T. ³
Duty _{10/100}	40	50	60	%	Duty cycle for 10BASE-T and 100BASE-TX. ³
T_R, T_F			.75	ns	Rise, fall time (20% to 80%).
$V_{thresh1.5}$ $V_{thresh2.5}$ $V_{thresh3.3}$		0.75 1.25 1.65		V V V	TX_CLK_n Switching Threshold based on VDD_{MAC}

¹ This implies that PC board design will require clocks to be routed such that an additional trace delay of greater than 1.5ns and less than 2.0ns will be added to the associated clock signal. This is normal operating mode (RGMII timing is not compensated). To enable RGMII timing compensation, see [MII Register 23.11:8](#).

² RGMII Compensated mode (RGMII with Internal Delay Compensation On) - a 2ns delay is added to the TX_CLK_n and RX_CLK_n signals inside the PHY.

³ Duty cycle may be stretched or shrunk during speed changes or while transitioning to a received packet's clock domain, as long as the minimum duty cycle is not violated, and stretching occurs for no more than three T_{CYC} of the lowest speed transitioned between.

Figure 31-1 diagrams RGMII timing and multiplexing in uncompensated mode.

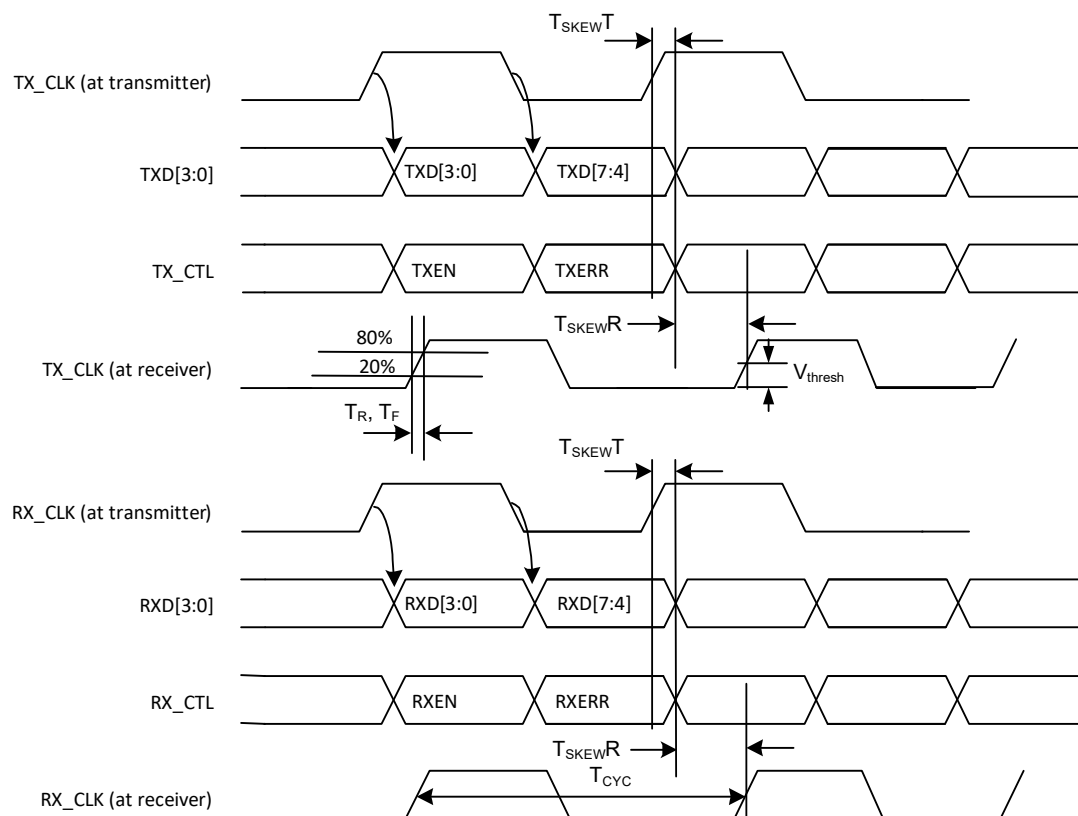


Figure 31-1. RGMII Uncompensated AC Timing and Multiplexing

The RGMII specification (v2.0) defines the following relationship between the clock and data signals at the MAC/PHY interface:

To meet this timing specification, a 1.5ns delay to the TX_CLK_n and RX_CLK_n signals is typically added on the PC board using a long “trombone shaped” trace.

The VSC8224 also includes an optional mode of operation where the PCB delay is handled internally (on-chip). This operation mode can be enabled by setting [MII Register 23.11:8](#) high. In this operation mode, the VSC8224 expects the following relationship between TX_CLK_n and TD on the transmit side and RX_CLK_n and RD on the receive side:

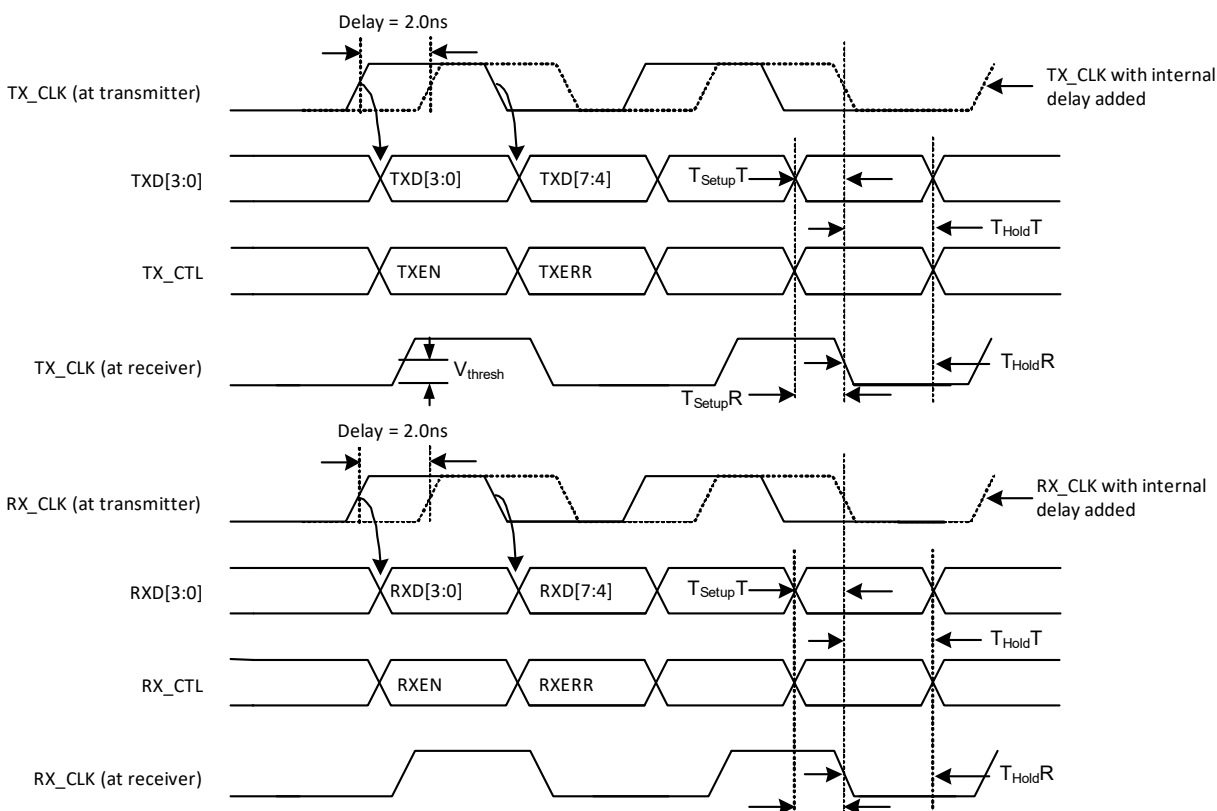


Figure 31-2. RGMII Compensated AC Timing and Multiplexing

Since no “trombone shaped” traces are required with this approach, the advantages of this compensated timing of RGMII v2.0 include:

- Simplified board design
- More compact routes; less board area
- Lower EMI emissions
- Greater distance possible between the MAC and PHY
- Improved signal integrity for a given distance between the MAC and PHY.

31.2 RTBI Mode Timing

For RTBI mode, the following specifications are valid when the I/O power supply (V_{DDIO_MAC}) is 1.5V, 2.5V, or 3.3V, $\pm 5\%$, per the RGMII (v2.0) specification, and the MAC I/F selection bits have been set to RTBI mode. See [MII Register bit 23.8](#) and the RTBI specification for more information.

Table 31-2. RTBI Mode AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_{skewT}	-500	0	500	ps	Data to clock output skew (at PHY) – uncompensated mode.
T_{skewR}	1	1.8	2.6	ns	Data to clock output skew (at receiver) – uncompensated mode. ¹
T_{setupT}	1.2	2.0	0	ns	Data to clock output Setup (at PHY integrated delay) ²
T_{holdT}	1.2	2.0	0	ns	Data to clock output Setup (at transmitter integrated delay) ²
T_{setupR}	1.0	2.0	0	ns	Data to clock output Setup (at receiver integrated delay) ²
T_{holdR}	1.0	2.0	0	ns	Data to clock output Setup (at PHY integrated delay) ²
$T_{CYC1000}$ T_{CYC100} T_{CYC10}	7.2 36 360	8 40 400	8.8 44 440	ns	Clock cycle duration.
Duty ₁₀₀₀	45	50	55	%	Duty cycle for 1000BASE-T. ³
Duty _{10/100}	40	50	60	%	Duty cycle for 10BASE-T and 100BASE-TX. ³
T_R, T_F			.75	ns	Rise, fall time (20% to 80%).
$V_{thresh1.5}$ $V_{thresh2.5}$ $V_{thresh3.3}$		0.75 1.25 1.65		V V V	TX_CLK_n Voltage Threshold based on V_{DDIO_MAC}

¹ This implies that PC board design will require clocks to be routed such that an additional trace delay of greater than 1.5ns and less than 2.0ns will be added to the associated clock signal. This is normal operating mode (RTBI timing is not compensated). To enable RGMII timing compensation, see [MII Register 23.11:8](#).

² RTBI compensated mode (RGMII with Internal Delay Compensation On) - a 2ns delay is added to the TX_CLK_n and RX_CLK_n signals inside the PHY.

³ Duty cycle may be stretched or shrunk during speed changes or while transitioning to a received packet's clock domain, as long as the minimum duty cycle is not violated, and stretching occurs for no more than three T_{CYC} of the lowest speed transitioned between.

Figure 31-1 diagrams RTBI timing and multiplexing in uncompensated mode.

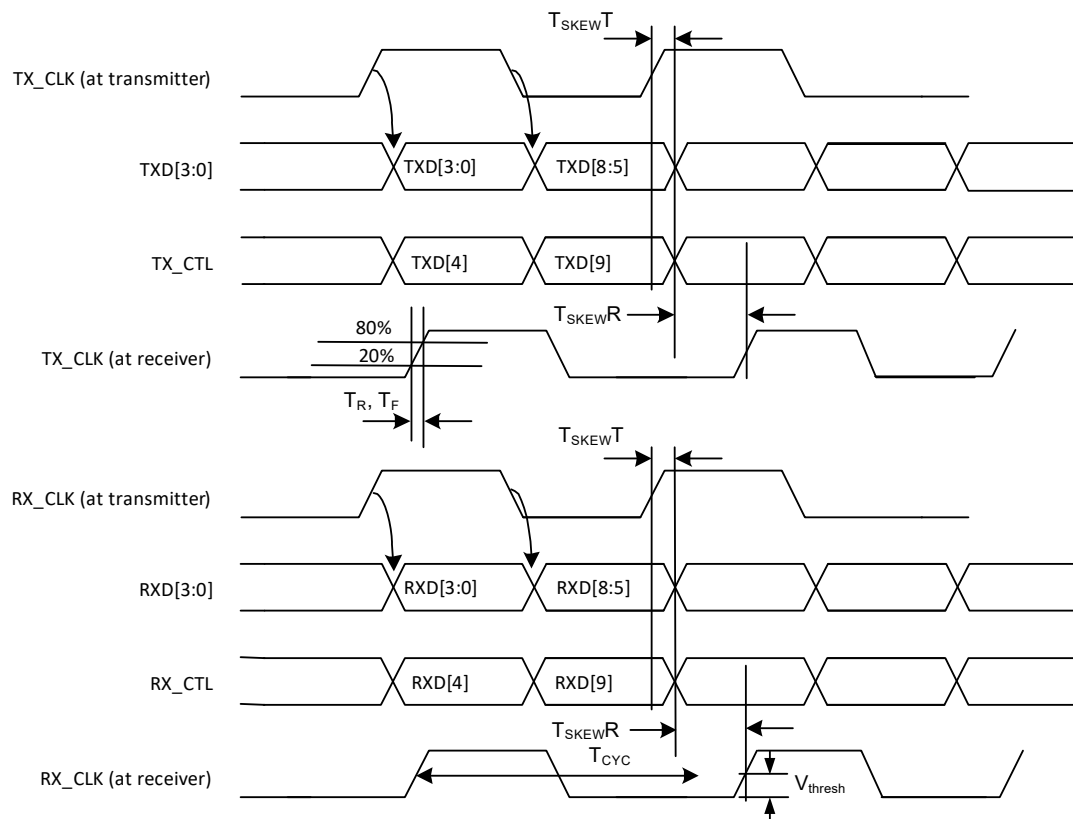


Figure 31-3. RTBI Uncompensated AC Timing and Multiplexing

The RGMII specification (v2.0) defines the following relationship between the clock and data signals at the MAC/PHY interface:

To meet this timing specification, a 1.5ns delay to the TX_CLK_n and RX_CLK_n signals is typically added on the PC board using a long “trombone shaped” trace.

The VSC8224 also includes a mode of operation where the addition of this delay is handled internally. This operation mode can be enabled by setting [MII Register 23.11:8](#) high. In this operation mode, the VSC8224 expects the following relationship between TX_CLK_n and TD on the transmit side and RX_CLK_n and RD on the receive side:

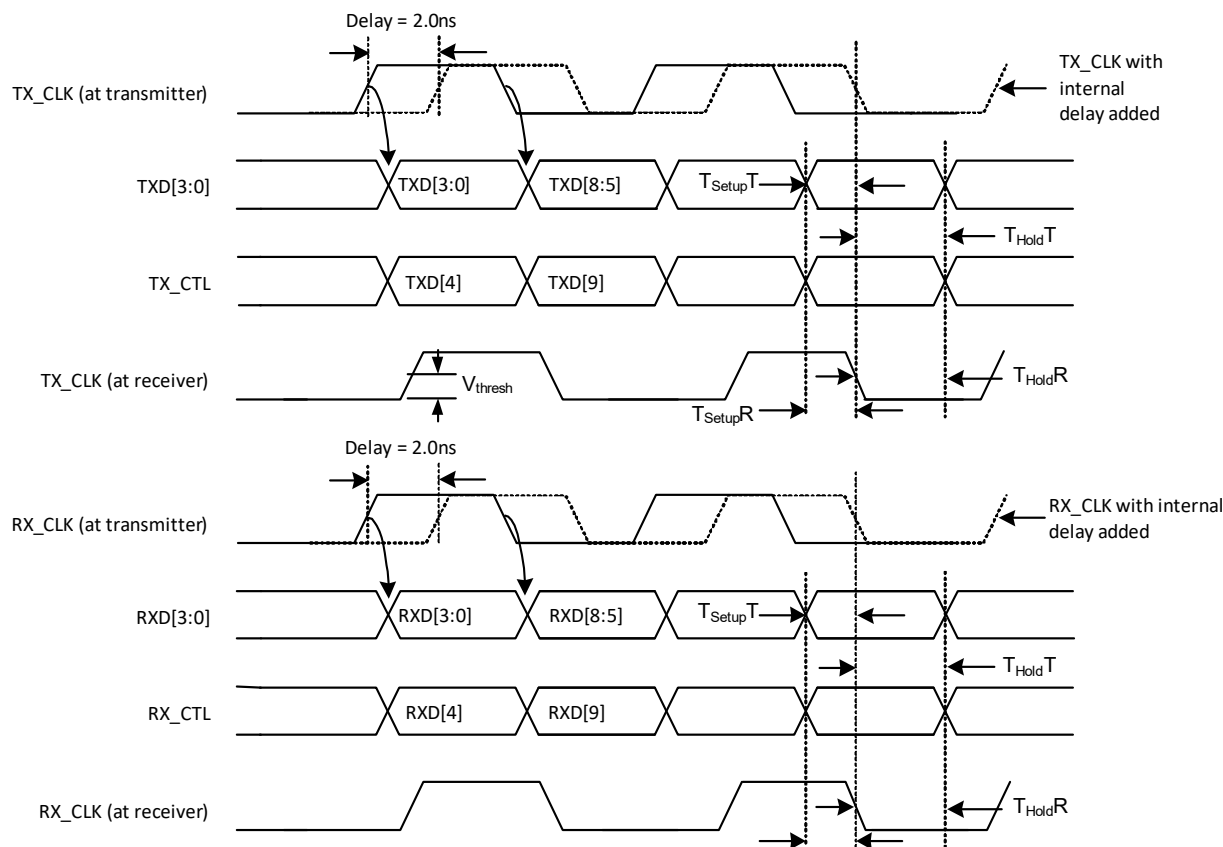


Figure 31-4. RTBI Compensated AC Timing and Multiplexing

Since no “trombone shaped” trace is required with this approach, the advantages of this compensated timing over RGMII v2.0 include:

- Simplified board design
- More compact routes; less board area
- Lower EMI emissions
- Greater distance possible between the MAC and PHY
- Improved signal integrity for a given distance between the MAC and PHY.

31.3 JTAG Timing

The following specifications are valid only when the I/O power supply ($V_{DDIO_{ctl}}$) is at either 3.3V, $\pm 5\%$, or 2.5V, $\pm 5\%$.

Table 31-3. JTAG Interface AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
$T_{TCK-Period}$	100			ns	TCK period.
$T_{TCK-High}$	45			ns	TCK minimum pulse width high.
$T_{TCK-Low}$	45			ns	TCK minimum pulse width low.
$T_{TDI/TMS-Setup}$	10			ns	(TMS or TDI) to TCK setup time.
$T_{TDI/TMS-Hold}$	10			ns	(TMS or TDI) to TCK hold time.
$T_{TDO-Delay}$			15	ns	TDO delay from TCK.

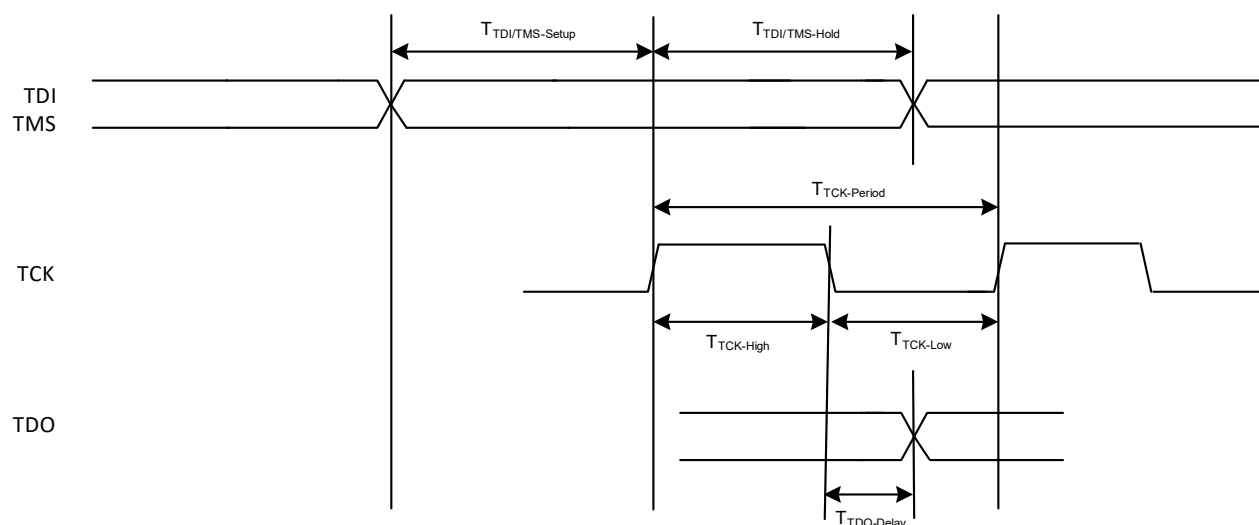


Figure 31-5. JTAG Interface AC Timing

31.4 SMI Timing

The following specifications are valid only when the I/O power supply (V_{DDIO_micro}) is at either 3.3V, $\pm 5\%$, or 2.5V, $\pm 5\%$.

Table 31-4. SMI AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
F_{MDC}	0	2.5	12.5	MHz	MDC clock frequency.
$T_{MDC-High}$	20	50		ns	MDC clock pulse width high.
$T_{MDC-Low}$	20	50		ns	MDC clock pulse width low.
$T_{MDIO-Setup}$	10			ns	MDIO to MDC setup time when sourced by Station Manager.
$T_{MDIO-Hold}$	10			ns	MDIO to MDC hold time when sourced by Station Manager.
T_R, T_F	100 $T_{MDC} \times 10\%^1$			ns	MDC rise and fall time. For MDC = 0 - 1MHz For MDC = 1MHz - $F_{MDC}(MAX)$
$T_{MDIO-Delay}$		10	300	ns	MDC to MDIO delay time from VSC8224. Delay will depend on value of external pull-up resistor on MDIO pin.

¹ For F_{MDC} above 1MHz, the minimum rise and fall times are in relation to the frequency of the MDC clock period. Example: if $F_{MDC} = 2MHz$, then the minimum T_R/T_F is 50ns.

Note: At 16MHz, a 400 Ω pull-up resistor on the MDIO pin is recommended; otherwise, a 2k Ω pull-up resistor is recommended at 2MHz.

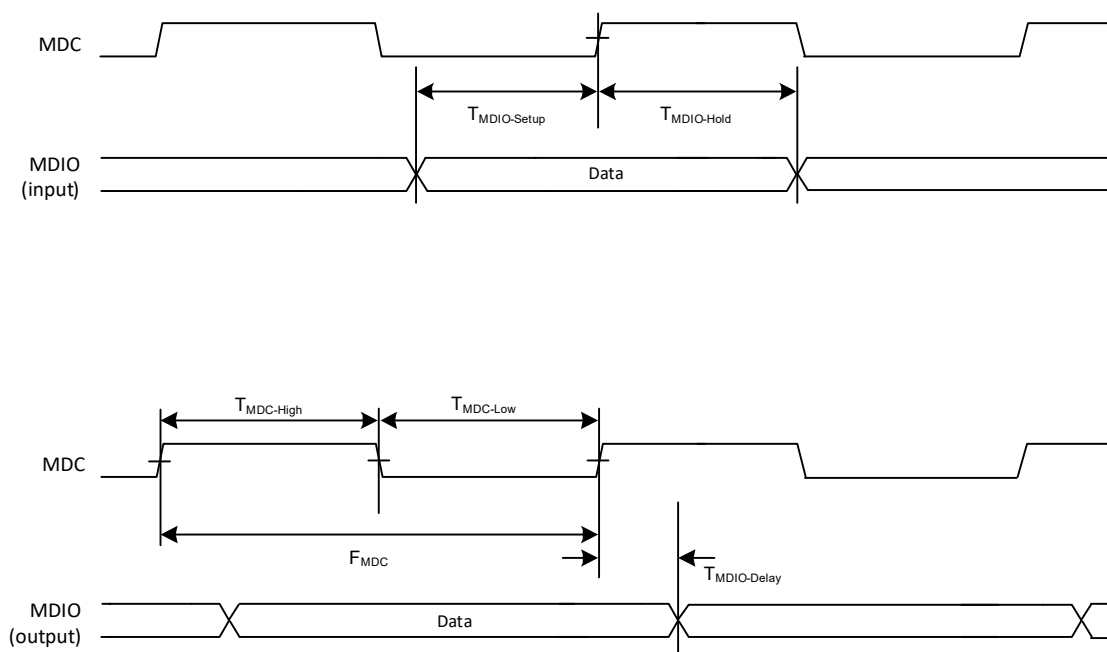


Figure 31-6. SMI AC Timing

31.5 MDINT Timing

The following specifications are valid only when the I/O power supply ($VDDIO_{micro}$) is at either 3.3V, $\pm 5\%$, or 2.5V, $\pm 5\%$.

Table 31-5. MDINT AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
t_F			110	ns	MDINT fall time, assuming a 2.2k Ω external pull-up resistor and a 50pF total capacitive load.

31.6 Serial LED_CLK and LED_DATA Timing

The following specifications are valid only when the I/O power supply ($VDD33$) is at either 3.3V, $\pm 5\%$, or 2.5V, $\pm 5\%$.

Table 31-6. LED_CLK and LED_DATA Output AC Timing Specification

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_{LED_CLK}	1			μs	LED_CLK output period.
$T_{LED_CLK-Pause}$		25		ms	LED_CLK pause between LED bit sequence repeat (un-preambled mode).
$T_{LED_DATA-Delay}$			15	ns	LED_DATA propagation delay from rising edge of LED_CLK.

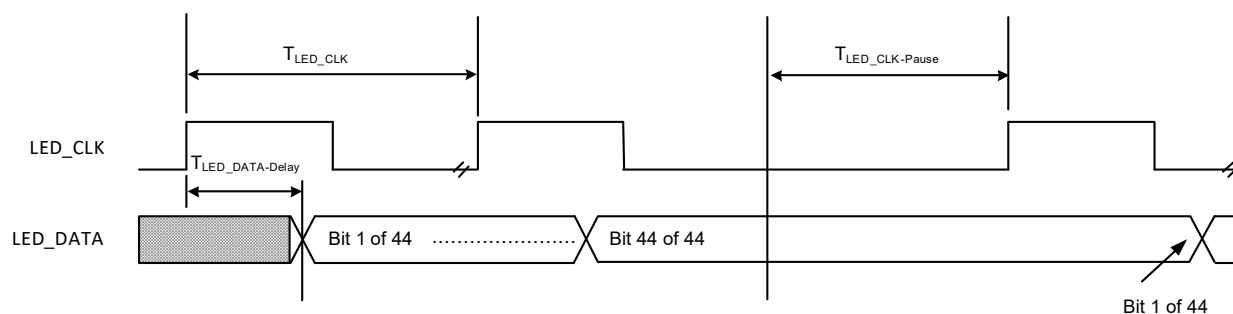


Figure 31-7. LED_CLK and LED_DATA Output AC Timing

31.7 REFCLK Timing

The following specifications are valid only when the I/O power supply (VDD33) is at either 3.3V, $\pm 5\%$, or 2.5V, $\pm 5\%$. For more information about clocking and frequency offset tolerance specifications when jumbo packet support is required, see the application note “Using Jumbo Packets with SimpliPHYS”.

Table 31-7. REFCLK AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_{REFCLK25}		40		ns	Reference clock period, PLLMODE = 0 (25MHz reference).
$T_{\text{REFCLK125}}$		8		ns	Reference clock period, PLLMODE = 1 (125MHz reference).
$F_{\text{STABILITY}}$			50	ppm	Reference clock frequency stability (0°C to 70°C).
T_{DUTY}	40	50	60	%	REFCLK duty cycle in both 25MHz and 125MHz modes.
$J_{\text{REFCLK25}}, J_{\text{REFCLK125}}$			300	ps	Total jitter of 25MHz or 125MHz reference clock (peak-to-peak).
$t_{\text{R/F}} (\text{REFCLK25})$			4	ns	Reference clock rise time, 25MHz mode (20% to 80%).
$t_{\text{R/F}} (\text{REFCLK125})$			1	ns	Reference clock rise time, 125MHz mode (20% to 80%).

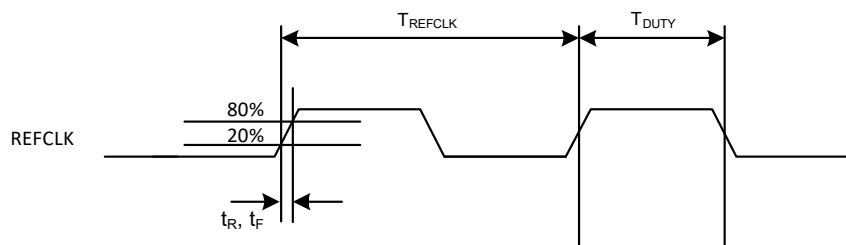


Figure 31-8. REFCLK AC Timing

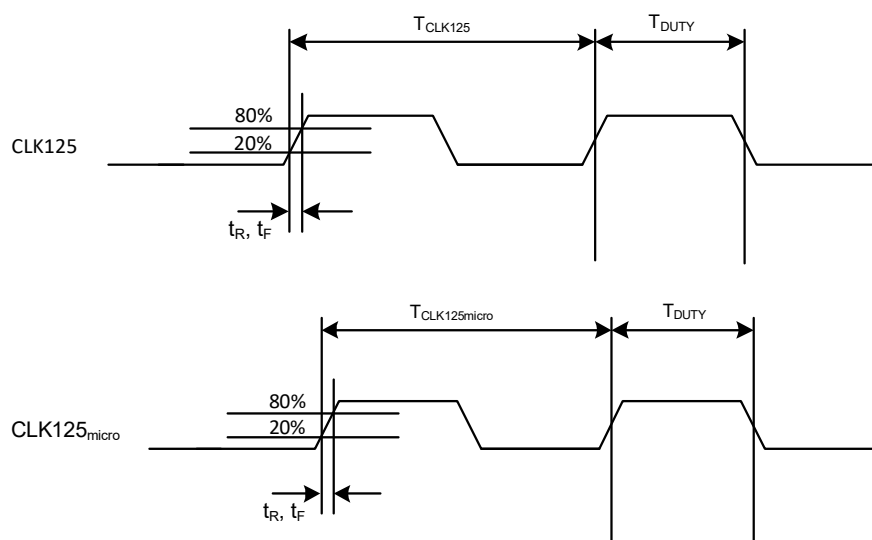
31.8 CLK125_{MAC} and CLK125_{micro} Timing

The following specifications are valid only when the I/O power supply (VDDIO_{MAC} for CLK125_{MAC}) is at either 3.3V ±5%, 2.5V ±5%, or 1.5V ±5%.

The following specifications are valid only when the I/O power supply (VDDIO_{micro} for CLK125_{micro}) is at either 3.3V ±5%, or 2.5V ±5%.

Table 31-8. CLK125 AC Timing Specifications

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
$T_{CLK125MAC}$		8		ns	Reference clock period.
$T_{CLK125micro}$		250 8		ns	Reference clock period. Either 4MHz, or 125MHz
$F_{STABILITY}$			50	ppm	Reference clock frequency stability (0°C to 70°C).
T_{DUTY}	40	50	60	%	Reference clock duty cycle.
J_{CLK125}			300	ps	Total jitter of reference clock (peak-to-peak).
$t_{R/F} (CLK125)$			1	ns	Reference clock rise time (20% to 80%).

**Figure 31-9. CLK125 AC Timing**

31.9 Reset Timing

The following specifications are valid only when the I/O power supply (VDDIOmicro) is at either 3.3 V $\pm 5\%$, or 2.5 V $\pm 5\%$.

Table 31-9. RESET AC Timing Specification

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
T_{RESET}	100			ns	Reset assertion time
T_{READY}		13	20	ms	Reset to SMI active time

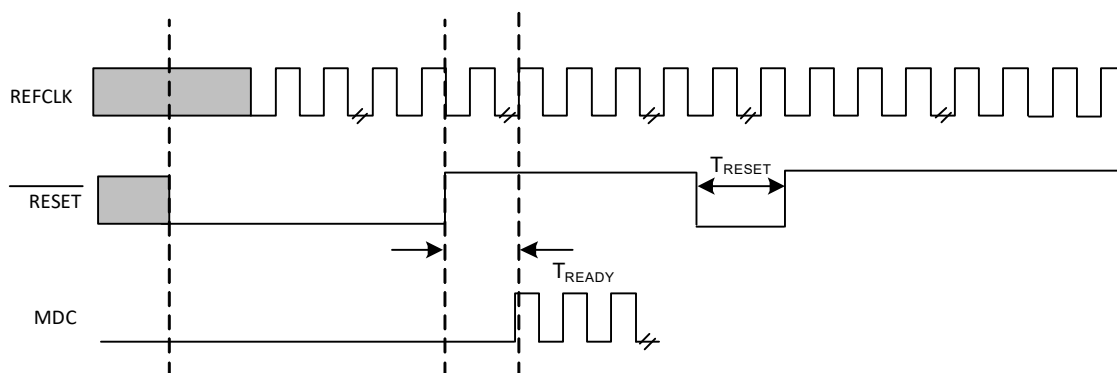


Figure 31-10. RESET AC Timing

32 Packaging Specifications

32.1 19 mm HS-PBGA Mechanical Specification

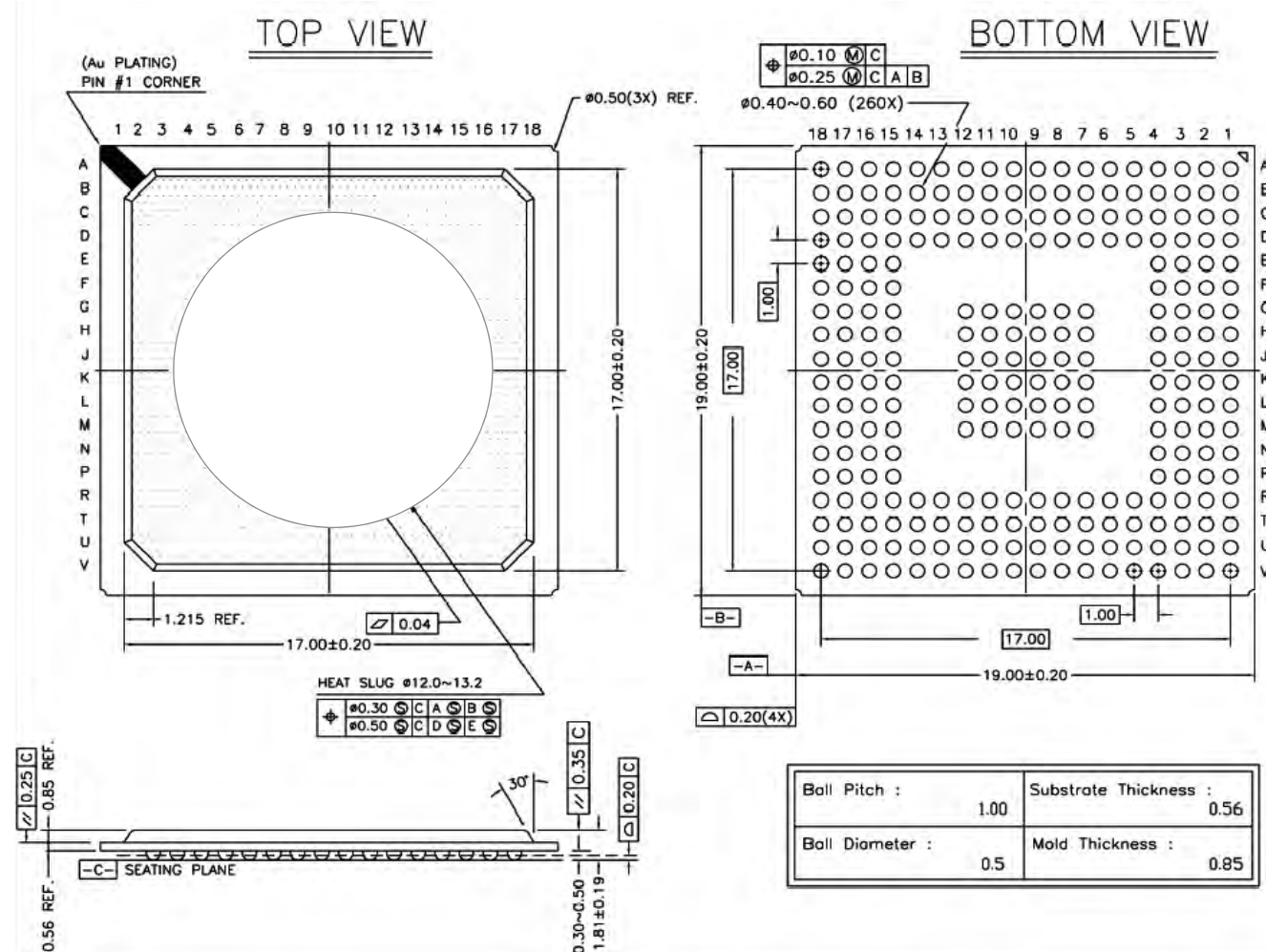


Figure 32-1. 19mm HS-PBGA Mechanical Specification

32.2 Package Moisture Sensitivity

Moisture sensitivity level ratings for Microsemi products comply with the joint IPC and JEDEC standard IPC/JEDEC J-STD-020.

VSC8224HG is rated moisture sensitivity level 3 or better.

VSC8224XHG is rated moisture sensitivity level 4.

For more information, see the IPC and JEDEC standard.

33 Ordering Information

33.1 Devices

Table 33-1. Part Number for the VSC8224

Part Number	Package Type	Description
VSC8224HG ¹	260 HS-PBGA 1mm ball pitch 19x19mm body	Quad 10/100/1000BASE-T/1000BASE-X PHY with RGMII/RTBI interfaces
VSC8224XHG	260 HS-PBGA 1mm ball pitch 19x19mm body	Lead(Pb)-free, quad 10/100/1000BASE-T/ 1000BASE-X PHY with RGMII/RTBI interfaces

¹ This device was previously available from Cicada Semiconductor Corporation (Cicada) as CIS8224-HFC. Cicada is now wholly owned by Microsemi Semiconductor Corporation, and the part number has been changed to reflect this.

33.2 Related Devices

Table 33-2. Part Numbers for Related Devices

Part Number	Package Type	Description
VSC8234HG	260 HS-PBGA 1mm ball pitch 19x19mm body	Quad 10/100/1000BASE-T PHY with SGMII/SerDes interfaces
VSC8234XHG	260 HS-PBGA 1mm ball pitch 19x19mm body	Lead(Pb)-free, quad 10/100/1000BASE-T PHY with SGMII/1000BASE-X SerDes MAC interfaces
VSC8244HG	260 HS-PBGA 1mm ball pitch 19x19mm body	Quad 10/100/1000BASE-T PHY with RGMII/RTBI interfaces
VSC8244XHG	260 HS-PBGA 1mm ball pitch 19x19mm body	Lead(Pb)-free, quad 10/100/1000BASE-T PHY with RGMII and RTBI interfaces

34 Design Guidelines

34.1 Required SMI Register Write Sequence

At initialization, a number of internal registers must be changed from their default values.

A series of register writes must be executed after each device power-up or reset. A microcontroller or a startup configuration EEPROM (connected to the device as described in [Section 24.4: "EEPROM Interface"](#)) must be included in the system design.

The register rewrites are listed in [Table 34-1: "Startup Write Sequence Changes"](#).

In executing the writes, use the format: smiwrite[PHY, register, data]. All register and data values listed in the table are in hexadecimal notation.

Table 34-1. Startup Write Sequence Changes

	PHY	Register	Data		PHY	Register	Data
smiwrite	0	1F	2A30	smiwrite	2	1F	2A30
smiwrite	0	08	0212	smiwrite	2	08	0212
smiwrite	0	1F	52B5	smiwrite	2	1F	52B5
smiwrite	0	10	AFA4	smiwrite	2	10	AFA4
smiwrite	0	12	000F	smiwrite	2	12	000F
smiwrite	0	11	492A	smiwrite	2	11	492A
smiwrite	0	10	8FA4	smiwrite	2	10	8FA4
smiwrite	0	1F	2A30	smiwrite	2	1F	2A30
smiwrite	0	08	0012	smiwrite	2	08	0012
smiwrite	1	1F	2A30	smiwrite	3	1F	2A30
smiwrite	1	08	0212	smiwrite	3	08	0212
smiwrite	1	1F	52B5	smiwrite	3	1F	52B5
smiwrite	1	10	AFA4	smiwrite	3	10	AFA4
smiwrite	1	12	000F	smiwrite	3	12	000F
smiwrite	1	11	492A	smiwrite	3	11	492A
smiwrite	1	10	8FA4	smiwrite	3	10	8FA4
smiwrite	1	1F	2A30	smiwrite	3	1F	2A30
smiwrite	1	08	0012	smiwrite	3	08	0012

34.2 Interoperability with Intel 82547E1 L322SQ96

The Intel 82547E1 PHY, by design, links in slave mode with over 99% probability and then changes its operating mode in a non-IEEE-compliant manner shortly after responding to a master link partner's initial transmission. The timing of this event is such that, over cabling shorter than approximately 2 meters in length, the affected link partner drops the link and attempts to link again. This cycle can repeat indefinitely.

A series of register writes must be executed after each device power-up or reset. A microcontroller (connected to the SMI) or a startup configuration EEPROM (connected to the device as described in [Section 24.4: "EEPROM Interface"](#)) must be included in the system design.

The register rewrites are listed in [Table 34-2: "Startup Write Sequence Changes for Intel 82547E1 Interoperability"](#).

In executing the writes, use the format: smiwrite[PHY, register, data]. All register and data values listed in the table are in hexadecimal notation.

Table 34-2. Startup Write Sequence Changes for Intel 82547E1 Interoperability

	PHY	Register	Data		PHY	Register	Data
smiwrite	0	1F	2A30	smiwrite	2	1F	2A30
smiwrite	0	08	0212	smiwrite	2	08	0212
smiwrite	0	1F	52B5	smiwrite	2	1F	52B5
smiwrite	0	12	0004	smiwrite	2	12	0004
smiwrite	0	11	0671	smiwrite	2	11	0671
smiwrite	0	10	8FAE	smiwrite	2	10	8FAE
smiwrite	0	1F	2A30	smiwrite	2	1F	2A30
smiwrite	0	08	0012	smiwrite	2	08	0012
smiwrite	0	1F	0000	smiwrite	2	1F	0000
smiwrite	0	12	0049	smiwrite	2	12	0049
smiwrite	1	1F	2A30	smiwrite	3	1F	2A30
smiwrite	1	08	0212	smiwrite	3	08	0212
smiwrite	1	1F	52B5	smiwrite	3	1F	52B5
smiwrite	1	12	0004	smiwrite	3	12	0004
smiwrite	1	11	0671	smiwrite	3	11	0671
smiwrite	1	10	8FAE	smiwrite	3	10	8FAE
smiwrite	1	1F	2A30	smiwrite	3	1F	2A30
smiwrite	1	08	0012	smiwrite	3	08	0012
smiwrite	1	1F	0000	smiwrite	3	1F	0000
smiwrite	1	12	0049	smiwrite	3	12	0049

34.3 SerDes Jitter

Under worst case conditions, total jitter performance may exceed the IEEE specifications for 1000BASE-X, as noted in the table below. In typical applications with robust PCB design practices, however, actual performance is typically better than the figures noted below.

Table 34-3. Worst Case SerDes Jitter

Symbol	Min	Typ	Max	Unit	Parameter Description and Conditions
$J_{(TOTAL, TX1)}$			285	ps	Worst case total transmit jitter when 3 copper and 1 fiber interfaces are active.
$J_{(TOTAL, RX1)}$			350	ps	Worst case total receive jitter tolerance when 3 copper and 1 fiber interfaces are active.
$J_{(TOTAL, TX2)}$			180	ps	Worst case total transmit jitter when all four fiber interfaces are active and no copper interfaces are active.
$J_{(TOTAL, RX2)}$			400	ps	Worst case total receive jitter tolerance when all four fiber interfaces are active and no copper interfaces are active.

35 Product Support

All support documents for the VSC8224 can be accessed on the Microsemi Web site at www.Microsemi.com. Access to some documents may require filing a non-disclosure agreement with Microsemi.

35.1 Available Documents and Application Notes

- Startup Script File (At initialization, a number of internal registers must be changed from their default values. For more information, see the VSC8224 Revision C startup script text file.
- IBIS Model
- OrCAD Symbol
- BSDL File
- Package Pinout Excel Spreadsheet File
- Design and Layout Guidelines application note
- SimpliPHY'd Magnetics for EMI Control application note
- Using Jumbo Packets with SimpliPHYs application note
- UNH Test Report (requires NDA)

For additional application notes and information about reference designs using the VSC8224 PHY device, visit the Microsemi Web site at www.Microsemi.com.

36 Document History & Notices

Table 36-1. Document Revision History

Revision Number	Date	Comments
0.2.0	Mar 30 04	- VeriPHY functional changes. Removed Registers 24E-28E. This feature requires support from an external MCU/CPU and the VeriPHY software library. Contact Microsemi Semiconductor for more information. - Silicon Revision A0 LED functions have been removed. - Added undocumented pins: C8, M15, R16 to the pin descriptions. Updated JTAG, RESET, SOFT_RESET, TX_CLK_n, TX_REF_n, MICROREF, SIGDET_n, EEDAT, EECLK, pin descriptions. - Updated Table 10-1 and Figure 32-3. - Added Section 11.5, 11.6, 12.5, 16, 31.1, 32.3. - Updated Sections 12.3, 12.4, 13, 15, 19, 21, 22, 23.3, 23.4, 24, 25, 26, 28.2, 28.5, 29, 35. - Simplified Register descriptions 0-15 for both Clause 28 and Clause 37 view. - Updated Register 16-18, 22, 23, 24, 28, 30, 16E, 19E, 20E, 22E.
2.0	May 13 04	Updated document style to reflect Microsemi corporate standards.
2.1	July 07 04	Added errata section to describe the transmission errors in the serial MAC to CAT-5 operating mode and the SGMII to CAT5 operating mode.
2.2	July 30 04	Errata section updated to reflect that the Serial MAC-to-CAT-5 and SGMII MAC-to-CAT-5 operating modes have been permanently removed as a feature from the VSC8224 device, and that this feature is only be available on the VSC8234 PHY.
4.0	Oct 29 04	- Added the maximum value for the worst case power dissipation (P_D) in the Absolute Maximum Ratings table. - Changed the symbol for the operating temperature from T_A to T_{OPER} and added the definition that the lower limit of the specification is the ambient temperature, and the upper limit is the case temperature. - Modified the digital pins specifications in Table 29-1 and Table 29-3. - Modified register information and descriptions for registers 1, 23, and 31. - Crystal clocking option is not supported in dual media applications. - Removed Errata section. - Added SerDes Jitter section to the Design Guidelines.
4.1	Aug 15 06	Added ordering information for lead(Pb)-free products. For more information, see Section 33: "Ordering Information". Also, for the MSL ratings of the lead(Pb)-free products, see Section 32.2: "Package Moisture Sensitivity".
4.2	February 2019	Updated VeriPHY® information. For functional details of the VeriPHY suite and the operating instructions, see the ENT-AN0125 PHY, Integrated PHY-Switch VeriPHY - Cable Diagnostics application note.



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